

PIC16F630/676 Data Sheet

14-Pin, Flash-Based 8-Bit CMOS Microcontrollers

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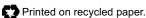
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14-Pin, Flash-Based 8-Bit CMOS Microcontroller

High-Performance RISC CPU:

- Only 35 Instructions to Learn
 - All single-cycle instructions except branches
- · Operating Speed:
 - DC 20 MHz oscillator/clock input
 - DC 200 ns instruction cycle
- Interrupt Capability
- 8-level Deep Hardware Stack
- Direct, Indirect, and Relative Addressing modes

Special Microcontroller Features:

- · Internal and External Oscillator Options
 - Precision Internal 4 MHz oscillator factory calibrated to $\pm 1\%$
 - External Oscillator support for crystals and resonators
 - 5 μ s wake-up from Sleep, 3.0V, typical
- Power-Saving Sleep mode
- Wide Operating Voltage Range 2.0V to 5.5V
- Industrial and Extended Temperature Range
- Low-Power Power-on Reset (POR)
- Power-up Timer (PWRT) and Oscillator Start-up Timer (OST)
- Brown-out Detect (BOD)
- Watchdog Timer (WDT) with Independent Oscillator for Reliable Operation
- Multiplexed MCLR/Input-pin
- Interrupt-on-Pin Change
- Individual Programmable Weak Pull-ups
- Programmable Code Protection
- High Endurance Flash/EEPROM Cell
 - 100,000 write Flash endurance
 - 1,000,000 write EEPROM endurance
 - Flash/data EEPROM retention: > 40 years

Low-Power Features:

- Standby Current:
 - 1 nA @ 2.0V, typical
- Operating Current:
 - 8.5 μA @ 32 kHz, 2.0V, typical
 - 100 μA @ 1 MHz, 2.0V, typical
- Watchdog Timer Current
 - 300 nA @ 2.0V, typical
- Timer1 Oscillator Current:
 - 4 μA @ 32 kHz, 2.0V, typical

Peripheral Features:

- 12 I/O Pins with Individual Direction Control
- High Current Sink/Source for Direct LED Drive
- · Analog Comparator module with:
 - One analog comparator
 - Programmable on-chip comparator voltage reference (CVREF) module
 - Programmable input multiplexing from device inputs
 - Comparator output is externally accessible
- · Analog-to-Digital Converter module (PIC16F676):
 - 10-bit resolution
 - Programmable 8-channel input
 - Voltage reference input
- Timer0: 8-bit Timer/Counter with 8-bit Programmable Prescaler
- Enhanced Timer1:
 - 16-bit timer/counter with prescaler
 - External Gate Input mode
 - Option to use OSC1 and OSC2 in LP mode as Timer1 oscillator, if INTOSC mode selected
- In-Circuit Serial Programming[™] (ICSP[™]) via two pins

	Device	Program Memory	Data M	Data Memory		10-bit A/D	Comporatora	Timers	
	Device	Flash (words)	SRAM (bytes)	EEPROM (bytes)	I/O	(ch)	Comparators	8/16-bit	
ſ	PIC16F630	1024	64	128	12	_	1	1/1	
	PIC16F676	1024	64	128	12	8	1	1/1	

Pin Diagrams

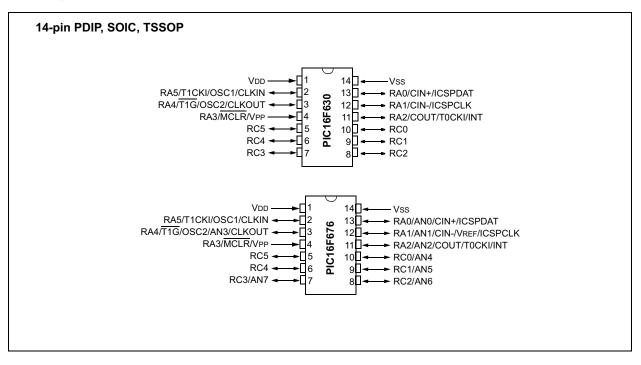


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NOTES:

1.0 DEVICE OVERVIEW

This document contains device specific information for the PIC16F630/676. Additional information may be found in the PIC[®] Mid-Range Reference Manual (DS33023), which may be obtained from your local Microchip Sales Representative or downloaded from the Microchip web site. The Reference Manual should be considered a complementary document to this Data Sheet and is highly recommended reading for a better understanding of the device architecture and operation of the peripheral modules.

The PIC16F630 and PIC16F676 devices are covered by this Data Sheet. They are identical, except the PIC16F676 has a 10-bit A/D converter. They come in 14-pin PDIP, SOIC and TSSOP packages. Figure 1-1 shows a block diagram of the PIC16F630/676 devices. Table 1-1 shows the pinout description.

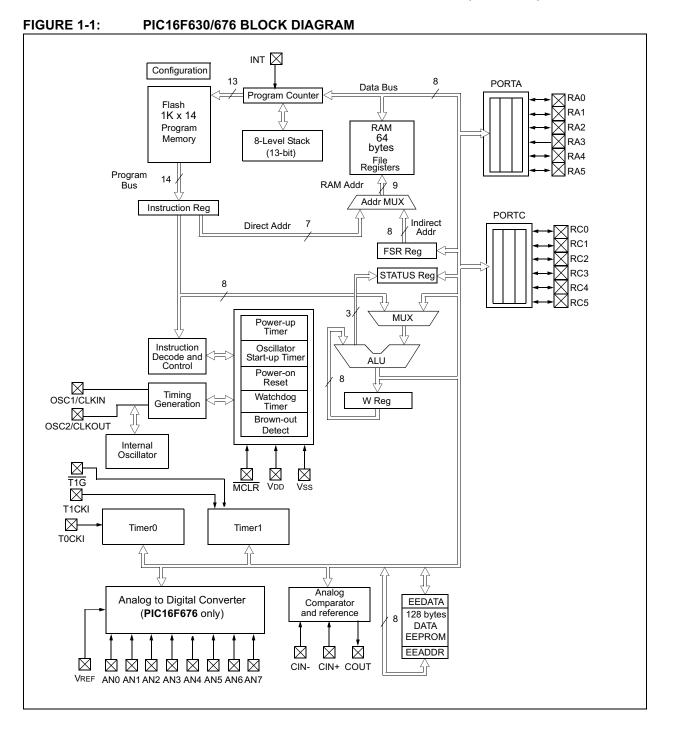


TABLE 1-1: PIC16F630/676 PINOUT DESCRIPTION

Name	Function	Input Type	Output Type	Description
RA0/AN0/CIN+/ICSPDAT	RA0	TTL	CMOS	Bidirectional I/O w/ programmable pull-up and
				interrupt-on-change.
	AN0	AN	—	A/D Channel 0 input.
	CIN+	AN		Comparator input.
	ICSPDAT	TTL	CMOS	Serial Programming Data I/O.
RA1/AN1/CIN-/VREF/ ICSPCLK	RA1	TTL	CMOS	Bidirectional I/O w/ programmable pull-up and interrupt-on-change.
	AN1	AN		A/D Channel 1 input.
	CIN-	AN	_	Comparator input.
	VREF	AN	_	External Voltage reference.
	ICSPCLK	ST	_	Serial Programming Clock.
RA2/AN2/COUT/T0CKI/INT	RA2	ST	CMOS	Bidirectional I/O w/ programmable pull-up and interrupt-on-change.
	AN2	AN	_	A/D Channel 2 input.
	COUT		CMOS	Comparator output.
	T0CKI	ST	_	Timer0 clock input.
	INT	ST	_	External Interrupt.
RA3/MCLR/Vpp	RA3	TTL	_	Input port with interrupt-on-change.
	MCLR	ST	_	Master Clear.
	VPP	HV	_	Programming voltage.
RA4/T1G/AN3/OSC2/ CLKOUT	RA4	TTL	CMOS	Bidirectional I/O w/ programmable pull-up and interrupt-on-change.
	T1G	ST	_	Timer1 gate.
	AN3	AN3	_	A/D Channel 3 input.
	OSC2	_	XTAL	Crystal/Resonator.
	CLKOUT	_	CMOS	Fosc/4 output.
RA5/T1CKI/OSC1/CLKIN	RA5	TTL	CMOS	Bidirectional I/O w/ programmable pull-up and interrupt-on-change.
	T1CKI	ST	_	Timer1 clock.
	OSC1	XTAL	_	Crystal/Resonator.
	CLKIN	ST	_	External clock input/RC oscillator connection.
RC0/AN4	RC0	TTL	CMOS	Bidirectional I/O.
	AN4	AN4	_	A/D Channel 4 input.
RC1/AN5	RC1	TTL	CMOS	Bidirectional I/O.
	AN5	AN5	—	A/D Channel 5 input.
RC2/AN6	RC2	TTL	CMOS	Bidirectional I/O.
	AN6	AN6	—	A/D Channel 6 input.
RC3/AN7	RC3	TTL	CMOS	Bidirectional I/O.
	AN7	AN7		A/D Channel 7 input.
RC4	RC4	TTL	CMOS	Bidirectional I/O.
RC5	RC5	TTL	CMOS	Bidirectional I/O.
Vss	Vss	Power	_	Ground reference.
Vdd	Vdd	Power	_	Positive supply.

Legend: Shade = PIC16F676 only

TTL = TTL input buffer

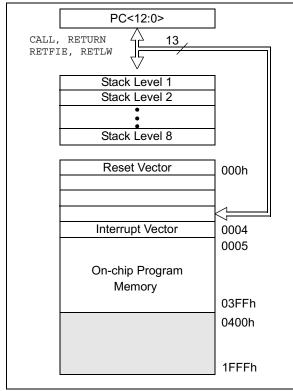
ST = Schmitt Trigger input buffer

2.0 MEMORY ORGANIZATION

2.1 Program Memory Organization

The PIC16F630/676 devices have a 13-bit program counter capable of addressing an 8K x 14 program memory space. Only the first 1K x 14 (0000h-03FFh) for the PIC16F630/676 devices is physically implemented. Accessing a location above these boundaries will cause a wrap around within the first 1K x 14 space. The Reset vector is at 0000h and the interrupt vector is at 0004h (see Figure 2-1).





2.2 Data Memory Organization

The data memory (see Figure 2-2) is partitioned into two banks, which contain the General Purpose Registers and the Special Function Registers. The Special Function Registers are located in the first 32 locations of each bank. Register locations 20h-5Fh are General Purpose Registers, implemented as static RAM and are mapped across both banks. All other RAM is unimplemented and returns '0' when read. RP0 (STATUS<5>) is the bank select bit.

- RP0 = 0 Bank 0 is selected
- RP0 = 1 Bank 1 is selected

Note:	The IRP and RP1 bits STATUS<7:6> are
	reserved and should always be maintained
	as '0's.

2.2.1 GENERAL PURPOSE REGISTER FILE

The register file is organized as 64 x 8 in the PIC16F630/676 devices. Each register is accessed, either directly or indirectly, through the File Select Register FSR (see Section 2.4 "Indirect Addressing, INDF and FSR Registers").

2.2.2 SPECIAL FUNCTION REGISTERS

The Special Function Registers are registers used by the CPU and peripheral functions for controlling the desired operation of the device (see Table 2-1). These registers are static RAM.

The special registers can be classified into two sets: core and peripheral. The Special Function Registers associated with the "core" are described in this section. Those related to the operation of the peripheral features are described in the section of that peripheral feature.

FIGURE 2-2: DATA MEMORY MAP OF THE PIC16F630/676

	THEF	PIC16F630/676	
	File Address	A	File ddress
Indirect addr. ⁽¹⁾	00h	Indirect addr. ⁽¹⁾	80h
TMR0	01h	OPTION_REG	81h
PCL	02h	PCL	82h
STATUS	03h	STATUS	83h
FSR	04h	FSR	84h
PORTA	05h	TRISA	85h
	06h		86h
PORTC	07h	TRISC	87h
	08h		88h
	09h		89h
PCLATH	0Ah	PCLATH	8Ah
INTCON	0Bh	INTCON	8Bh
PIR1	0Ch	PIE1	8Ch
	0Dh		8Dh
TMR1L	0Eh	PCON	8Eh
TMR1H	0Fh		8Fh
T1CON	10h	OSCCAL	90h
	11h	ANSEL ⁽²⁾	91h
	12h	/	92h
	13h		93h
	14h		94h
	15h	WPUA	95h
	16h	IOCA	96h
	17h	100/1	97h
	18h		98h
CMCON	19h	VRCON	99h
	1Ah	EEDAT	9Ah
	1Bh	EEADR	9Bh
	1Ch	EECON1	9Ch
	1Dh	EECON2 ⁽¹⁾	9Dh
ADRESH ⁽²⁾	1Eh	ADRESL ⁽²⁾	9Eh
ADCON0 ⁽²⁾	1Fh	ADCON1 ⁽²⁾	9Fh
71200110	20h	ABOONT	A0h
General Purpose Registers 64 Bytes		accesses 20h-5Fh	
	5Fh		DFh
	60h		E0h
	0011		Lon
D	7Fh		FFh
Bank 0		Bank 1	
Unimplemente1: Not a physical2: PIC16F676 on	register.	mory locations, rea	d as '0'.

TABLE 2-1:	PIC16F630/676 SPECIAL	REGISTERS SUMMARY BANK 0

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOD	Page
Bank 0											
00h	INDF	Addressing	this location	uses content	ts of FSR to a	address data	memory (not	a physical re	gister)	XXXX XXXX	20,63
01h	TMR0	Timer0 Mod	dule's Registe	er						XXXX XXXX	31
02h	PCL	Program Co	ounter's (PC)	Least Signifi	icant Byte	-				0000 0000	19
03h	STATUS	IRP ⁽²⁾	RP1 ⁽²⁾	RP0	TO	PD	Z	DC	С	0001 1xxx	13
04h	FSR	Indirect data	a memory Ac	dress Pointe	r	•	•			XXXX XXXX	20
05h	PORTA	_	_	I/O Control	Registers					xx xxxx	21
06h	_	Unimpleme	nted							-	_
07h	PORTC	_	_	I/O Control	Registers					xx xxxx	28
08h	_	Unimpleme	nted							_	_
09h	_	Unimpleme	nted							_	-
0Ah	PCLATH	· -	_	- 1	Write buffer	for upper 5 b	oits of progra	m counter		0 0000	19
0Bh	INTCON	GIE	PEIE	T0IE	INTE	RAIE	TOIF	INTF	RAIF	0000 0000	15
0Ch	PIR1	EEIF	ADIF	_	_	CMIF	_	_	TMR1IF	00 00	17
0Dh	_	Unimpleme	nted	J			1			_	-
0Eh	TMR1L	Holding reg	ister for the l	east Signific	ant Byte of th	e 16-bit TMR	81			xxxx xxxx	34
0Fh	TMR1H	Holding reg	ister for the I	Most Significa	ant Byte of the	e 16-bit TMR	1			xxxx xxxx	34
10h	T1CON	_	T1GE	T1CKPS1	T1CKPS0	T10SCEN	T1SYNC	TMR1CS	TMR10N	-000 0000	36
11h	_	Unimpleme	nted							-	-
12h	_	Unimpleme	nted							_	_
13h	_	Unimpleme	nted							_	-
14h	_	Unimpleme	nted							_	-
15h	—	Unimpleme	nted							-	-
16h	_	Unimpleme	nted							-	-
17h	—	Unimpleme	nted							-	-
18h	—	Unimpleme	nted							_	-
19h	CMCON	—	COUT	—	CINV	CIS	CM2	CM1	CM0	-0-0 0000	39
1Ah	—	Unimpleme	nted							_	_
1Bh	—	Unimpleme								_	_
1Ch	—	Unimpleme								-	-
1Dh	—	Unimpleme								-	-
1Eh	ADRESH ⁽³⁾	Most Signifi	icant 8 bits o	f the left shifte	ed A/D result	or 2 bits of rig	ght shifted re	sult		XXXX XXXX	46
1Fh	ADCON0 ⁽³⁾	ADFM	VCFG	_	CHS2	CHS1	CHS0	GO/DONE	ADON	00-0 0000	47,63

- = Unimplemented locations read <u>as '0'</u>, <u>u</u> = unchanged, <u>x</u> = unknown, <u>q</u> = value depends on condition shaded = unimplemented Other (non Power-up) Resets include MCLR Reset, Brown-out Detect and Watchdog Timer Reset during normal operation. IRP and RP1 bits are reserved, always maintain these bits clear. PIC16F676 only. Legend: Note 1:

2: 3:

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOD	Page
Bank 1											
80h	INDF	Addressing	this location	uses content	s of FSR to a	address data	memory (not	a physical re	egister)	xxxx xxxx	20,63
81h	OPTION_REG	RAPU	INTEDG	TOCS	TOSE	PSA	PS2	PS1	PS0	1111 1111	14,32
82h	PCL	Program Co	ounter's (PC)							0000 0000	19
83h	STATUS	IRP ⁽²⁾	RP1 ⁽²⁾	RP0	TO	PD	Z	DC	С	0001 1xxx	13
84h	FSR	Indirect data	a memory Ad	_				50		xxxx xxxx	20
85h	TRISA	_	_	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	11 1111	21
86h	_	Unimpleme	nted		•	•		•		-	_
87h	TRISC		_	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	11 1111	_
88h	_	Unimpleme	nted				•		•	-	_
89h	—	Unimpleme	nted							_	_
8Ah	PCLATH	_	_		Write buffer	for upper 5 b	oits of program	m counter		0 0000	19
8Bh	INTCON	GIE	PEIE	T0IE	INTE	RAIE	T0IF	INTF	RAIF	0000 0000	15
8Ch	PIE1	EEIE	ADIE	l	_	CMIE	_	_	TMR1IE	00 00	16
8Dh	—	Unimpleme	nted							-	_
8Eh	PCON	_	_	_	_	_	_	POR	BOD	dd	18
8Fh	_		•				•		•	-	
90h	OSCCAL	CAL5	CAL4	CAL3	CAL2	CAL1	CAL0		_	1000 00	18
91h	ANSEL ⁽³⁾	ANS7	ANS6	ANS5	ANS4	ANS3	ANS2	ANS1	ANS0	1111 1111	48
92h	_	Unimpleme	nted		•	•		•		-	_
93h	_	Unimpleme	nted							-	_
94h	—	Unimpleme	nted							_	_
95h	WPUA	_	_	WPUA5	WPUA4	_	WPUA2	WPUA1	WPUA0	11 -111	22
96h	IOCA	_	_	IOCA5	IOCA4	IOCA3	IOCA2	IOCA1	IOCA0	00 0000	23
97h	—	Unimpleme	nted							_	_
98h	—	Unimpleme	nted							_	_
99h	VRCON	VREN	_	VRR		VR3	VR2	VR1	VR0	0-0- 0000	44
9Ah	EEDAT	EEPROM d	ata register							0000 0000	51
9Bh	EEADR		EEPROM a	ddress regist	er					0000 0000	51
9Ch	EECON1	_	—	—	—	WRERR	WREN	WR	RD	x000	52
9Dh	EECON2	EEPROM o	ontrol registe	r 2 (not a ph	ysical registe	r)					51
9Eh	ADRESL ⁽³⁾	Least Signif	icant 2 bits o	f the left shift	ed result or 8	bits of the ri	ght shifted re	sult		XXXX XXXX	46
9Fh	ADCON1 ⁽³⁾	—	ADCS2	ADCS1	ADCS0	—	—	_	—	-000	47,63

TABLE 2-2: PIC16F630/676 SPECIAL FUNCTION REGISTERS SUMMARY BANK 1

-= Unimplemented locations read as '0', u = unchanged, x = unknown, q = value depends on condition, shaded = unimplemented
Other (non Power-up) Resets include MCLR Reset, Brown-out Detect and Watchdog Timer Reset during normal operation.
IRP and RP1 bits are reserved, always maintain these bits clear.
PIC16F676 only. Legend:

Note 1:

2.2.2.1 STATUS Register

The STATUS register, shown in Register 2-1, contains:

- the arithmetic status of the ALU
- · the Reset status
- the bank select bits for data memory (SRAM)

The STATUS register can be the destination for any instruction, like any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the TO and PD bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, CLRF STATUS will clear the upper three bits and set the Z bit. This leaves the STATUS register as 000u uluu (where u = unchanged).

It is recommended, therefore, that only BCF, BSF, SWAPF and MOVWF instructions are used to alter the STATUS register, because these instructions do not affect any Status bits. For other instructions not affecting any Status bits, see Section 10.0 "Instruction Set Summary".

- **Note 1:** Bits IRP and RP1 (STATUS<7:6>) are not used by the PIC16F630/676 and should be maintained as clear. Use of these bits is not recommended, since this may affect upward compatibility with future products.
 - 2: The <u>C</u> and <u>DC</u> bits operate as a Borrow and <u>Digit</u> Borrow out bit, respectively, in subtraction. See the SUBLW and SUBWF instructions for examples.

REGISTER 2-1:	STATUS — STATUS REGISTER (ADDRESS: 03h OR 83h)
---------------	--

	Reserved	Reserved	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x						
	IRP	RP1	RP0	TO	PD	Z	DC	С						
	bit 7							bit 0						
bit 7	IRP: This b	IRP: This bit is reserved and should be maintained as '0'												
bit 6	RP1: This	bit is reserve	ed and shou	ld be mainta	ained as '0'									
bit 5	1 = Bank 1	ster Bank Se (80h-FFh) (00h-7Fh)	elect bit (use	d for direct a	addressing)									
bit 4	TO : Time-o	()		ction, or SLE	EP instructi	on								
bit 3		-Down bit ower-up or b cution of the			n									
bit 2		sult of an ari sult of an ari		• •		D								
bit 1	 0 = The result of an arithmetic or logic operation is not zero DC: Digit carry/borrow bit (ADDWF, ADDLW, SUBLW, SUBWF instructions) For borrow, the polarity is reversed. 1 = A carry-out from the 4th low order bit of the result occurred 0 = No carry-out from the 4th low order bit of the result 													
bit 0	1 = A carry	prrow bit (AD -out from the ry-out from t	e Most Sign	ificant bit of	the result of	ccurred								
	Note:	complemen	t of the sec	ond operan	d. For rotate	on is execut e (RRF, RLF) e source reg) instructions							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented	bit, read as '0'
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

2.2.2.2 OPTION Register

The OPTION register is a readable and writable register, which contains various control bits to configure:

- TMR0/WDT prescaler
- External RA2/INT interrupt
- TMR0
- Weak pull-ups on PORTA

REGISTER 2-2: OPTION_REG — OPTION REGISTER (ADDRESS: 81h)

	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
	RAPU	INTEDG	TOCS	T0SE	PSA	PS2	PS1	PS0
	bit 7							bit 0
bit 7	1 = PORTA	A pull-ups a	p Enable bit re disabled re enabled l	by individual	PORT latch	values		
bit 6	1 = Interru	pt on rising	ge Select bi edge of RA edge of RA	2/INT pin				
bit 5	1 = Transit	ion on RA2	ource Selec /T0CKI pin n cycle clock	t bit (CLKOUT)				
bit 4	1 = Increm	ent on high		t bit sition on RA2 sition on RA2				
bit 3	1 = Presca	0	ned to the V	VDT imer0 module	Э			
bit 2-0	PS2:PS0:	Prescaler F	Rate Select I	oits				
	ł	Bit Value	TMR0 Rate	WDT Rate				
	-	000 001 010 011 100 101 110 111	1:2 1:4 1:8 1:16 1:32 1:64 1:128 1:256	1 : 1 1 : 2 1 : 4 1 : 8 1 : 16 1 : 32 1 : 64 1 : 128				
	Legend:							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

Note: To achieve a 1:1 prescaler assignment for TMR0, assign the prescaler to the WDT by setting PSA bit to '1' (OPTION<3>). See Section 4.4 "Prescaler".

2.2.2.3 INTCON Register

The INTCON register is a readable and writable register, which contains the various enable and flag bits for TMR0 register overflow, PORTA change and external RA2/INT pin interrupts.

Note: Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

REGISTER 2-3: INTCON — INTERRUPT CONTROL REGISTER (ADDRESS: 0Bh OR 8Bh)

	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
	GIE	PEIE	T0IE	INTE	RAIE	T0IF	INTF	RAIF	
	bit 7							bit 0	
bit 7	1 = Enable	Il Interrupt E s all unmas es all interru	ked interrup	ts					
bit 6	PEIE: Peripheral Interrupt Enable bit 1 = Enables all unmasked peripheral interrupts 0 = Disables all peripheral interrupts								
bit 5	T0IE: TMR0 Overflow Interrupt Enable bit 1 = Enables the TMR0 interrupt 0 = Disables the TMR0 interrupt								
bit 4	INTE: RA2/INT External Interrupt Enable bit 1 = Enables the RA2/INT external interrupt 0 = Disables the RA2/INT external interrupt								
bit 3	1 = Enable	s the PORT	errupt Enab A change in A change ir	terrupt					
bit 2	1 = TMR0	register has	Interrupt Fla overflowed not overflow	(must be cle	eared in soft	ware)			
bit 1	1 = The RA	A2/INT exter	•	Flag bit : occurred (n : did not occ		red in softwa	are)		
bit 0	RAIF: Port Change Interrupt Flag bit 1 = When at least one of the PORTA <5:0> pins changed state (must be cleared in software) 0 = None of the PORTA <5:0> pins have changed state							software)	
	Note 1:	IOCA regis	ter must als	o be enable	d.				
	2:			mer0 rolls o aring T0IF b		is unchange	ed on Reset	and should	
	Legend:								
	R = Reada	ble bit	W = W	/ritable bit	U = Unin	nplemented	bit, read as	'0'	

'1' = Bit is set

'0' = Bit is cleared

- n = Value at POR

x = Bit is unknown

2.2.2.4 PIE1 Register

The PIE1 register contains the interrupt enable bits, as shown in Register 2-4.

Note: Bit PEIE (INTCON<6>) must be set to enable any peripheral interrupt.

	R/W-0	R/W-0	U-0	U-0	R/W-0	U-0	U-0	R/W-0	
	EEIE	ADIE	_	_	CMIE	_	_	TMR1IE	
	bit 7							bit 0	
bit 7	EEIE: EE Write Complete Interrupt Enable bit 1 = Enables the EE write complete interrupt 0 = Disables the EE write complete interrupt								
bit 6	ADIE: A/D Converter Interrupt Enable bit (PIC16F676 only) 1 = Enables the A/D converter interrupt 0 = Disables the A/D converter interrupt								
bit 5-4	Unimplemented: Read as '0'								
bit 3	CMIE: Comparator Interrupt Enable bit 1 = Enables the comparator interrupt 0 = Disables the comparator interrupt								
bit 2-1	Unimpleme	nted: Read	d as ' 0'						
bit 0	TMR1IE: TMR1 Overflow Interrupt Enable bit 1 = Enables the TMR1 overflow interrupt 0 = Disables the TMR1 overflow interrupt								
	Legend:								
	R = Readab	le bit	W = W	/ritable bit	U = Unim	plemented	bit, read as	'0'	
	- n = Value a	at POR	'1' = B	it is set	'0' = Bit is	s cleared	x = Bit is ι	Inknown	

REGISTER 2-4: PIE1 — PERIPHERAL INTERRUPT ENABLE REGISTER 1 (ADDRESS: 8Ch)

2.2.2.5 **PIR1** Register

The PIR1 register contains the interrupt flag bits, as shown in Register 2-5.

- n = Value at POR

Note: Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

PIR1 — PERIPHERAL INTERRUPT REGISTER 1 (ADDRESS: 0Ch) **REGISTER 2-5:**

	R/W-0	R/W-0	U-0	U-0	R/W-0	U-0	U-0	R/W-0	
	EEIF	ADIF	_	_	CMIF	_		TMR1IF	
	bit 7							bit 0	
bit 7	1 = The wr 0 = The wr	ite operatior ite operatior	n completed n has not co	nterrupt Flag (must be cle mpleted or h	eared in soft las not been	,			
bit 6	ADIF: A/D Converter Interrupt Flag bit (PIC16F676 only) 1 = The A/D conversion is complete (must be cleared in software) 0 = The A/D conversion is not complete								
bit 5-4	Unimplem	ented: Rea	d as '0'						
bit 3	CMIF : Comparator Interrupt Flag bit 1 = Comparator input has changed (must be cleared in software) 0 = Comparator input has not changed								
bit 2-1	Unimplem	ented: Rea	d as ' 0'						
bit 0	TMR1IF : TMR1 Overflow Interrupt Flag bit 1 = TMR1 register overflowed (must be cleared in software) 0 = TMR1 register did not overflow								
	Legend:								
	R = Reada	ble bit	W = W	/ritable bit	U = Unin	plemented	bit, read as	ʻ0'	

'0' = Bit is cleared

'1' = Bit is set

x = Bit is unknown

2.2.2.6 PCON Register

The Power Control (PCON) register contains flag bits to differentiate between a:

- · Power-on Reset (POR)
- Brown-out Detect (BOD)
- Watchdog Timer Reset (WDT)
- External MCLR Reset

The PCON Register bits are shown in Register 2-6.

REGISTER 2-6: PCON — POWER CONTROL REGISTER (ADDRESS: 8Eh)

	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-x
	_	—	—	_	_	_	POR	BOD
I	oit 7							bit 0

bit 7-2 Unimplemented: Read as '0'

bit 1 **POR:** Power-on Reset Status bit

1 = No Power-on Reset occurred

0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0 **BOD:** Brown-out Detect Status bit

- 1 = No Brown-out Detect occurred
- 0 = A Brown-out Detect occurred (must be set in software after a Brown-out Detect occurs)

Legend:				
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'		
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown	

2.2.2.7 OSCCAL Register

bit 7-2

bit 1-0

The Oscillator Calibration register (OSCCAL) is used to calibrate the internal 4 MHz oscillator. It contains 6 bits to adjust the frequency up or down to achieve 4 MHz.

The OSCCAL register bits are shown in Register 2-7.

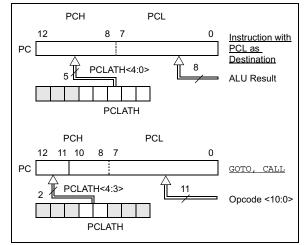
REGISTER 2-7: OSCCAL—INTERNALOSCILLATOR CALIBRATION REGISTER (ADDRESS: 90h)

R/W-1	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0		
CAL5	CAL4	CAL3	CAL2	CAL1	CAL0	—	—		
bit 7							bit (
100000 = C	111111 = Maximum frequency 100000 = Center frequency 000000 = Minimum frequency								
Unimpleme	nted: Read	d as '0'							
Legend:									
R = Readabl	le bit	W = W	ritable bit	U = Unin	nplemented	bit, read as	'0'		
- n = Value a	at POR	'1' = B	t is set	'0' = Bit i	s cleared	x = Bit is u	nknown		

2.3 PCL and PCLATH

The program counter (PC) is 13-bits wide. The low byte comes from the PCL register, which is a readable and writable register. The high byte (PC<12:8>) is not directly readable or writable and comes from PCLATH. On any Reset, the PC is cleared. Figure 2-3 shows the two situations for the loading of the PC. The upper example in Figure 2-3 shows how the PC is loaded on a write to PCL (PCLATH<4:0> \rightarrow PCH). The lower example in Figure 2-3 shows how the PC is loaded during a CALL or GOTO instruction (PCLATH<4:3> \rightarrow PCH).

FIGURE 2-3: LOADING OF PC IN DIFFERENT SITUATIONS



2.3.1 COMPUTED GOTO

A computed GOTO is accomplished by adding an offset to the program counter (ADDWF PCL). When performing a table read using a computed GOTO method, care should be exercised if the table location crosses a PCL memory boundary (each 256-byte block). Refer to the Application Note *"Implementing a Table Read"* (AN556).

2.3.2 STACK

The PIC16F630/676 family has an 8-level x 13-bit wide hardware stack (see Figure 2-1). The stack space is not part of either program or data space and the Stack Pointer is not readable or writable. The PC is PUSHed onto the stack when a CALL instruction is executed or an interrupt causes a branch. The stack is POPed in the event of a RETURN, RETLW or a RETFIE instruction execution. PCLATH is not affected by a PUSH or POP operation.

The stack operates as a circular buffer. This means that after the stack has been PUSHed eight times, the ninth push overwrites the value that was stored from the first push. The tenth push overwrites the second push (and so on).

Note 1: There are no Status bits to indicate Stack Overflow or Stack Underflow conditions.

2: There are no instructions/mnemonics called PUSH or POP. These are actions that occur from the execution of the CALL, RETURN, RETLW and RETFIE instructions or the vectoring to an interrupt address.

2.4 Indirect Addressing, INDF and FSR Registers

The INDF register is not a physical register. Addressing the INDF register will cause indirect addressing.

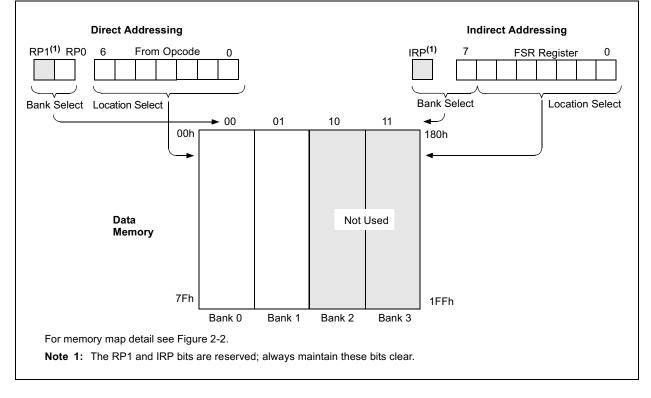
Indirect addressing is possible by using the INDF register. Any instruction using the INDF register actually accesses data pointed to by the File Select Register (FSR). Reading INDF itself indirectly will produce 00h. Writing to the INDF register indirectly results in a no operation (although Status bits may be affected). An effective 9-bit address is obtained by concatenating the 8-bit FSR register and the IRP bit (STATUS<7>), as shown in Figure 2-4.

A simple program to clear RAM location 20h-2Fh using indirect addressing is shown in Example 2-1.

EXAMPLE 2-1: INDIRECT ADDRESSING

	MOVLW	0x20	;initialize pointer
	MOVWF	FSR	;to RAM
NEXT	CLRF	INDF	;clear INDF register
	INCF	FSR	;inc pointer
	BTFSS	FSR,4	;all done?
	GOTO	NEXT	;no clear next
CONTINUE			;yes continue

FIGURE 2-4: DIRECT/INDIRECT ADDRESSING PIC16F630/676



3.0 PORTS A AND C

There are as many as twelve general purpose I/O pins available. Depending on which peripherals are enabled, some or all of the pins may not be available as general purpose I/O. In general, when a peripheral is enabled, the associated pin may not be used as a general purpose I/O pin.

Note:	Additional information on I/O ports may be
	found in the PIC [®] Mid-Range Reference
	Manual, (DS33023)

3.1 PORTA and the TRISA Registers

PORTA is an 6-bit wide, bidirectional port. The corresponding data direction register is TRISA. Setting a TRISA bit (= 1) will make the corresponding PORTA pin an input (i.e., put the corresponding output driver in a High-Impedance mode). Clearing a TRISA bit (= 0) will make the corresponding PORTA pin an output (i.e., put the contents of the output latch on the selected pin). The exception is RA3, which is input only and its TRIS bit will always read as '1'. Example 3-1 shows how to initialize PORTA.

Reading the PORTA register reads the status of the pins, whereas writing to it will write to the PORT latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read, this value is modified and then written to the PORT data latch. RA3 reads '0' when MCLREN = 1.

The TRISA register controls the direction of the PORTA pins, even when they are being used as analog inputs. The user must ensure the bits in the TRISA

register are maintained set when using them as analog inputs. I/O pins configured as analog input always read '0'.

Note:	The ANSEL (91h) and CMCON (19h)					
	registers must be initialized to configure an					
	analog channel as a digital input. Pins					
	configured as analog inputs will read '0'.					
	The ANSEL register is defined for the					
	PIC16F676.					

EXAMPLE 3-1: INITIALIZING PORTA

BCF	STATUS, RPO	;Bank 0
CLRF	PORTA	;Init PORTA
MOVLW	05h	;Set RA<2:0> to
MOVWF	CMCON	;digital I/O
BSF	STATUS, RPO	;Bank 1
CLRF	ANSEL	;digital I/O
MOVLW	0Ch	;Set RA<3:2> as inputs
MOVWF	TRISA	;and set RA<5:4,1:0>
		;as outputs
BCF	STATUS, RPO	;Bank 0
L		

3.2 Additional Pin Functions

Every PORTA pin on the PIC16F630/676 has an interrupt-on-change option and every PORTA pin, except RA3, has a weak pull-up option. The next two sections describe these functions.

3.2.1 WEAK PULL-UP

Each of the PORTA pins, except RA3, has an individually configurable weak internal pull-up. Control bits WPUAx enable or disable each pull-up. Refer to Register 3-3. Each weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are disabled on a Power-on Reset by the RAPU bit (OPTION<7>).

U-0 R/W-x R/W-x R/W-x U-0 R/W-x R/W-x R/W-x RA5 RA4 RA3 RA2 RA1 RA0 bit 7 bit 0 bit 7-6: Unimplemented: Read as '0' bit 5-0: PORTA<5:0>: PORTA I/O pin bits

PORTA — PORTA REGISTER (ADDRESS: 05h)

1 = Port pin is >VIH

0 = Port pin is <VIL

Legend:				
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'		
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown	

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REGISTER 3-1:

REGIS	TER 3-2:	TRISA — PORTA TRI-STATE REGISTER (ADDRESS: 85h)												
		U-0	U-0	R/W-x	R/W-x	R-1	R/W-x	R/W-x	R/W-x					
			_	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0					
		bit 7						•	bit 0					
	bit 7-6:		ented: Rea											
	bit 5-0:			Tri-State Co		I)								
			1 = PORTA pin configured as an input (tri-stated)0 = PORTA pin configured as an output											
		Note: TRISA<3> always reads 1.												
		Note. INIONS diways leaus 1.												
		Legend:												
		R = Reada	ble bit	W = W	Vritable bit	U = Unim	plemented b	oit, read as '	0'					
		- n = Value	at POR	'1' = B	Bit is set	'0 ' = Bit is	cleared	x = Bit is u	nknown					
	TED 2 2.						056)							
REGIS	TER 3-3:	WPUA —	WEAR PU	LL-UP RE	GISTER (A	ADDRESS: 9	9511)							
		U-0	U-0	R/W-1	R/W-1	U-0	R/W-1	R/W-1	R/W-1					
		—	—	WPUA5	WPUA4	_	WPUA2	WPUA1	WPUA0					
		bit 7							bit 0					
	bit 7-6	Unimplem	ented: Rea	d as '∩'										
	bit 7-0	•		ull-up Regist	ter hits									
		1 = Pull-up		ull-up regis										
		0 = Pull-up												
	bit 3	Unimplem	ented: Rea	d as ' 0'										
	bit 2-0	WPUA<2:()>: Weak P	ull-up Regist	ter bits									
		1 = Pull-up												
		0 = Pull-up	disabled											
		Note 1: 0	Blobal RAPU	J must be e	nabled for in	ndividual pull-	ups to be er	abled.						
		2: T	he weak pu	III-up device					node					
		2: The weak pull-up device is automatically disabled if the pin is in Output mode (TRISA = 0).												
	Legend:													
		R = Reada	hla hit	\\/ - \\	/ritable bit	= Inim	nlamanted k	oit, read as '	0'					
		- n = Value			Bit is set	0 – 01111 0' = Bit is		x = Bit is u						
			αι Γ Ο Κ	I – D	011 13 3CL		CIEdi EU							
322	INTERR	UPT-ON-CH	IANGE		This i	nterrupt can	wake the d	evice from	Sleep. The					

3.2.2 INTERRUPT-ON-CHANGE

Each of the PORTA pins is individually configurable as an interrupt-on-change pin. Control bits IOCAx enable or disable the interrupt function for each pin. Refer to Register 3-4. The interrupt-on-change is disabled on a Power-on Reset.

For enabled interrupt-on-change pins, the values are compared with the old value latched on the last read of PORTA. The 'mismatch' outputs of the last read are OR'd together to set, the PORTA Change Interrupt flag bit (RAIF) in the INTCON register. This interrupt can wake the device from Sleep. The user, in the Interrupt Service Routine, can clear the interrupt in the following manner:

- a) Any read or write of PORTA. This will end the mismatch condition.
- b) Clear the flag bit RAIF.

A mismatch condition will continue to set flag bit RAIF. Reading PORTA will end the mismatch condition and allow flag bit RAIF to be cleared.

Note: If a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then the RAIF interrupt flag may not get set.

REGISTER 3-4: IOCA — INTERRUPT-ON-CHANGE PORTA REGISTER (ADDRESS: 96h)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
_	—	IOCA5	IOCA4	IOCA3	IOCA2	IOCA1	IOCA0
bit 7							bit 0

bit 7-6 Unimplemented: Read as '0'

bit 5-0

IOCA<5:0>: Interrupt-on-Change PORTA Control bits

1 = Interrupt-on-change enabled

0 = Interrupt-on-change disabled

Note: Global Interrupt Enable (GIE) must be enabled for individual interrupts to be recognized.

Legend:					
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'			
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown		

3.2.3 PIN DESCRIPTIONS AND DIAGRAMS

Each PORTA pin is multiplexed with other functions. The pins and their combined functions are briefly described here. For specific information about individual functions such as the comparator or the A/D, refer to the appropriate section in this Data Sheet.

3.2.3.1 RA0/AN0/CIN+

Figure 3-1 shows the diagram for this pin. The RA0 pin is configurable to function as one of the following:

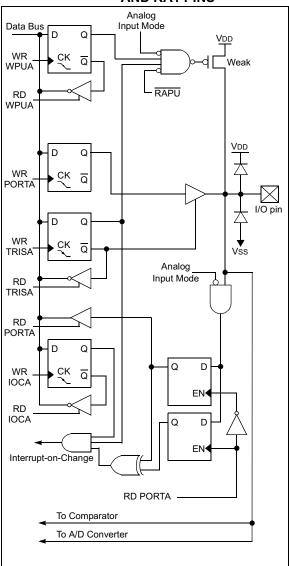
- a general purpose I/O
- an analog input for the A/D (PIC16F676 only)
- · an analog input to the comparator

3.2.3.2 RA1/AN1/CIN-/VREF

Figure 3-1 shows the diagram for this pin. The RA1 pin is configurable to function as one of the following:

- as a general purpose I/O
- an analog input for the A/D (PIC16F676 only)
- an analog input to the comparator
- a voltage reference input for the A/D (PIC16F676 only)

FIGURE 3-1: BLOCK DIAGRAM OF RA0 AND RA1 PINS



3.2.3.3 RA2/AN2/T0CKI/INT/COUT

Figure 3-2 shows the diagram for this pin. The RA2 pin is configurable to function as one of the following:

- a general purpose I/O
- an analog input for the A/D (PIC16F676 only)
- · a digital output from the comparator
- the clock input for TMR0
- an external edge triggered interrupt

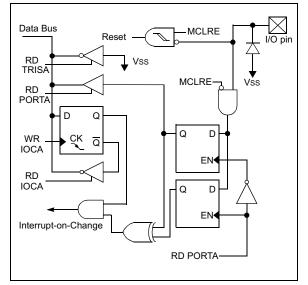
FIGURE 3-2: **BLOCK DIAGRAM OF RA2** Analog Data Bus Input Mode D Q Vdd WR CK Q Weak WPUA RAPU RD WPUA Analog COUT Input Mode Enable Vdd D Q +WR СК Q COUT PORTA 1 \times I/O pin Ż Q D WR **∀** Vss СК Q TRIS. Analog Input Mode RD TRISA RD PORTA Q п D Q WR СК Q IOCA EN RD IOCA Q D ΕN Interrupt-on-Change **RD PORTA** To TMR0 To INT To A/D Converter

3.2.3.4 RA3/MCLR/VPP

Figure 3-3 shows the diagram for this pin. The RA3 pin is configurable to function as one of the following:

- a general purpose input
- as Master Clear Reset

FIGURE 3-3: BLOCK DIAGRAM OF RA3

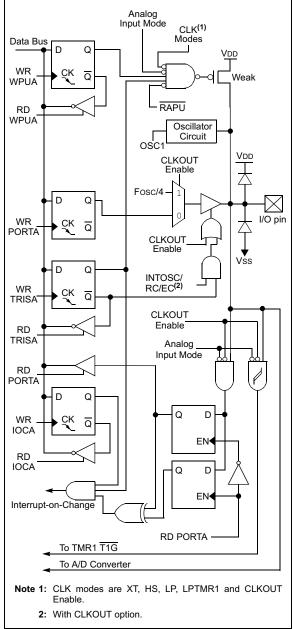


3.2.3.5 RA4/AN3/T1G/OSC2/CLKOUT

Figure 3-4 shows the diagram for this pin. The RA4 pin is configurable to function as one of the following:

- a general purpose I/O
- an analog input for the A/D (PIC16F676 only)
- · a TMR1 gate input
- · a crystal/resonator connection
- · a clock output

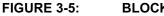
BLOCK DIAGRAM OF RA4 FIGURE 3-4:



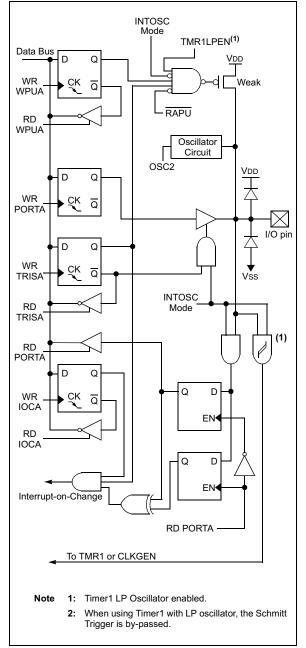
3.2.3.6 RA5/T1CKI/OSC1/CLKIN

Figure 3-5 shows the diagram for this pin. The RA5 pin is configurable to function as one of the following:

- a general purpose I/O
- · a TMR1 clock input
- · a crystal/resonator connection
- · a clock input



BLOCK DIAGRAM OF RA5



Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOD	Value on all other Resets
05h	PORTA	_	—	RA5	RA4	RA3	RA2	RA1	RA0	xx xxxxx	uu uuuu
0Bh/8Bh	INTCON	GIE	PEIE	T0IE	INTE	RAIE	T0IF	INTF	RAIF	0000 0000	0000 000u
19h	CMCON	_	COUT	_	CINV	CIS	CM2	CM1	CM0	-0-0 0000	-0-0 0000
81h	OPTION_REG	RAPU	INTEDG	TOCS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
85h	TRISA	_	_	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	11 1111	11 1111
91h	ANSEL ⁽¹⁾	ANS7	ANS6	ANS5	ANS4	ANS3	ANS2	ANS1	ANS0	1111 1111	1111 1111
95h	WPUA	_		WPUA5	WPUA4	_	WPUA2	WPUA1	WPUA0	11 -111	11 -111
96h	IOCA	_	_	IOCA5	IOCA4	IOCA3	IOCA2	IOCA1	IOCA0	00 0000	00 0000

Note 1: PIC16F676 only.

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by PORTA.

3.3 PORTC

PORTC is a general purpose I/O port consisting of 6 bidirectional pins. The pins can be configured for either digital I/O or analog input to A/D converter. For specific information about individual functions such as the comparator or the A/D, refer to the appropriate section in this Data Sheet.

Note:	The ANSEL register (91h) must be clear to
	configure an analog channel as a digital
	input. Pins configured as analog inputs will
	read '0'. The ANSEL register is defined for
	the PIC16F676.

EXAMPLE 3-2: INITIALIZING PORTC

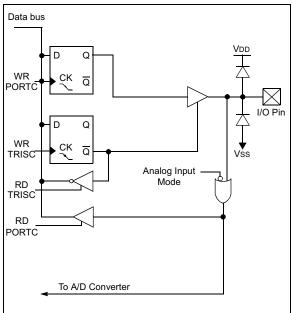
BCF	STATUS, RPO	;Bank 0
CLRF	PORTC	;Init PORTC
BSF	STATUS, RPO	;Bank 1
CLRF	ANSEL	;digital I/O
MOVLW	0Ch	;Set RC<3:2> as inputs
MOVWF	TRISC	;and set RC<5:4,1:0>
		;as outputs
BCF	STATUS, RPO	;Bank 0

3.3.1 RC0/AN4, RC1/AN5, RC2/AN6, RC3/ AN7

The RC0/RC1/RC2/RC3 pins are configurable to function as one of the following:

- a general purpose I/O
- an analog input for the A/D Converter (PIC16F676 only)

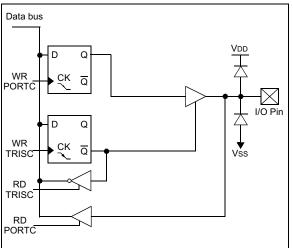




3.3.2 RC4 AND RC5

The RC4 and RC5 pins are configurable to function as a general purpose I/Os.





REGISTER 3-5: PORTC — PORTC REGISTER (ADDRESS: 07h) R/W-x U-0 U-0 R/W-x R/W-x R/W-x R/W-x R/W-x RC5 RC4 RC3 RC2 RC1 RC0 bit 7 bit 0 bit 7-6: Unimplemented: Read as '0' PORTC<5:0>: General Purpose I/O pin bits bit 5-0: 1 = Port pin is >VIH 0 = Port pin is <VIL Legend: R = Readable bit W = Writable bit U = Unimplemented bit, read as '0' '1' = Bit is set - n = Value at POR '0' = Bit is cleared x = Bit is unknown **REGISTER 3-6:** TRISC — PORTC TRI-STATE REGISTER (ADDRESS: 87h) U-0 U-0 R/W-1 R/W-1 R/W-1 R/W-1 R/W-1 R/W-1 TRISC5 TRISC4 TRISC3 TRISC2 TRISC1 TRISC0 bit 7 bit 0 bit 7-6: Unimplemented: Read as '0' bit 5-0: TRISC<5:0>: PORTC Tri-State Control bits 1 = PORTC pin configured as an input (tri-stated) 0 = PORTC pin configured as an output Legend: R = Readable bit W = Writable bit U = Unimplemented bit, read as '0' - n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

TABLE 3-2: SUMMARY OF REGISTERS ASSOCIATED WITH PORTC

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOD	Value on all other Resets
07h	PORTC		-	RC5	RC4	RC3	RC2	RC1	RC0	xx xxxx	uu uuuu
87h	TRISC	_	_	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	11 1111	11 1111
91h	ANSEL ⁽¹⁾	ANS7	ANS6	ANS5	ANS4	ANS3	ANS2	ANS1	ANS0	1111 1111	1111 1111

Note 1: PIC16F676 only.

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by PORTC.

NOTES:

4.0 TIMER0 MODULE

The Timer0 module timer/counter has the following features:

- 8-bit timer/counter
- Readable and writable
- 8-bit software programmable prescaler
- · Internal or external clock select
- Interrupt on overflow from FFh to 00h
- Edge select for external clock

Figure 4-1 is a block diagram of the Timer0 module and the prescaler shared with the WDT.

Note:	Additional information		on	the	Timer0
	module is a	available in the	e PIC	C [®] Mic	d-Range
	Reference	Manual, (DS3	3302	3).	

4.1 Timer0 Operation

Timer mode is selected by clearing the T0CS bit (OPTION_REG<5>). In Timer mode, the Timer0 module will increment every instruction cycle (without prescaler). If TMR0 is written, the increment is inhibited for the following two instruction cycles. The user can work around this by writing an adjusted value to the TMR0 register.

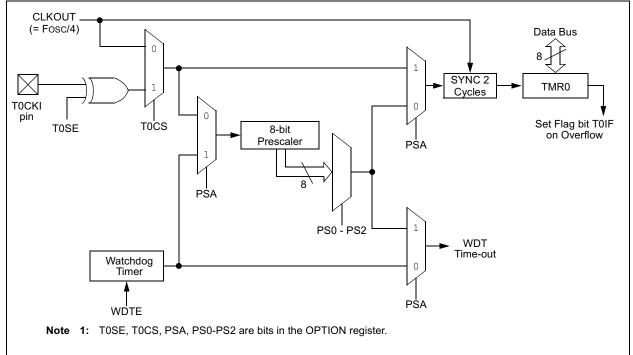
Counter mode is selected by setting the T0CS bit (OPTION_REG<5>). In this mode, the Timer0 module will increment either on every rising or falling edge of pin RA2/T0CKI. The incrementing edge is determined by the source edge (T0SE) control bit (OPTION_REG<4>). Clearing the T0SE bit selects the rising edge.

Note:	requirements.	Additional	ic external clock information on
	these requirem	ients is avai	lable in the PIC®
	Mid-Range (DS33023).	Reference	ce Manual,

4.2 Timer0 Interrupt

A Timer0 interrupt is generated when the TMR0 register timer/counter overflows from FFh to 00h. This overflow sets the T0IF bit. The interrupt can be masked by clearing the T0IE bit (INTCON<5>). The T0IF bit (INTCON<2>) must be cleared in software by the Timer0 module Interrupt Service Routine before reenabling this interrupt. The Timer0 interrupt cannot wake the processor from Sleep since the timer is shut-off during Sleep.





4.3 Using Timer0 with an External Clock

When no prescaler is used, the external clock input is the same as the prescaler output. The synchronization of T0CKI, with the internal phase clocks, is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks. Therefore, it is necessary for T0CKI to be high for at least 2Tosc (and a small RC delay of 20 ns) and low for at least 2Tosc (and a small RC delay of 20 ns). Refer to the electrical specification of the desired device.

Note:	The ANSEL (91h) and CMCON (19h)
	registers must be initialized to configure an
	analog channel as a digital input. Pins
	configured as analog inputs will read '0'.
	The ANSEL register is defined for the
	PIC16F676.

REGISTER 4-1: OPTION_REG — OPTION REGISTER (ADDRESS: 81h)

	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1				
	RAPU	INTEDG	TOCS	T0SE	PSA	PS2	PS1	PS0				
	bit 7							bit 0				
bit 7	RAPU: PORTA Pull-up Enable bit 1 = PORTA pull-ups are disabled											
				by individual	PORT latch	values						
bit 6			lge Select bi			- and o o						
			edge of RA									
	0 = Interru	pt on fallin	g edge of RA	2/INT pin								
bit 5			Source Selec	t bit								
			2/T0CKI pin n cycle clocł									
bit 4			•	. ,								
bit 1		T0SE: TMR0 Source Edge Select bit 1 = Increment on high-to-low transition on RA2/T0CKI pin										
	0 = Incren	nent on low	-to-high tran	sition on RA2	2/T0CKI pin							
bit 3		scaler Assi										
			ned to the V	VDT imer0 modul	2							
bit 2-0			Rate Select		5							
5112 0			TMR0 Rate									
		000 001	1:2 1:4	1:1 1:2								
		010	1:8	1:4								
		011	1 : 16 1 : 32	1 : 8 1 : 16								
		100 101	1:64	1:32								
		110 1:128 1:64										
		111	1 : 256	1 : 128								
	l egend:											
	Legend.	Legend:										

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented I	bit, read as '0'
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

4.4 Prescaler

An 8-bit counter is available as a prescaler for the Timer0 module, or as a postscaler for the Watchdog Timer. For simplicity, this counter will be referred to as "prescaler" throughout this Data Sheet. The prescaler assignment is controlled in software by the control bit PSA (OPTION_REG<3>). Clearing the PSA bit will assign the prescaler to Timer0. Prescale values are selectable via the PS2:PS0 bits (OPTION_REG<2:0>).

The prescaler is not readable or writable. When assigned to the Timer0 module, all instructions writing to the TMR0 register (e.g., CLRF 1, MOVWF 1, BSF 1, x...etc.) will clear the prescaler. When assigned to WDT, a CLRWDT instruction will clear the prescaler along with the Watchdog Timer.

4.4.1 SWITCHING PRESCALER ASSIGNMENT

The prescaler assignment is fully under software control (i.e., it can be changed "on the fly" during program execution). To avoid an unintended device Reset, the following instruction sequence (Example 4-1) must be executed when changing the prescaler assignment from Timer0 to WDT.

EXAMPLE 4-1: CHANGING PRESCALER (TIMER0→WDT)

BCF	STATUS, RPO	;Bank 0
CLRWDT		;Clear WDT
CLRF	TMR0	;Clear TMR0 and
		; prescaler
BSF	STATUS, RPO	;Bank 1
MOVLW	b'00101111'	;Required if desired
MOVWF	OPTION_REG	; PS2:PS0 is
CLRWDT		; 000 or 001
		;
MOVLW	b'00101xxx'	;Set postscaler to
MOVWF	OPTION_REG	; desired WDT rate
BCF	STATUS, RPO	;Bank 0

To change prescaler from the WDT to the TMR0 module, use the sequence shown in Example 4-2. This precaution must be taken even if the WDT is disabled.

EXAMPLE 4-2: CHANGING PRESCALER (WDT→TIMER0)

CLRWDT		;Clear WDT and
BSF	STATUS, RPO	; postscaler ;Bank 1
MOVLW	b'xxxx0xxx'	;Select TMR0, ; prescale, and ; clock source
MOVWF BCF	OPTION_REG STATUS,RPO	; ;Bank O

TABLE 4-1:REGISTERS ASSOCIATED WITH TIMER0

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOD	Value on all other Resets
01h	TMR0	Timer0 M	imer0 Module Register							XXXX XXXX	uuuu uuuu
0Bh/8Bh	INTCON	GIE	PEIE	T0IE	INTE	RAIE	T0IF	INTF	RAIF	0000 0000	0000 000u
81h	OPTION_REG	RAPU	INTEDG	TOCS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
85h	TRISA	—	—	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	11 1111	11 1111

Legend: -= Unimplemented locations, read as '0', u = unchanged, x = unknown. Shaded cells are not used by the Timer0 module.

5.0 TIMER1 MODULE WITH GATE CONTROL

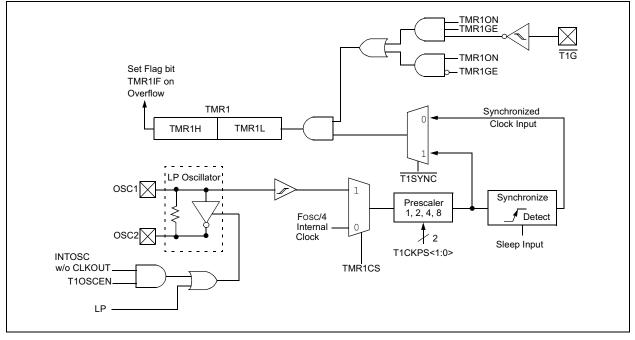
The PIC16F630/676 devices have a 16-bit timer. Figure 5-1 shows the basic block diagram of the Timer1 module. Timer1 has the following features:

- 16-bit timer/counter (TMR1H:TMR1L)
- · Readable and writable
- Internal or external clock selection
- Synchronous or asynchronous operation
- Interrupt on overflow from FFFFh to 0000h
- Wake-up upon overflow (Asynchronous mode)
- Optional external enable input $(\overline{T1G})$
- · Optional LP oscillator

FIGURE 5-1: TIMER1 BLOCK DIAGRAM

The Timer1 Control register (T1CON), shown in Register 5-1, is used to enable/disable Timer1 and select the various features of the Timer1 module.

Note: Additional information on timer modules is available in the PIC[®] Mid-Range Reference Manual, (DS33023).



5.1 Timer1 Modes of Operation

Timer1 can operate in one of three modes:

- 16-bit timer with prescaler
- 16-bit synchronous counter
- · 16-bit asynchronous counter

FIGURE 5-2:

In Timer mode, Timer1 is incremented on every instruction cycle. In Counter mode, Timer1 is incremented on the rising edge of the external clock input T1CKI. In addition, the Counter mode clock can be synchronized to the microcontroller system clock or run asynchronously.

In counter and timer modules, the counter/timer clock can be gated by the $\overline{\text{T1G}}$ input.

If an external clock oscillator is needed (and the microcontroller is using the INTOSC w/o CLKOUT), Timer1 can use the LP oscillator as a clock source.

Note:	In Counter mode, a falling edge must be
	registered by the counter prior to the first
	incrementing rising edge.

TIMER1 INCREMENTING EDGE

5.2 Timer1 Interrupt

The Timer1 register pair (TMR1H:TMR1L) increments to FFFFh and rolls over to 0000h. When Timer1 rolls over, the Timer1 interrupt flag bit (PIR1<0>) is set. To enable the interrupt on rollover, you must set these bits:

- Timer1 interrupt Enable bit (PIE1<0>)
- PEIE bit (INTCON<6>)
- GIE bit (INTCON<7>).

The interrupt is cleared by clearing the TMR1IF in the Interrupt Service Routine.

Note: The TMR1H:TTMR1L register pair and the TMR1IF bit should be cleared before enabling interrupts.

5.3 Timer1 Prescaler

Timer1 has four prescaler options allowing 1, 2, 4, or 8 divisions of the clock input. The T1CKPS bits (T1CON<5:4>) control the prescale counter. The prescale counter is not directly readable or writable; however, the prescaler counter is cleared upon a write to TMR1H or TMR1L.

T1CKI = 1 when TMR1 Enabled T1CKI = 0 when TMR1 Enabled Note 1: Arrows indicate counter increments. 2: In Counter mode, a falling edge must be registered by the counter prior to the first incrementing rising edge of the

clock.

STER 5-1:	T1CON — TIMER1 CONTROL REGISTER (ADDRESS: 10h)									
	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0		
	—	TMR1GE	1CKPS1	T1CKPS0	T1OSCEN	T1SYNC	TMR1CS	TMR10N		
	bit 7							bit 0		
bit 7	Unimplom	ontod: Pood	ac '0'							
bit 6	Unimplemented: Read as '0' TMR1GE: Timer1 Gate Enable bit									
DILO	If TMR10E.									
	This bit is i	ignored								
	If TMR10		nin in Invu							
	1 = Timer1 0 = Timer1	is on if T1G	pin is low							
bit 5-4	T1CKPS1:T1CKPS0: Timer1 Input Clock Prescale Select bits									
bit o 1	11 = 1:8 Prescale Value									
		rescale Value								
		rescale Value rescale Value								
bit 3				Control bit						
DIL J	T1OSCEN: LP Oscillator Enable Control bit If INTOSC without CLKOUT oscillator is active:									
	1 = LP osc	illator is enab			_					
		cillator is off								
	<u>Else:</u> This bit is i	ianored								
bit 2		•	nal Clock I	nout Synchr	onization Co	ntrol bit				
	T1SYNC: Timer1 External Clock Input Synchronization Control bit <u>TMR1CS = 1:</u>									
		synchronize								
	0 = Synchi <u>TMR1CS</u> =	ronize externa -	al clock inp	but						
		<u></u> ignored. Time	r1 uses th	e internal clo	ock.					
bit 1	TMR1CS: Timer1 Clock Source Select bit									
	1 = External clock from T1OSO/T1CKI pin (on the rising edge)									
		al clock (Fosc	,							
bit 0	TMR1ON: 1 = Enable	Timer1 On bi	t							
	$1 - Enable 0 = Stops^{-1}$									
	° Cicpo									
	Legend:									
	R = Reada	able bit	W = V	Vritable bit	U = Unim	plemented	bit, read as	'0'		
	- n = Value	e at POR	'1' = E	Bit is set	'0' = Bit is	s cleared	x = Bit is u	Inknown		

REGISTER 5-1: T1CON — TIMER1 CONTROL REGISTER (ADDRESS: 10h)

5.4 Timer1 Operation in Asynchronous Counter Mode

If control bit $\overline{T1SYNC}$ (T1CON<2>) is set, the external clock input is not synchronized. The timer continues to increment asynchronous to the internal phase clocks. The timer will continue to run during Sleep and can generate an interrupt on overflow, which will wake-up the processor. However, special precautions in software are needed to read/write the timer (Section 5.4.1).

Note:	The ANSEL (91h) and CMCON (19h)
	registers must be initialized to configure an
	analog channel as a digital input. Pins
	configured as analog inputs will read '0'.
	The ANSEL register is defined for the
	PIC16F676.

5.4.1 READING AND WRITING TIMER1 IN ASYNCHRONOUS COUNTER MODE

Reading TMR1H or TMR1L, while the timer is running from an external asynchronous clock, will ensure a valid read (taken care of in hardware). However, the user should keep in mind that reading the 16-bit timer in two 8-bit values itself, poses certain problems, since the timer may overflow between the reads.

For writes, it is recommended that the user simply stop the timer and write the desired values. A write contention may occur by writing to the timer registers, while the register is incrementing. This may produce an unpredictable value in the timer register.

Reading the 16-bit value requires some care. Examples 12-2 and 12-3 in the PIC[®] Mid-Range MCU Family Reference Manual (DS33023) show how to read and write Timer1 when it is running in Asynchronous mode.

5.5 Timer1 Oscillator

A crystal oscillator circuit is built-in between pins OSC1 (input) and OSC2 (amplifier output). It is enabled by setting control bit T1OSCEN (T1CON<3>). The oscillator is a low power oscillator rated up to 32 kHz. It will continue to run during Sleep. It is primarily intended for a 32 kHz crystal. Table 9-2 shows the capacitor selection for the Timer1 oscillator.

The Timer1 oscillator is shared with the system LP oscillator. Thus, Timer1 can use this mode only when the system clock is derived from the internal oscillator. As with the system LP oscillator, the user must provide a software time delay to ensure proper oscillator start-up.

TRISA5 and TRISA4 bits are set when the Timer1 oscillator is enabled. RA5 and RA4 read as '0' and TRISA5 and TRISA4 bits read as '1'.

Note: The oscillator requires a start-up and stabilization time before use. Thus, T1OSCEN should be set and a suitable delay observed prior to enabling Timer1.

5.6 Timer1 Operation During Sleep

Timer1 can only operate during Sleep when setup in Asynchronous Counter mode. In this mode, an external crystal or clock source can be used to increment the counter. To setup the timer to wake the device:

- Timer1 must be on (T1CON<0>)
- TMR1IE bit (PIE1<0>) must be set
- PEIE bit (INTCON<6>) must be set

The device will wake-up on an overflow. If the GIE bit (INTCON<7>) is set, the device will wake-up and jump to the Interrupt Service Routine on an overflow.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value POR,			e on other sets
0Bh/8Bh	INTCON	GIE	PEIE	T0IE	INTE	RAIE	T0IF	INTF	RAIF	0000	0000	0000	000u
0Ch	PIR1	EEIF	ADIF		_	CMIF	_	_	TMR1IF	00	00	00	00
0Eh	TMR1L	Holding	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								XXXX	uuuu	uuuu
0Fh	TMR1H	Holding	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register							XXXX	XXXX	uuuu	uuuu
10h	T1CON	_	TMR1GE	T1CKPS1	T1CKPS0	T1OSCEN	T1SYNC	TMR1CS	TMR10N	-000	0000	-uuu	uuuu
8Ch	PIE1	EEIE	ADIE		_	CMIE	_	_	TMR1IE	00	00	00	00

 TABLE 5-1:
 REGISTERS ASSOCIATED WITH TIMER1 AS A TIMER/COUNTER

 $\label{eq:Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by the Timer1 module.$

NOTES:

6.0 **COMPARATOR MODULE**

The PIC16F630/676 devices have one analog comparator. The inputs to the comparator are multiplexed with the RA0 and RA1 pins. There is an on-chip Comparator Voltage Reference that can also be applied to an input of the comparator. In addition, RA2 can be configured as the comparator output. The Comparator Control Register (CMCON), shown in Register 6-1, contains the bits to control the comparator.

REGISTER 6-1: CMCON — COMPARATOR CONTROL REGISTER (ADDRESS: 19h)

	U-0	R-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0		
	—	COUT	—	CINV	CIS	CM2	CM1	CM0		
	bit 7							bit 0		
bit 7	Unimplem	Unimplemented: Read as '0'								
bit 6	<u>When CIN</u> 1 = VIN+ > 0 = VIN+ < <u>When CIN</u> 1 = VIN+ <	COUT: Comparator Output bit <u>When CINV = 0:</u> 1 = VIN+ > VIN- 0 = VIN+ < VIN- <u>When CINV = 1:</u> 1 = VIN+ < VIN- 0 = VIN+ > VIN-								
bit 5	Unimplem	Unimplemented: Read as '0'								
bit 4	1 = Output	CINV: Comparator Output Inversion bit 1 = Output inverted 0 = Output not inverted								
bit 3	<u>When CM2</u> 1 = VIN- co	arator Input <u>CM0 = 110</u> nnects to C nnects to C	<u>) or 101:</u> IN+							
bit 2-0		Comparato shows the 0		modes and (CM2:CM0 bi	it settings				
	Legend:									
	D - Doodo	bla bit	$\lambda \Lambda I = \lambda \Lambda$	/ritable bit	II – I Inim	anlomontod	hit road ac	' ∩'		

- J				
R = Readable bit	W = Writable bit	U = Unimplemented	bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown	

6.1 Comparator Operation

A single comparator is shown in Figure 6-1, along with the relationship between the analog input levels and the digital output. When the analog input at VIN+ is less than the analog input VIN-, the output of the comparator is a digital low level. When the analog input at VIN+ is greater than the analog input VIN-, the output of the comparator is a digital high level. The shaded areas of the output of the comparator in Figure 6-1 represent the uncertainty due to input offsets and response time.

Note:	To use	CIN+	and	CIN-	pins	as ana	alog
	inputs,	the	appro	priate	bits	must	be
	program	imed i	in the (CMCC	DN (19	h) regis	ster.

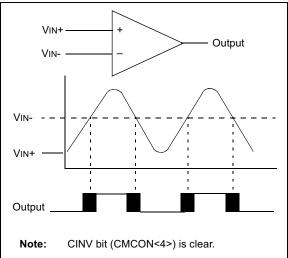
The polarity of the comparator output can be inverted by setting the CINV bit (CMCON<4>). Clearing CINV results in a non-inverted output. A complete table showing the output state versus input conditions and the polarity bit is shown in Table 6-1.

TABLE 6-1: OUTPUT STATE VS. INPUT CONDITIONS

Input Conditions	CINV	COUT
VIN- > VIN+	0	0
VIN- < VIN+	0	1
VIN- > VIN+	1	1
VIN- < VIN+	1	0



SINGLE COMPARATOR



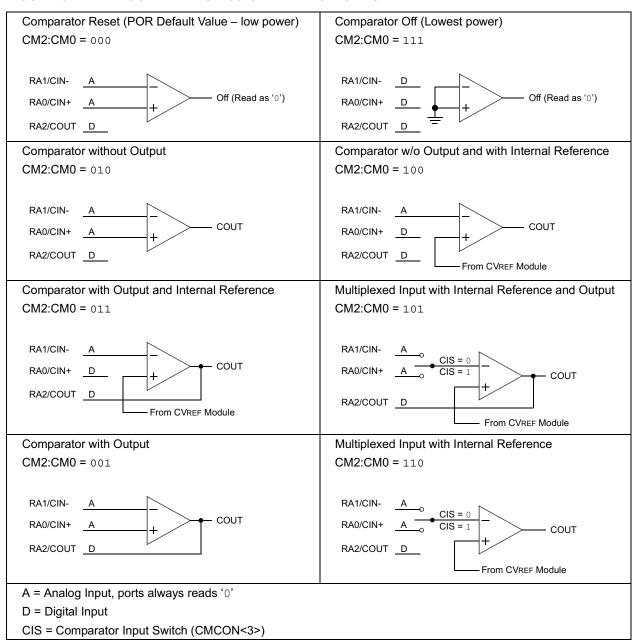
6.2 Comparator Configuration

There are eight modes of operation for the comparator. The CMCON register, shown in Register 6-1, is used to select the mode. Figure 6-2 shows the eight possible modes. The TRISA register controls the data direction of the comparator pins for each mode. If the Comparator mode is changed, the comparator output

FIGURE 6-2: COMPARATOR I/O OPERATING MODES

level may not be valid for a specified period of time. Refer to the specifications in **Section 12.0** "**Electri**cal Specifications".

Note: Comparator interrupts should be disabled during a Comparator mode change. Otherwise, a false interrupt may occur.

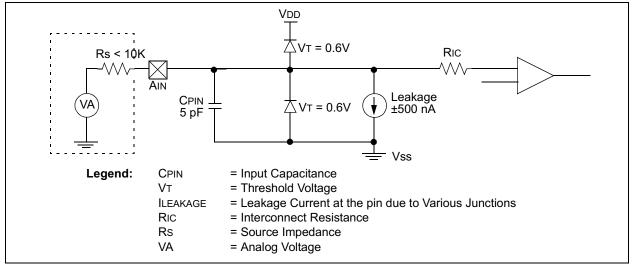


6.3 Analog Input Connection Considerations

A simplified circuit for an analog input is shown in Figure 6-3. Since the analog pins are connected to a digital output, they have reverse biased diodes to VDD and Vss. The analog input, therefore, must be between Vss and VDD. If the input voltage deviates from this

range by more than 0.6V in either direction, one of the diodes is forward biased and a latch-up may occur. A maximum source impedance of $10 \text{ k}\Omega$ is recommended for the analog sources. Any external component connected to an analog input pin, such as a capacitor or a Zener diode, should have very little leakage current.

FIGURE 6-3: ANALOG INPUT MODE



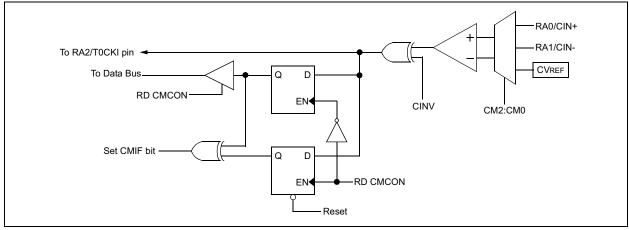
6.4 Comparator Output

The comparator output, COUT, is read through the CMCON register. This bit is read-only. The comparator output may also be directly output to the RA2 pin in three of the eight possible modes, as shown in Figure 6-2. When in one of these modes, the output on RA2 is asynchronous to the internal clock. Figure 6-4 shows the comparator output block diagram.

The TRISA<2> bit functions as an output enable/ disable for the RA2 pin while the comparator is in an Output mode.

- Note 1: When reading the PORTA register, all pins configured as analog inputs will read as a '0'. Pins configured as digital inputs will convert an analog input according to the TTL input specification.
 - 2: Analog levels on any pin that is defined as a digital input, may cause the input buffer to consume more current than is specified.

FIGURE 6-4: MODIFIED COMPARATOR OUTPUT BLOCK DIAGRAM



6.5 Comparator Reference

The comparator module also allows the selection of an internally generated voltage reference for one of the comparator inputs. The internal reference signal is used for four of the eight Comparator modes. The VRCON register, Register 6-2, controls the voltage reference module shown in Figure 6-5.

6.5.1 CONFIGURING THE VOLTAGE REFERENCE

The voltage reference can output 32 distinct voltage levels, 16 in a high range and 16 in a low range.

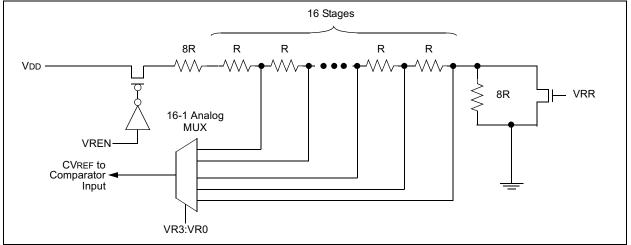
The following equations determine the output voltages:

$VRR = 1$ (low range): $CVREF = (VR3: VR0 / 24) \times VDD$
VRR = 0 (high range): $CVREF = (VDD / 4) + (VR3:VR0 x)$
VDD / 32)

6.5.2 VOLTAGE REFERENCE ACCURACY/ERROR

The full range of VSS to VDD cannot be realized due to the construction of the module. The transistors on the top and bottom of the resistor ladder network (Figure 6-5) keep CVREF from approaching VSS or VDD. The Voltage Reference is VDD derived and therefore, the CVREF output changes with fluctuations in VDD. The tested absolute accuracy of the Comparator Voltage Reference can be found in **Section 12.0 "Electrical Specifications"**.





6.6 Comparator Response Time

Response time is the minimum time, after selecting a new reference voltage or input source, before the comparator output is ensured to have a valid level. If the internal reference is changed, the maximum delay of the internal voltage reference must be considered when using the comparator outputs. Otherwise, the maximum delay of the comparators should be used (Table 12-7).

6.7 Operation During Sleep

Both the comparator and voltage reference, if enabled before entering Sleep mode, remain active during Sleep. This results in higher Sleep currents than shown in the power-down specifications. The additional current consumed by the comparator and the voltage reference is shown separately in the specifications. To minimize power consumption while in Sleep mode, turn off the comparator, CM2:CM0 = 111, and voltage reference, VRCON<7> = 0.

While the comparator is enabled during Sleep, an interrupt will wake-up the device. If the device wakes up from Sleep, the contents of the CMCON and VRCON registers are not affected.

6.8 Effects of a Reset

A device Reset forces the CMCON and VRCON registers to their Reset states. This forces the comparator module to be in the Comparator Reset mode, CM2:CM0 = 000 and the voltage reference to its off state. Thus, all potential inputs are analog inputs with the comparator and voltage reference disabled to consume the smallest current possible.

	moon				NOLNEO			UNI)
	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	VREN	_	VRR	_	VR3	VR2	VR1	VR0
	bit 7							bit 0
bit 7	1 = CVREF	REF Enable circuit powe circuit powe		no IDD drain				
bit 6	Unimplemented: Read as '0'							
bit 5	VRR: CVREF Range Selection bit 1 = Low range 0 = High range							
bit 4	Unimplem	ented: Rea	d as '0'					
bit 3-0	VR3:VR0: CVREF value selection bits $0 \le VR$ [3:0] ≤ 15 When VRR = 1: CVREF = (VR3:VR0 / 24) * VDD When VRR = 0: CVREF = VDD/4 + (VR3:VR0 / 32) * VDD							
	Legend:							
	R = Reada	ble bit	W = W	/ritable bit	U = Unim	plemented	bit, read as	'0'
	- n = Value	at POR	'1' = B	it is set	'0' = Bit i	s cleared	x = Bit is u	inknown

REGISTER 6-2: VRCON — VOLTAGE REFERENCE CONTROL REGISTER (ADDRESS: 99h)

6.9 Comparator Interrupts

The comparator interrupt flag is set whenever there is a change in the output value of the comparator. Software will need to maintain information about the status of the output bits, as read from CMCON<6>, to determine the actual change that has occurred. The CMIF bit, PIR1<3>, is the comparator interrupt flag. This bit must be reset in software by clearing it to '0'. Since it is also possible to write a '1' to this register, a simulated interrupt may be initiated.

The CMIE bit (PIE1<3>) and the PEIE bit (INTCON<6>) must be set to enable the interrupt. In addition, the GIE bit must also be set. If any of these bits are cleared, the interrupt is not enabled, though the CMIF bit will still be set if an interrupt condition occurs.

The user, in the Interrupt Service Routine, can clear the interrupt in the following manner:

- a) Any read or write of CMCON. This will end the mismatch condition.
- b) Clear flag bit CMIF.

A mismatch condition will continue to set flag bit CMIF. Reading CMCON will end the mismatch condition and allow flag bit CMIF to be cleared.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOD	Value on all other Resets
0Bh/8Bh	INTCON	GIE	PEIE	T0IE	INTE	RAIE	T0IF	INTF	RAIF	0000 0000	0000 000u
0Ch	PIR1	EEIF	ADIF	—	—	CMIF	—	—	TMR1IF	00 00	00 00
19h	CMCON	—	COUT	—	CINV	CIS	CM2	CM1	CM0	-0-0 0000	-0-0 0000
8Ch	PIE1	EEIE	ADIE	_	_	CMIE	_	_	TMR1IE	00 00	00 00
85h	TRISA	—	_	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	11 1111	11 1111
99h	VRCON	VREN		VRR		VR3	VR2	VR1	VR0	0-0- 0000	0-0- 0000

TABLE 6-2: REGISTERS ASSOCIATED WITH COMPARATOR MODULE

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by the comparator module.

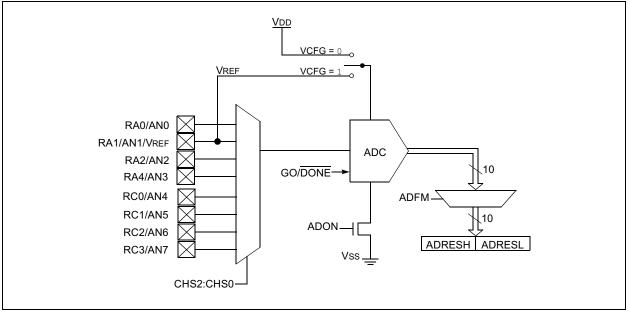
Note: If a change in the CMCON register (COUT) should occur when a read operation is being executed (start of the Q2 cycle), then the CMIF (PIR1<3>) interrupt flag may not get set.

7.0 ANALOG-TO-DIGITAL CONVERTER (A/D) MODULE (PIC16F676 ONLY)

The Analog-to-Digital Converter (ADC) allows conversion of an analog input signal to a 10-bit binary representation of that signal. The PIC16F676 has eight analog inputs, multiplexed into one sample and hold

FIGURE 7-1: A/D BLOCK DIAGRAM

circuit. The output of the sample and hold is connected to the input of the converter. The converter generates a binary result via successive approximation and stores the result in a 10-bit register. The voltage reference used in the conversion is software selectable to either VDD or a voltage applied by the VREF pin. Figure 7-1 shows the block diagram of the A/D on the PIC16F676.



7.1 A/D Configuration and Operation

There are three registers available to control the functionality of the A/D module:

- 1. ADCON0 (Register 7-1)
- 2. ADCON1 (Register 7-2)
- 3. ANSEL (Register 7-3)

7.1.1 ANALOG PORT PINS

The ANS7:ANS0 bits (ANSEL<7:0>) and the TRISA bits control the operation of the A/D port pins. Set the corresponding TRISA bits to set the pin output driver to its high-impedance state. Likewise, set the corresponding ANS bit to disable the digital input buffer.

Note: Analog voltages on any pin that is defined as a digital input may cause the input buffer to conduct excess current.

7.1.2 CHANNEL SELECTION

There are eight analog channels on the PIC16F676, AN0 through AN7. The CHS2:CHS0 bits (ADCON0<4:2>) control which channel is connected to the sample and hold circuit.

7.1.3 VOLTAGE REFERENCE

There are two options for the voltage reference to the A/D converter: either VDD is used, or an analog voltage applied to VREF is used. The VCFG bit (ADCON0<6>) controls the voltage reference selection. If VCFG is set, then the voltage on the VREF pin is the reference; otherwise, VDD is the reference.

7.1.4 CONVERSION CLOCK

The A/D conversion cycle requires 11 TAD. The source of the conversion clock is software selectable via the ADCS bits (ADCON1<6:4>). There are seven possible clock options:

- Fosc/2
- Fosc/4
- Fosc/8
- Fosc/16
- Fosc/32
- Fosc/64
- · FRC (dedicated internal oscillator)

For correct conversion, the A/D conversion clock (1/TaD) must be selected to ensure a minimum TAD of 1.6 μ s. Table 7-1 shows a few TAD calculations for selected frequencies.

TABLE 7-1: TAD vs. DEVICE OPERATING FREQUENCIES

A/D Clock	(Source (TAD)	Device Frequency						
Operation	ADCS2:ADCS0	20 MHz	5 MHz	4 MHz	1.25 MHz			
2 Tosc	000	100 ns ⁽²⁾	400 ns ⁽²⁾	500 ns ⁽²⁾	1.6 μs			
4 Tosc	100	200 ns ⁽²⁾	800 ns ⁽²⁾	1.0 μs ⁽²⁾	3.2 μs			
8 Tosc	001	400 ns ⁽²⁾	1.6 μs	2.0 μs	6.4 μs			
16 Tosc	101	800 ns ⁽²⁾	3.2 μs	4.0 μs	12.8 μs ⁽³⁾			
32 Tosc	010	1.6 μs	6.4 μs	8.0 μs ⁽³⁾	25.6 μs ⁽³⁾			
64 Tosc	110	3.2 μs	12.8 μs ⁽³⁾	16.0 μs ⁽³⁾	51.2 μs ⁽³⁾			
A/D RC	x11	2 - 6 μs ^(1,4)						

Legend: Shaded cells are outside of recommended range.

Note 1: The A/D RC source has a typical TAD time of 4 μ s for VDD > 3.0V.

- 2: These values violate the minimum required TAD time.
- 3: For faster conversion times, the selection of another clock source is recommended.
- 4: When the device frequency is greater than 1 MHz, the A/D RC clock source is only recommended if the conversion will be performed during Sleep.

7.1.5 STARTING A CONVERSION

The A/D conversion is initiated by setting the GO/DONE bit (ADCON0<1>). When the conversion is complete, the A/D module:

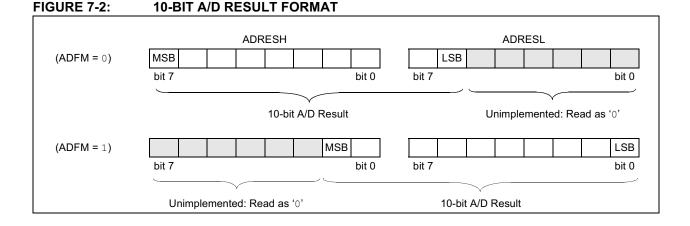
- Clears the GO/DONE bit
- Sets the ADIF flag (PIR1<6>)
- · Generates an interrupt (if enabled)

If the conversion must be aborted, the GO/DONE bit can be cleared in software. The ADRESH:ADRESL registers will not be updated with the partially complete A/D conversion sample. Instead, the ADRESH:ADRESL registers will retain the value of the previous conversion. After an aborted conversion, a 2 TAD delay is required before another acquisition can be initiated. Following the delay, an input acquisition is automatically started on the selected channel.

Note: The GO/DONE bit should not be set in the same instruction that turns on the A/D.

7.1.6 CONVERSION OUTPUT

The A/D conversion can be supplied in two formats: left or right shifted. The ADFM bit (ADCON0<7>) controls the output format. Figure 7-2 shows the output formats.



	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0					
	ADFM	VCFG	_	CHS2	CHS1	CHS0	GO/DONE	ADON					
	bit 7							bit 0					
bit 7	ADFM: A/[1 = Right ji 0 = Left jus		med Select	bit									
bit 6		VCFG: Voltage Reference bit 1 = VREF pin 0 = VDD											
bit 5	Unimplem	ented: Rea	d as zero										
bit 4-2	000 = Cha 001 = Cha 010 = Cha 100 = Cha 101 = Cha 101 = Cha 110 = Cha	50: Analog (annel 00 (AN annel 01 (AN annel 02 (AN annel 03 (AN annel 04 (AN annel 05 (AN annel 06 (AN annel 07 (AN	NO) N1) N2) N3) N4) N5) N6)	ect bits									
bit 1	GO/DONE 1 = A/D co This bit	 GO/DONE: A/D Conversion Status bit 1 = A/D conversion cycle in progress. Setting this bit starts an A/D conversion cycle. This bit is automatically cleared by hardware when the A/D conversion has completed. 0 = A/D conversion completed/not in progress 											
bit 0	 1 = A/D converter module is operating 0 = A/D converter is shut-off and consumes no operating current 												
	Legend:												
	R = Reada			/ritable bit		•	l bit, read as '(
	- n = Value	at POR	.1. = B	it is set	.0. = Bit i	s cleared	x = Bit is ur	iknown					
REGISTER 7-2:	ADCON1	— A/D CO	NTROL RE	EGISTER 1	I (ADRESS	6: 9Fh)							
	U-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0					
		ADCS2	ADCS1	ADCS0			0-0						
	bit 7	ADOOZ	ADOUT	ADCOU				bit 0					
								bit 0					
bit 7:	Unimplem	ented: Rea	d as '∩'										
bit 6-4:	-	>: A/D Conv		k Salact hits	-								
bit 0-4.	000 = Fos				5								
	000 = FOS												
	010 = Fos	c/32		x11 = FRC (clock derived from a dedicated internal oscillator = 500 kHz max)									
	x11 = FRC	(clock deriv	ed from a d	edicated inte	ernal oscillat	or = 500 kH	Iz max)						
	x11 = FRC 100 = FOS	(clock deriv c/4	ed from a de	edicated inte	ernal oscillat	or = 500 kH	Iz max)						
	x11 = FRC 100 = FOS 101 = FOS	(clock deriv c/4 c/16	ed from a d	edicated inte	ernal oscillat	or = 500 kH	Hz max)						
bit 3-0:	x11 = FRC 100 = FOS 101 = FOS 110 = FOS	(clock deriv c/4 c/16		edicated inte	ernal oscillat	or = 500 kH	Ηz max)						
bit 3-0:	x11 = FRC 100 = FOS 101 = FOS 110 = FOS	(clock deriv c/4 c/16 c/64		edicated inte	ernal oscillat	or = 500 kH	Ηz max)						
bit 3-0:	x11 = FRC 100 = FOS 101 = FOS 110 = FOS	(clock deriv c/4 c/16 c/64		edicated inte	ernal oscillat	or = 500 kH	Ηz max)						
bit 3-0:	x11 = FRC 100 = Fos 101 = Fos 110 = Fos Unimplem	(clock deriv c/4 c/16 c/64 eented: Rea	d as '0'	edicated inte			Hz max) it, read as '0'						

REGISTER 7-1: ADCON0 — A/D CONTROL REGISTER (ADDRESS: 1Fh)

REGISTER 7-3:	ANSEL — ANALOG SELECT REGISTER (ADRESS: 91h) (PIC16F676 ONLY)
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	R/W-1							
	ANS7	ANS6	ANS5	ANS4	ANS3	ANS2	ANS1	ANS0
bi	it 7							bit 0

bit 7-0: **ANS<7:0>**: Analog Select between analog or digital function on pins AN<7:0>, respectively. 1 = Analog input. Pin is assigned as analog input.⁽¹⁾

0 = Digital I/O. Pin is assigned to port or special function.

Note 1: Setting a pin to an analog input automatically disables the digital input circuitry, weak pull-ups, and interrupt-on-change if available. The corresponding TRIS bit must be set to Input mode in order to allow external control of the voltage on the pin.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented	bit, read as '0'
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

7.2 A/D Acquisition Requirements

For the A/D converter to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 7-3. The source impedance (Rs) and the internal sampling switch (Rss) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (Rss) impedance varies over the device voltage (VDD), see Figure 7-3. The maximum recommended impedance for analog sources is 10 k\Omega. As the impedance

EQUATION 7-1: ACQUISITION TIME

is decreased, the acquisition time may be decreased. After the analog input channel is selected (changed), this acquisition must be done before the conversion can be started.

To calculate the minimum acquisition time, Equation 7-1 may be used. This equation assumes that 1/2 LSb error is used (1024 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified resolution.

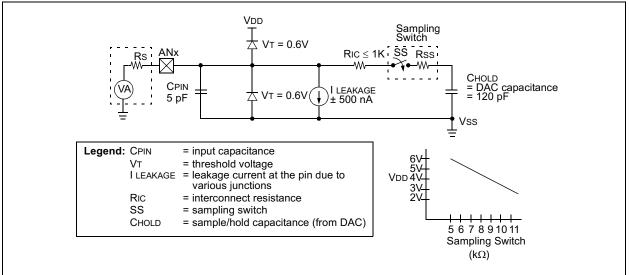
To calculate the minimum acquisition time, TACQ, see the PIC[®] Mid-Range Reference Manual (DS33023).

TACQ	= Amplifier Settling Time + Hold Capacitor Charging Time + Temperature Coefficient
Тс	= TAMP + TC + TCOFF = $2\mu s$ + TC + [(Temperature -25°C)(0.05 μs /°C)] = CHOLD (RIC + RSS + RS) In(1/2047) = -120pF (1k Ω + 7k Ω + 10k Ω) In(0.0004885)
TACQ	= 16.47μs = 2μs + 16.47μs + [(50°C -25°C)(0.05μs/°C) = 19.72μs

Note 1: The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

- **2:** The charge holding capacitor (CHOLD) is not discharged after each conversion.
- **3:** The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.





7.3 A/D Operation During Sleep

The A/D converter module can operate during Sleep. This requires the A/D clock source to be set to the internal oscillator. When the RC clock source is selected, the A/D waits one instruction before starting the conversion. This allows the SLEEP instruction to be executed, thus eliminating much of the switching noise from the conversion. When the conversion is complete, the GO/DONE bit is cleared, and the result is loaded into the ADRESH:ADRESL registers. If the A/D interrupt is enabled, the device awakens from Sleep. If the A/D interrupt is not enabled, the A/D module is turned off, although the ADON bit remains set. When the A/D clock source is something other than RC, a SLEEP instruction causes the present conversion to be aborted, and the A/D module is turned off. The ADON bit remains set.

7.4 Effects of Reset

A device Reset forces all registers to their Reset state. Thus, the A/D module is turned off and any pending conversion is aborted. The ADRESH:ADRESL registers are unchanged.

IADLL	1- <u>2</u> . (DICEOR							
Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOD	Value on all other Resets
05h	PORTA	—	—	PORTA5	PORTA4	PORTA3	PORTA2	PORTA1	PORTA0	xx xxxx	uu uuuu
07h	PORTC	—	—	PORTC5	PORTC4	PORTC3	PORTC2	PORTC1	PORTC0	xx xxxx	uu uuuu
0Bh, 8Bh	INTCON	GIE	PEIE	T0IE	INTE	RAIE	T0IF	INTF	RAIF	0000 0000	0000 000u
0Ch	PIR1	EEIF	ADIF	_	—	CMIF	—	_	TMR1IF	00 00	00 00
1Eh	ADRESH	Most Signi	ficant 8 bits	of the Left	Shifted A/D	result or 2 l	bits of the R	light Shifted	Result	XXXX XXXX	uuuu uuuu
1Fh	ADCON0	ADFM	VCFG		CHS2	CHS1	CHS0	GO	ADON	00-0 0000	00-0 0000
85h	TRISA	—	—	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	11 1111	11 1111
87h	TRISC	—	—	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	11 1111	11 1111
8Ch	PIE1	EEIE	ADIE	_	—	CMIE	—	_	TMR1IE	00 00	00 00
91h	ANSEL	ANS7	ANS6	ANS5	ANS4	ANS3	ANS2	ANS1	ANS0	1111 1111	1111 1111
9Eh	ADRESL	Least Sign	ificant 2 bits	s of the Left	Shifted A/D	Result or 8	3 bits of the	Right Shifte	ed Result	XXXX XXXX	uuuu uuuu
9Fh	ADCON1	—	ADCS2	ADCS1	ADCS0	—	—	_	_	-000	-000

TABLE 7-2: SUMMARY OF A/D REGISTERS

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used for A/D converter module.

8.0 DATA EEPROM MEMORY

The EEPROM data memory is readable and writable during normal operation (full VDD range). This memory is not directly mapped in the register file space. Instead, it is indirectly addressed through the Special Function Registers. There are four SFRs used to read and write this memory:

- EECON1
- EECON2 (not a physically implemented register)
- EEDATA
- EEADR

EEDATA holds the 8-bit data for read/write, and EEADR holds the address of the EEPROM location being accessed. PIC16F630/676 devices have 128 bytes of data EEPROM with an address range from 0h to 7Fh. The EEPROM data memory allows byte read and write. A byte write automatically erases the location and writes the new data (erase before write). The EEPROM data memory is rated for high erase/write cycles. The write time is controlled by an on-chip timer. The write time will vary with voltage and temperature as well as from chip to chip. Please refer to AC Specifications for exact limits.

When the data memory is code-protected, the CPU may continue to read and write the data EEPROM memory. The device programmer can no longer access this memory.

Additional information on the data EEPROM is available in the ${\rm PIC}^{\circledast}$ Mid-Range Reference Manual, (DS33023).

REGISTER 8-1: EEDAT — EEPROM DATA REGISTER (ADDRESS: 9Ah)

| R/W-0 |
|--------|--------|--------|--------|--------|--------|--------|--------|
| EEDAT7 | EEDAT6 | EEDAT5 | EEDAT4 | EEDAT3 | EEDAT2 | EEDAT1 | EEDAT0 |
| bit 7 | | | | | | | bit 0 |

bit 7-0 **EEDATn**: Byte value to write to or read from data EEPROM

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented	bit, read as '0'
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

REGISTER 8-2: EEADR — EEPROM ADDRESS REGISTER (ADDRESS: 9Bh)

U-0	R/W-0						
—	EADR6	EADR5	EADR4	EADR3	EADR2	EADR1	EADR0
bit 7							bit 0

bit 7 Unimplemented: Should be set to '0'

bit 6-0 **EEADR**: Specifies one of 128 locations for EEPROM Read/Write Operation

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented	bit, read as '0'
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

8.1 EEADR

The EEADR register can address up to a maximum of 128 bytes of data EEPROM. Only seven of the eight bits in the register (EEADR<6:0>) are required. The MSb (bit 7) is ignored.

The upper bit should always be '0' to remain upward compatible with devices that have more data EEPROM memory.

8.2 EECON1 AND EECON2 REGISTERS

EECON1 is the control register with four low order bits physically implemented. The upper four bits are non-implemented and read as '0's.

Control bits RD and WR initiate read and write, respectively. These bits cannot be cleared, only set, in software. They are cleared in hardware at completion

- n

of the read or write operation. The inability to clear the WR bit in software prevents the accidental, premature termination of a write operation.

The WREN bit, when set, will allow a write operation. On power-up, the WREN bit is clear. The WRERR bit is set when a write operation is interrupted by a MCLR Reset, or a WDT Time-out Reset during normal operation. In these situations, following Reset, the user can check the WRERR bit, clear it, and rewrite the location. The data and address will be cleared, therefore, the EEDATA and EEADR registers will need to be re-initialized.

The Interrupt flag bit EEIF in the PIR1 register is set when the write is complete. This bit must be cleared in software.

EECON2 is not a physical register. Reading EECON2 will read all '0's. The EECON2 register is used exclusively in the data EEPROM write sequence.

REGISTER 8-3: EECON1 — EEPROM CONTROL REGISTER (ADDRESS: 9Ch)

ER 8-3:	EECON1 –	- EEPROI		OL REGIS	IER (ADDI	RESS: 9Ch	1)	
	U-0	U-0	U-0	U-0	R/W-x	R/W-0	R/S-0	R/S-0
	—	_	_	_	WRERR	WREN	WR	RD
	bit 7							bit 0
bit 7-4	Unimpleme	ented: Read	d as '0'					
bit 3	WRERR: E	EPROM Er	ror Flag bit					
		operation of	BOD detec		l (any MCLR	Reset, any	WDT Reset	during
bit 2	WREN: EE	PROM Writ	e Enable bit					
	1 = Allows v 0 = Inhibits	,		ОМ				
bit 1	WR: Write C	Control bit						
		be set, no	t cleared, in	software.)	hardware or ete	nce write is o	complete. Th	ne WR bit
bit 0	RD: Read C	ontrol bit						
			0M read (Re t cleared, in		ne cycle. RD	is cleared in	n hardware.	The RD bit
	0 = Does no	ot initiate ar	EEPROM	read				
	Legend:							
	S = Bit can	only be set						
	R = Readab	ole bit	W = W	/ritable bit	U = Unim	plemented	bit, read as '	0'

- Readable bit		0 – Unimplemented	i bit, read as 0	
n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown	

8.3 READING THE EEPROM DATA MEMORY

To read a data memory location, the user must write the address to the EEADR register and then set control bit RD (EECON1<0>), as shown in Example 8-1. The data is available in the very next cycle in the EEDATA register. Therefore, it can be read in the next instruction. EEDATA holds this value until another read, or until it is written to by the user (during a write operation).

EXAMPLE 8-1: DATA EEPROM READ

BSF	STATUS, RPO	;Bank 1
MOVLW	CONFIG_ADDR	;
MOVWF	EEADR	;Address to read
BSF	EECON1,RD	;EE Read
MOVF	EEDATA,W	;Move data to W

8.4 WRITING TO THE EEPROM DATA MEMORY

To write an EEPROM data location, the user must first write the address to the EEADR register and the data to the EEDATA register. Then the user must follow a specific sequence to initiate the write for each byte, as shown in Example 8-2.

EXAMPLE 8-2: DATA EEPROM WRITE

ſ		BSF	STATUS, RPO	;Bank 1
		BSF	EECON1,WREN	;Enable write
		BCF	INTCON,GIE	;Disable INTs
		MOVLW	55h	;Unlock write
	ed	MOVWF	EECON2	;
	equir	MOVLW	AAh	;
	Sec	MOVWF	EECON2	;
		BSF	EECON1,WR	;Start the write
		BSF	INTCON,GIE	;Enable INTS

The write will not initiate if the above sequence is not exactly followed (write 55h to EECON2, write AAh to EECON2, then set WR bit) for each byte. We strongly recommend that interrupts be disabled during this code segment. A cycle count is executed during the required sequence. Any number that is not equal to the required cycles to execute the required sequence will prevent the data from being written into the EEPROM.

Additionally, the WREN bit in EECON1 must be set to enable write. This mechanism prevents accidental writes to data EEPROM due to errant (unexpected) code execution (i.e., lost programs). The user should keep the WREN bit clear at all times, except when updating EEPROM. The WREN bit is not cleared by hardware. After a write sequence has been initiated, clearing the WREN bit will not affect this write cycle. The WR bit will be inhibited from being set unless the WREN bit is set.

At the completion of the write cycle, the WR bit is cleared in hardware and the EE Write Complete Interrupt Flag bit (EEIF) is set. The user can either enable this interrupt or poll this bit. The EEIF bit (PIR<7>) register must be cleared by software.

8.5 WRITE VERIFY

Depending on the application, good programming practice may dictate that the value written to the data EEPROM should be verified (see Example 8-3) to the desired value to be written.

EXAMPLE 8-3: WRITE VERIFY

BCF	STATUS, RPO	;Bank 0
:		;Any code
BSF	STATUS, RPO	;Bank 1 READ
MOVF	EEDATA,W	;EEDATA not changed
		;from previous write
BSF	EECON1,RD	;YES, Read the
		;value written
XORWF	EEDATA,W	
BTFSS	STATUS,Z	;Is data the same
GOTO	WRITE_ERR	;No, handle error
:		;Yes, continue

8.5.1 USING THE DATA EEPROM

The data EEPROM is a high-endurance, byte addressable array that has been optimized for the storage of frequently changing information (e.g., program variables or other data that are updated often). Frequently changing values will typically be updated more often than specifications D120 or D120A. If this is not the case, an array refresh must be performed. For this reason, variables that change infrequently (such as constants, IDs, calibration, etc.) should be stored in Flash program memory.

8.6 PROTECTION AGAINST SPURIOUS WRITE

There are conditions when the user may not want to write to the data EEPROM memory. To protect against spurious EEPROM writes, various mechanisms have been built in. On power-up, WREN is cleared. Also, the Power-up Timer (72 ms duration) prevents EEPROM write.

The write initiate sequence and the WREN bit together help prevent an accidental write during:

- brown-out
- power glitch
- software malfunction

8.7 DATA EEPROM OPERATION DURING CODE-PROTECT

Data memory can be code-protected by programming the CPD bit to '0'.

When the data memory is code-protected, the CPU is able to read and write data to the data EEPROM. It is recommended to code-protect the program memory when code protecting data memory. This prevents anyone from programming zeroes over the existing code (which will execute as NOPS) to reach an added routine, programmed in unused program memory, which outputs the contents of data memory. Programming unused locations to '0' will also help prevent data memory code protection from becoming breached.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0		e on BOD	Value otł Res	ner
0Ch	PIR1	EEIF	ADIF	_		CMIF	_		TMR1IF	00	00	00	00
9Ah	EEDATA	EEPROM	1 Data Reg	gister						0000	0000	0000	0000
9Bh	EEADR	_	EEPRON	1 Address	Register					-000	0000	-000	0000
9Ch	EECON1	_	—	—	—	WRERR	WREN	WR	RD		x000		q000
9Dh	EECON2 ⁽¹⁾	EEPROM	1 Control F	Register 2									

TABLE 8-1: REGISTERS/BITS ASSOCIATED WITH DATA EEPROM

Legend: x = unknown, u = unchanged, - = unimplemented read as '0', q = value depends upon condition. Shaded cells are not used by the data EEPROM module.

Note 1: EECON2 is not a physical register.

9.0 SPECIAL FEATURES OF THE CPU

Certain special circuits that deal with the needs of real time applications are what sets a microcontroller apart from other processors. The PIC16F630/676 family has a host of such features intended to:

- maximize system reliability
- minimize cost through elimination of external components
- provide power-saving operating modes and offer code protection

These features are:

- Oscillator selection
- Reset
 - Power-on Reset (POR)
 - Power-up Timer (PWRT)
 - Oscillator Start-up Timer (OST)
 - Brown-out Detect (BOD)
- Interrupts
- Watchdog Timer (WDT)
- Sleep
- Code protection
- · ID Locations
- In-Circuit Serial Programming[™]

The PIC16F630/676 has a Watchdog Timer that is controlled by Configuration bits. It runs off its own RC oscillator for added reliability. There are two timers that offer necessary delays on power-up. One is the Oscillator Start-up Timer (OST), intended to keep the chip in Reset until the crystal oscillator is stable. The other is the Power-up Timer (PWRT), which provides a fixed delay of 72 ms (nominal) on power-up only, designed to keep the part in Reset while the power supply stabilizes. There is also circuitry to reset the device if a brown-out occurs, which can provide at least a 72 ms Reset. With these three functions on-chip, most applications need no external Reset circuitry.

The Sleep mode is designed to offer a very low current Power-down mode. The user can wake-up from Sleep through:

- External Reset
- · Watchdog Timer wake-up
- An interrupt

Several oscillator options are also made available to allow the part to fit the application. The INTOSC option saves system cost while the LP crystal option saves power. A set of Configuration bits are used to select various options (see Register 9-1).

9.1 Configuration Bits

The Configuration bits can be programmed (read as '0'), or left unprogrammed (read as '1') to select various device configurations, as shown in Register 9-1. These bits are mapped in program memory location 2007h.

Note: Address 2007h is beyond the user program memory space. It belongs to the special configuration memory space (2000h-3FFFh), which can be accessed only during programming. See PIC16F630/676 Programming Specification for more information.

REGISTER 9-1: CONFIG — CONFIGURATION WORD (ADDRESS: 2007h)

R/P-1	R/P-	U-0	U-0	U-0	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	
BG1	BG0		_	_	CPD	CP	BODEN	MCLRE	PWRTE	WDTE	F0SC2	F0SC1	F0SC0	
bit 13													bit 0	
bit 13-	0	0 = Low): Bandga est bandg iest bandg	ap voltag	ge	for BOE) and POI	R voltage	(1)					
bit 11-9	9 L	Inimpler	nented: F	Read as '	0'									
bit 8	1 0	CPD: Data Code Protection bit ⁽²⁾ 1 = Data memory code protection is disabled 0 = Data memory code protection is enabled												
bit 7	1 0	CP : Code Protection bit ⁽³⁾ L = Program Memory code protection is disabled D = Program Memory code protection is enabled												
bit 6	1 0	BODEN: Brown-out Detect Enable bit ⁽⁴⁾ 1 = BOD enabled 0 = BOD disabled												
bit 5	1 0	MCLRE: RA3/MCLR pin function select bit ⁽⁵⁾ 1 = RA3/MCLR pin function is MCLR 0 = RA3/MCLR pin function is digital I/O, MCLR internally tied to VDD												
bit 4	1	PWRTE : Power-up Timer Enable bit 1 = PWRT disabled 0 = PWRT enabled												
bit 3	1	= WDT		Fimer En	able bit									
bit 2-0	1 1 1 0 0 0	0 = WDT disabled FOSC2:FOSC0 : Oscillator Selection bits 111 = RC oscillator: CLKOUT function on RA4/OSC2/CLKOUT pin, RC on RA5/OSC1/CLKIN 110 = RC oscillator: I/O function on RA4/OSC2/CLKOUT pin, RC on RA5/OSC1/CLKIN 101 = INTOSC oscillator: CLKOUT function on RA4/OSC2/CLKOUT pin, I/O function on RA5/OSC1/CLKIN 100 = INTOSC oscillator: I/O function on RA4/OSC2/CLKOUT pin, I/O function on RA5/OSC1/CLKIN 111 = EC: I/O function on RA4/OSC2/CLKOUT pin, CLKIN on RA5/OSC1/CLKIN 110 = HS oscillator: High speed crystal/resonator on RA4/OSC2/CLKOUT and RA5/OSC1/CLKIN 111 = XT oscillator: Crystal/resonator on RA4/OSC2/CLKOUT and RA5/OSC1/CLKIN 112 = C oscillator: Low power crystal on RA4/OSC2/CLKOUT and RA5/OSC1/CLKIN												
		 Note 1: The Bandgap Calibration bits are factory programmed and must be read and saved prior to erasing the device as specified in the PIC16F630/676 Programming Specification. These bits are reflected in an export of the Configuration Word. Microchip Development Tools maintain all calibration bits to factory settings. 2: The entire data EEPROM will be erased when the code protection is turned off. 3: The entire program memory will be erased, including OSCCAL value, when the code protection is turned off. 4: Enabling Brown-out Detect does not automatically enable Power-up Timer. 5: When MCLR is asserted in INTOSC or RC mode, the internal clock oscillator is disabled. 												
		.egend: P = Proar	rammed u	sing ICS	P™									
		R = Read				/ = Writa	ble bit	U =	Unimplen	nented b	it, read a	as 'O'		
	-	n = Value	e at POR		1	= bit is s	set		oit is clea			t is unkn	own	

9.2 Oscillator Configurations

9.2.1 OSCILLATOR TYPES

The PIC16F630/676 can be operated in eight different Oscillator Option modes. The user can program three Configuration bits (FOSC2 through FOSC0) to select one of these eight modes:

- LP Low-Power Crystal
- XT Crystal/Resonator
- HS High Speed Crystal/Resonator
- RC External Resistor/Capacitor (2 modes)
- · INTOSC Internal Oscillator (2 modes)
- EC External Clock In

Note:	Additional information on oscillator config- urations is available in the PIC [®] Mid-Range
	Reference Manual, (DS33023).

9.2.2 CRYSTAL OSCILLATOR / CERAMIC RESONATORS

In XT, LP or HS modes a crystal or ceramic resonator is connected to the OSC1 and OSC2 pins to establish oscillation (see Figure 9-1). The PIC16F630/676 oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may yield a frequency outside of the crystal manufacturers specifications. When in XT, LP or HS modes, the device can have an external clock source to drive the OSC1 pin (see Figure 9-2).

FIGURE 9-1: CRYSTAL OPERATION (OR CERAMIC RESONATOR) (HS, XT OR LP OSC CONFIGURATION)

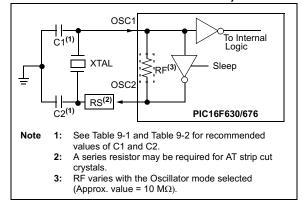
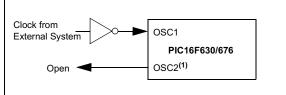


FIGURE 9-2:

EXTERNAL CLOCK INPUT OPERATION (HS, XT, EC, OR LP OSC CONFIGURATION)



Note 1: Functions as RA4 in EC Osc mode.

TABLE 9-1:CAPACITOR SELECTION FOR
CERAMIC RESONATORS

	Ranges Characterized:												
Mode	Freq	OSC1(C1)	OSC2(C2)										
ХТ	455 kHz 2.0 MHz 4.0 MHz	68-100 pF 15-68 pF 15-68 pF	68-100 pF 15-68 pF 15-68 pF										
HS	8.0 MHz 16.0 MHz	10-68 pF 10-22 pF	10-68 pF 10-22 pF										
Note 1:	of the oscilla start-up time guidance on its own char consult the r	citance increase ator but also incr e. These values Ily. Since each r acteristics, the u resonator manuf values of extern c.	eases the are for design esonator has user should acturer for										

TABLE 9-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATOR

ORIGIAE ODDIEEATOR											
Mode	Freq	OSC1(C1)	OSC2(C2)								
LP	32 kHz	68-100 pF	68-100 pF								
ХТ	100 kHz 2 MHz 4 MHz	68-150 pF 15-30 pF 15-30 pF	150-200 pF 15-30 pF 15-30 pF								
HS	8 MHz 10 MHz 20 MHz	15-30 pF 15-30 pF 15-30 pF	15-30 pF 15-30 pF 15-30 pF								
Note 1:	• ·	citance increase	-								

of the oscillator but also increases the start-up time. These values are for design guidance only. Rs may be required in HS mode as well as XT mode to avoid overdriving crystals with low drive level specification. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values of external components.

9.2.3 EXTERNAL CLOCK IN

For applications where a clock is already available elsewhere, users may directly drive the PIC16F630/ 676 provided that this external clock source meets the AC/DC timing requirements listed in **Section 12.0 "Electrical Specifications"**. Figure 9-2 shows how an external clock circuit should be configured.

9.2.4 RC OSCILLATOR

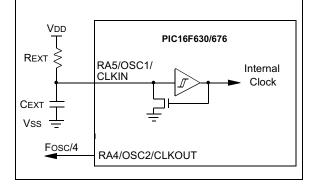
For applications where precise timing is not a requirement, the RC oscillator option is available. The operation and functionality of the RC oscillator is dependent upon a number of variables. The RC oscillator frequency is a function of:

- Supply voltage
- Resistor (REXT) and capacitor (CEXT) values
- Operating temperature

The oscillator frequency will vary from unit to unit due to normal process parameter variation. The difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low CEXT values. The user also needs to account for the tolerance of the external R and C components. Figure 9-3 shows how the R/C combination is connected.

Two options are available for this Oscillator mode which allow RA4 to be used as a general purpose I/O or to output Fosc/4.

FIGURE 9-3: RC OSCILLATOR MODE



9.2.5 INTERNAL 4 MHz OSCILLATOR

When calibrated, the internal oscillator provides a fixed 4 MHz (nominal) system clock. See Electrical Specifications, **Section 12.0** "Electrical Specifications", for information on variation over voltage and temperature.

Two options are available for this Oscillator mode which allow RA4 to be used as a general purpose I/O or to output Fosc/4.

9.2.5.1 Calibrating the Internal Oscillator

A calibration instruction is programmed into the last location of program memory. This instruction is a RETLW XX, where the literal is the calibration value. The literal is placed in the OSCCAL register to set the calibration of the internal oscillator. Example 9-1 demonstrates how to calibrate the internal oscillator. For best operation, decouple (with capacitance) VDD and Vss as close to the device as possible.

Note: Erasing the device will also erase the preprogrammed internal calibration value for the internal oscillator. The calibration value must be saved prior to erasing part as specified in the PIC16F630/676 Programming specification. Microchip Development Tools maintain all calibration bits to factory settings.

EXAMPLE 9-1: CALIBRATING THE INTERNAL OSCILLATOR

BSF CALL	STATUS, 3FFh	RP0	;Bank 1 ;Get the cal value
MOVWF	OSCCAL		;Calibrate
BCF	STATUS,	RP0	;Bank 0

9.2.6 CLKOUT

The PIC16F630/676 devices can be configured to provide a clock out signal in the INTOSC and RC Oscillator modes. When configured, the oscillator frequency divided by four (Fosc/4) is output on the RA4/OSC2/CLKOUT pin. Fosc/4 can be used for test purposes or to synchronize other logic.

9.3 Reset

The PIC16F630/676 differentiates between various kinds of Reset:

- a) Power-on Reset (POR)
- b) WDT Reset during normal operation
- c) WDT Reset during Sleep
- d) MCLR Reset during normal operation
- e) MCLR Reset during Sleep
- f) Brown-out Detect (BOD)

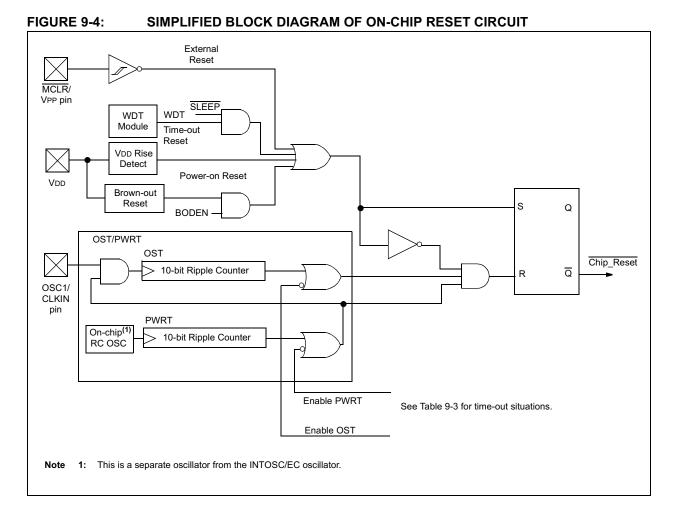
Some registers are not affected in any Reset condition; their status is unknown on POR and unchanged in any other Reset. Most other registers are reset to a "Reset state" on:

- · Power-on Reset
- MCLR Reset
- WDT Reset
- WDT Reset during Sleep
- Brown-out Detect (BOD)

They are not affected by a WDT wake-up, since this is viewed as the resumption of normal operation. $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits are set or cleared differently in different Reset situations as indicated in Table 9-4. These bits are used in software to determine the nature of the Reset. See Table 9-7 for a full description of Reset states of all registers.

A simplified block diagram of the On-Chip Reset Circuit is shown in Figure 9-4.

The $\overline{\text{MCLR}}$ Reset path has a noise filter to detect and ignore small pulses. See Table 12-4 in Electrical Specifications Section for pulse-width specification.



9.3.1 MCLR

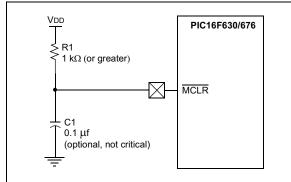
PIC16F630/676 devices have a noise filter in the MCLR Reset path. The filter will detect and ignore small pulses.

It should be noted that a WDT Reset does not drive MCLR pin low.

The behavior of the ESD protection on the $\overline{\text{MCLR}}$ pin has been altered from previous devices of this family. Voltages applied to the pin that exceed its specification can result in both $\overline{\text{MCLR}}$ Resets and excessive current beyond the device specification during the ESD event. For this reason, Microchip recommends that the $\overline{\text{MCLR}}$ pin no longer be tied directly to VDD. The use of an RC network, as shown in Figure 9-5, is suggested.

An internal MCLR option is enabled by setting the MCLRE bit in the Configuration Word. When enabled, MCLR is internally tied to VDD. No internal pull-up option is available for the MCLR pin.

FIGURE 9-5: RECOMMENDED MCLR CIRCUIT



9.3.2 POWER-ON RESET (POR)

The on-chip POR circuit holds the chip in Reset until VDD has reached a high enough level for proper operation. To take advantage of the POR, simply tie the MCLR pin through a resistor to VDD. This will eliminate external RC components usually needed to create Power-on Reset. A maximum rise time for VDD is required. See Section 12.0 "Electrical Specifications" for details. If the BOD is enabled, the maximum rise time specification does not apply. The BOD circuitry will keep the device in Reset until VDD reaches VBOD (see Section 9.3.5 "Brown-out Detect (BOD)").

Note:	The POR circuit does not produce an inter-
	nal Reset when VDD declines.

When the device starts normal operation (exits the Reset condition), device operating parameters (i.e., voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in Reset until the operating conditions are met.

For additional information, refer to Application Note AN607 "Power-up Trouble Shooting."

9.3.3 POWER-UP TIMER (PWRT)

The Power-up Timer provides a fixed 72 ms (nominal) time-out on power-up only, from POR or Brown-out Detect. The Power-up Timer operates on an internal RC oscillator. The chip is kept in Reset as long as PWRT is active. The PWRT delay allows the <u>VDD to</u> rise to an acceptable level. A Configuration bit, <u>PWRTE</u> can disable (if set) or enable (if cleared or programmed) the Power-up Timer. The Power-up Timer should always be enabled when Brown-out Detect is enabled.

The Power-up Time delay will vary from chip to chip and due to:

- VDD variation
- Temperature variation
- · Process variation.

See DC parameters for details (Section 12.0 "Electrical Specifications").

9.3.4 OSCILLATOR START-UP TIMER (OST)

The Oscillator Start-up Timer (OST) provides a 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over. This ensures that the crystal oscillator or resonator has started and stabilized.

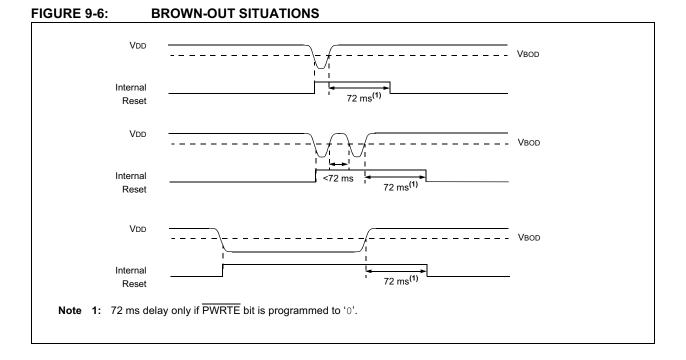
The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset or wake-up from Sleep.

9.3.5 BROWN-OUT DETECT (BOD)

The PIC16F630/676 members have on-chip Brown-out Detect circuitry. A Configuration bit, BODEN, can disable (if clear/programmed) or enable (if set) the Brown-out Detect circuitry. If VDD falls below VBOD for greater than parameter (TBOD) in Table 12-4 (see **Section 12.0 "Electrical Specifications"**), the Brown-out situation will reset the device. This will occur regardless of VDD slew-rate. A Reset is not guaranteed to occur if VDD falls below VBOD for less than parameter (TBOD). On any Reset (Power-on, Brown-out Detect, Watchdog, etc.), the chip will remain in Reset until VDD rises above BVDD (see Figure 9-6). The Power-up Timer will now be invoked, if enabled, and will keep the chip in Reset an additional 72 ms.

Note: A Brown-out Detect does not enable the Power-up Timer if the PWRTE bit in the Configuration Word is set.

If VDD drops below BVDD while the Power-up Timer is running, the chip will go back into a Brown-out Detect and the Power-up Timer will be re-initialized. Once VDD rises above BVDD, the Power-up Timer will execute a 72 ms Reset.



9.3.6 TIME-OUT SEQUENCE

On power-up, the time-out sequence is as follows: first, PWRT time-out is invoked after POR has expired. Then, OST is activated. The total time-out will vary based on oscillator configuration and <u>PWRTE</u> bit status. For example, in EC mode with <u>PWRTE</u> bit erased (PWRT disabled), there will be no time-out at all. Figure 9-7, Figure 9-8 and Figure 9-9 depict time-out sequences.

Since the time-outs occur from the POR pulse, if $\overline{\text{MCLR}}$ is kept low long enough, the time-outs will expire. Then bringing $\overline{\text{MCLR}}$ high will begin execution immediately (see Figure 9-8). This is useful for testing purposes or to synchronize more than one PIC16F630/676 device operating in parallel.

Table 9-6 shows the Reset conditions for some special registers, while Table 9-7 shows the Reset conditions for all the registers.

9.3.7 POWER CONTROL (PCON) STATUS REGISTER

The power CONTROL/STATUS register, PCON (address 8Eh) has two bits.

Bit 0 is \overline{BOD} (Brown-out). \overline{BOD} is unknown on Poweron Reset. It must then be set by the user and checked on subsequent Resets to see if $\overline{BOD} = 0$, indicating that a brown-out has occurred. The \overline{BOD} Status bit is a "don't care" and is not necessarily predictable if the brown-out circuit is disabled (by setting \overline{BODEN} bit = 0 in the Configuration Word).

Bit 1 is POR (Power-on Reset). It is a '0' on Power-on Reset and unaffected otherwise. The user must write a '1' to this bit following a Power-on Reset. On a subsequent Reset, if POR is '0', it will indicate that a Power-on Reset must have occurred (i.e., VDD may have gone too low).

Oscillator Configuration	Powe	er-up	Brown-o	Wake-up		
	PWRTE = 0	PWRTE = 1	PWRTE = 0	PWRTE = 1	from Sleep	
XT, HS, LP	Tpwrt + 1024•Tosc	1024•Tosc	Tpwrt + 1024•Tosc	1024•Tosc	1024•Tosc	
RC, EC, INTOSC	TPWRT	—	TPWRT	—	_	

TABLE 9-3: TIME-OUT IN VARIOUS SITUATIONS

TABLE 9-4: STATUS/PCON BITS AND THEIR SIGNIFICANCE

POR	BOD	то	PD	
0	u	1	1	Power-on Reset
1	0	1	1	Brown-out Detect
u	u	0	u	WDT Reset
u	u	0	0	WDT Wake-up
u	u	u	u	MCLR Reset during normal operation
u	u	1	0	MCLR Reset during Sleep

Legend: u = unchanged, x = unknown

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOD	Value on all other Resets ⁽¹⁾
03h	STATUS	IRP	RP1	RPO	TO	PD	Z	DC	С	0001 1xxx	000q quuu
8Eh	PCON	_	_	_	_	_	_	POR	BOD	0x	uq

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as '0', q = value depends on condition.
 Note 1: Other (non Power-up) Resets include MCLR Reset, Brown-out Detect and Watchdog Timer Reset during normal operation.

TABLE 9-6: INITIALIZATION CONDITION FOR SPECIAL REGISTERS

Condition	Program Counter	STATUS Register	PCON Register
Power-on Reset	000h	0001 1xxx	0x
MCLR Reset during normal operation	000h	000u uuuu	uu
MCLR Reset during Sleep	000h	0001 Ouuu	uu
WDT Reset	000h	0000 uuuu	uu
WDT Wake-up	PC + 1	սսս0 Օսսս	uu
Brown-out Detect	000h	0001 luuu	10
Interrupt Wake-up from Sleep	PC + 1 ⁽¹⁾	uuul Ouuu	uu

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as '0'.

Note 1: When the wake-up is due to an interrupt and global enable bit GIE is set, the PC is loaded with the interrupt vector (0004h) after execution of PC + 1.

TABLE 9-7:	INITIALIZ	ATION CONDIT	ION FOR REGIS	TERS	
Register	Address	Power-on Reset	 MCLR Reset WDT Reset Brown-out Det 	tect ⁽¹⁾	 Wake-up from Sleep through interrupt Wake-up from Sleep through WDT time-out
W		XXXX XXXX	นนนน เ	นนนน	นนนน นนนน
INDF	00h/80h	—	_	-	_
TMR0	01h	XXXX XXXX	นนนน เ	uuuu	սսսս սսսս
PCL	02h/82h	0000 0000	0000 0	0000	PC + 1 ⁽³⁾
STATUS	03h/83h	0001 1xxx	000q c	quuu (4)	uuuq quuu (4)
FSR	04h/84h	XXXX XXXX	นนนน เ	սսսս	սսսս սսսս
PORTA	05h	xx xxxx	uu u	นนนน	uu uuuu
PORTC	07h	xx xxxx	uu ı	นนนน	uu uuuu
PCLATH	0Ah/8Ah	0 0000	0 (0000	u uuuu
INTCON	0Bh/8Bh	0000 0000	0000 0	000u	uuuu uuqq ⁽²⁾
PIR1	0Ch	00 00	00 0	00	qq qq (2,5)
T1CON	10h	-000 0000	-uuu ı	นนนน	-uuu uuuu
CMCON	19h	-0-0 0000	-0-0 (0000	-u-u uuuu
ADRESH	1Eh	XXXX XXXX	นนนน เ	นนนน	սսսս սսսս
ADCON0	1Fh	00-0 0000	00-0 (0000	uu-u uuuu
OPTION_REG	81h	1111 1111	1111 1	1111	սսսս սսսս
TRISA	85h	11 1111	11 1	1111	uu uuuu
TRISC	87h	11 1111	11 1	1111	uu uuuu
PIE1	8Ch	00 00	00 0	00	uu uu
PCON	8Eh	0x		(1,6)	
OSCCAL	90h	1000 00	1000 0	00	uuuu uu
ANSEL	91h	1111 1111	1111 1	1111	սսսս սսսս
WPUA	95h	11 -111	11 -	-111	սսսս սսսս
IOCA	96h	00 0000	00 0	0000	uu uuuu
VRCON	99h	0-0- 0000	0-0- 0	0000	u-u- uuuu
EEDATA	9Ah	0000 0000	0000 0	0000	սսսս սսսս
EEADR	9Bh	-000 0000	-000 0	0000	-uuu uuuu
EECON1	9Ch	x000	c	q000	uuuu
EECON2	9Dh				
ADRESL	9Eh	XXXX XXXX	นนนน เ	uuuu	นนนน นนนน
ADCON1	9Fh	-000	-000 -		-uuu

TABLE 9-7: INITIALIZATION CONDITION FOR REGISTERS

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as '0', q = value depends on condition.

- Note 1: If VDD goes too low, Power-on Reset will be activated and registers will be affected differently.
 2: One or more bits in INTCON and/or PIR1 will be affected (to cause wake-up).
 - 3: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).
 - 4: See Table 9-6 for Reset value for specific condition.
 - 5: If wake-up was due to data EEPROM write completing, bit 7 = 1; A/D conversion completing, bit 6 = 1; Comparator input changing, bit 3 = 1; or Timer1 rolling over, bit 0 = 1. All other interrupts generating a wake-up will cause these bits to = u.
 - **6:** If Reset was due to brown-out, then bit 0 = 0. All other Resets will cause bit 0 = u.

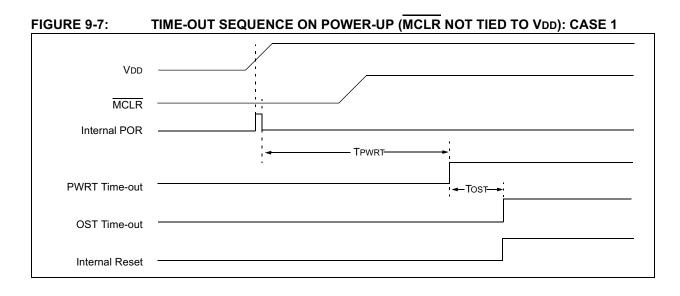


FIGURE 9-8: TIME-OUT SEQUENCE ON POWER-UP (MCLR NOT TIED TO VDD): CASE 2

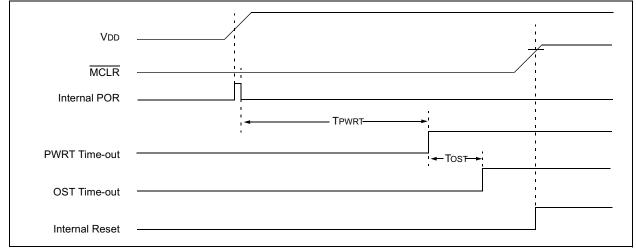
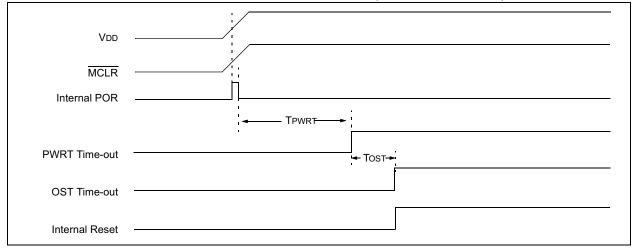


FIGURE 9-9: TIME-OUT SEQUENCE ON POWER-UP (MCLR TIED TO VDD)



9.4 Interrupts

The PIC16F630/676 has 7 sources of interrupt:

- External Interrupt RA2/INT
- TMR0 Overflow Interrupt
- PORTA Change Interrupts
- Comparator Interrupt
- A/D Interrupt (PIC16F676 only)
- TMR1 Overflow Interrupt
- EEPROM Data Write Interrupt

The Interrupt Control register (INTCON) and Peripheral Interrupt register (PIR) record individual interrupt requests in flag bits. The INTCON register also has individual and Global Interrupt Enable bits.

A Global Interrupt Enable bit, GIE (INTCON<7>) enables (if set) all unmasked interrupts, or disables (if cleared) all interrupts. Individual interrupts can be disabled through their corresponding enable bits in INTCON register and PIE register. GIE is cleared on Reset.

The return from interrupt instruction, RETFIE, exits interrupt routine, as well as sets the GIE bit, which reenables unmasked interrupts.

The following interrupt flags are contained in the INTCON register:

- INT pin interrupt
- · PORTA change interrupt
- TMR0 overflow interrupt

The peripheral interrupt flags are contained in the special register PIR1. The corresponding interrupt enable bit is contained in Special Register PIE1.

The following interrupt flags are contained in the PIR register:

- EEPROM data write interrupt
- A/D interrupt
- · Comparator interrupt
- Timer1 overflow interrupt
- When an interrupt is serviced:
- The GIE is cleared to disable any further interrupt
- The return address is pushed onto the stack
- The PC is loaded with 0004h

Once in the Interrupt Service Routine, the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid RA2/INT recursive interrupts.

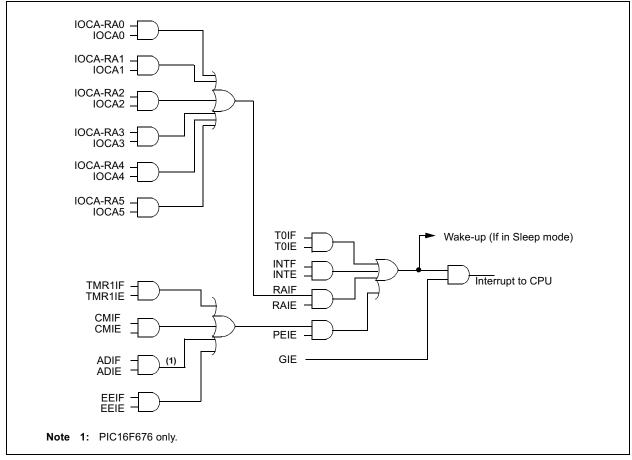
For external interrupt events, such as the INT pin, or PORTA change interrupt, the interrupt latency will be three or four instruction cycles. The exact latency depends upon when the interrupt event occurs (see Figure 9-11). The latency is the same for one or twocycle instructions. Once in the Interrupt Service Routine, the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid multiple interrupt requests.

Note 1: Individual interrupt flag bits are set, regardless of the status of their corresponding mask bit or the GIE bit.

2: When an instruction that clears the GIE bit is executed, any interrupts that were pending for execution in the next cycle are ignored. The interrupts which were ignored are still pending to be serviced when the GIE bit is set again.

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FIGURE 9-10: INTERRUPT LOGIC



9.4.1 **RA2/INT INTERRUPT**

External interrupt on RA2/INT pin is edge-triggered; either rising if INTEDG bit (OPTION<6>) is set, or falling, if INTEDG bit is clear. When a valid edge appears on the RA2/INT pin, the INTF bit (INTCON<1>) is set. This interrupt can be disabled by clearing the INTE control bit (INTCON<4>). The INTF bit must be cleared in software in the Interrupt Service Routine before re-enabling this interrupt. The RA2/INT interrupt can wake-up the processor from Sleep if the INTE bit was set prior to going into Sleep. The status of the GIE bit decides whether or not the processor branches to the interrupt vector following wake-up. See Section 9.7 "Power-Down Mode (Sleep)" for details on Sleep and Figure 9-13 for timing of wake-up from Sleep through RA2/INT interrupt.

Note: The ANSEL (91h) and CMCON (19h) registers must be initialized to configure an analog channel as a digital input. Pins configured as analog inputs will read '0'. The ANSEL register is defined for the PIC16F676.

9.4.2 TMR0 INTERRUPT

An overflow (FFh \rightarrow 00h) in the TMR0 register will set the T0IF (INTCON<2>) bit. The interrupt can be enabled/disabled by setting/clearing T0IE (INTCON<5>) bit. For operation of the Timer0 module, see Section 4.0 "Timer0 Module".

9.4.3 PORTA INTERRUPT

An input change on PORTA change sets the RAIF (INTCON<0>) bit. The interrupt can be enabled/ disabled by setting/clearing the RAIE (INTCON<3>) bit. Plus individual pins can be configured through the IOCA register.

Note:	If a change on the I/O pin should occur
	when the read operation is being executed
	(start of the Q2 cycle), then the RAIF inter-
	rupt flag may not get set.

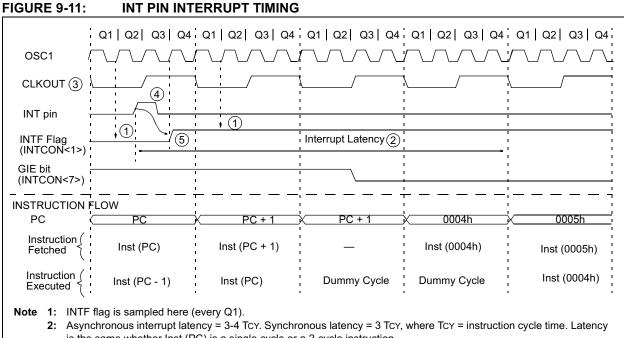
9.4.4 COMPARATOR INTERRUPT

See Section 6.9 "Comparator Interrupts" for description of comparator interrupt.

9.4.5 A/D CONVERTER INTERRUPT

After a conversion is complete, the ADIF flag (PIR<6>) is set. The interrupt can be enabled/disabled by setting or clearing ADIE (PIE<6>).

See Section 7.0 "Analog-to-Digital Converter (A/D) Module (PIC16F676 only)" for operation of the A/D converter interrupt.



is the same whether Inst (PC) is a single cycle or a 2-cycle instruction.

3: CLKOUT is available only in RC Oscillator mode.

4: For minimum width of INT pulse, refer to AC specs.

INTF is enabled to be set any time during the Q4-Q1 cycles.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOD	Value on all other Resets
0Bh, 8Bh	INTCON	GIE	PEIE	T0IE	INTE	RAIE	T0IF	INTF	RAIF	0000 0000	0000 000u
0Ch	PIR1	EEIF	ADIF	_	_	CMIF	_	_	TMR1IF	00 00	00 00
8Ch	PIE1	EEIE	ADIE	_	_	CMIE	_	_	TMR1IE	00 00	00 00

TABLE 9-8: SUMMARY OF INTERRUPT REGISTERS

Legend: x = unknown, u = unchanged, - = unimplemented read as '0', q = value depends upon condition. Shaded cells are not used by the Interrupt module.

9.5 Context Saving During Interrupts

During an interrupt, only the return PC value is saved on the stack. Typically, users may wish to save key registers during an interrupt (e.g., W register and STATUS register). This must be implemented in software.

Example 9-2 stores and restores the STATUS and W registers. The user register, W_TEMP, must be defined in both banks and must be defined at the same offset from the bank base address (i.e., W_TEMP is defined at 0x20 in Bank 0 and it must also be defined at 0xA0 in Bank 1). The user register, STATUS_TEMP, must be defined in Bank 0. The Example 9-2:

- Stores the W register
- Stores the STATUS register in Bank 0
- · Executes the ISR code
- Restores the Status (and bank select bit register)
- · Restores the W register

EXAMPLE 9-2: SAVING THE STATUS AND W REGISTERS IN RAM

MOVWF	W_TEMP	;copy W to temp register, could be in either bank
SWAPF	STATUS,W	;swap status to be saved into W
BCF	STATUS, RPO	;change to bank 0 regardless of current bank
MOVWF	STATUS TEMP	;save status to bank 0 register
:		
: (ISR)	
:		
SWAPF	STATUS_TEMP,	W;swap STATUS_TEMP register into
		W, sets bank to original state
MOVWF	STATUS	;move W into STATUS register
SWAPF	W_TEMP,F	;swap W_TEMP
SWAPF	W_TEMP,W	;swap W_TEMP into W

9.6 Watchdog Timer (WDT)

The Watchdog Timer is a free running, on-chip RC oscillator, which requires no external components. This RC oscillator is separate from the external RC oscillator of the CLKIN pin. That means that the WDT will run, even if the clock on the OSC1 and OSC2 pins of the device has been stopped (for example, by execution of a SLEEP instruction). During normal operation, a WDT time-out generates a device Reset. If the device is in Sleep mode, a WDT time-out causes the device to wake-up and continue with normal operation. The WDT can be permanently disabled by programming the Configuration bit WDTE as clear (Section 9.1 "Configuration Bits").

9.6.1 WDT PERIOD

The WDT has a nominal time-out period of 18 ms, (with no prescaler). The time-out periods vary with temperature, VDD and process variations from part to part (see DC specs). If longer time-out periods are desired, a prescaler with a division ratio of up to 1:128 can be assigned to the WDT under software control by writing to the OPTION register. Thus, time-out periods up to 2.3 seconds can be realized.

The CLRWDT and SLEEP instructions clear the WDT and the prescaler, if assigned to the WDT, and prevent it from timing out and generating a device Reset.

The $\overline{\text{TO}}$ bit in the STATUS register will be cleared upon a Watchdog Timer time-out.

9.6.2 WDT PROGRAMMING CONSIDERATIONS

It should also be taken in account that under worstcase conditions (i.e., VDD = Min., Temperature = Max., Max. WDT prescaler) it may take several seconds before a WDT time-out occurs.



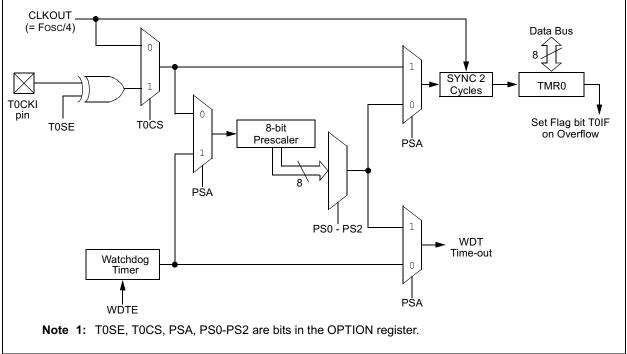


TABLE 9-9: SUMMARY OF WATCHDOG TIMER REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOD	Value on all other Resets
81h	OPTION_REG	RAPU	INTEDG	TOCS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
2007h	Config. bits	CP	BODEN	MCLRE	PWRTE	WDTE	F0SC2	F0SC1	F0SC0	uuuu uuuu	uuuu uuuu

Legend: u = Unchanged, shaded cells are not used by the Watchdog Timer.

9.7 Power-Down Mode (Sleep)

The Power-down mode is entered by executing a SLEEP instruction.

If the Watchdog Timer is enabled:

- · WDT will be cleared but keeps running
- PD bit in the STATUS register is cleared
- TO bit is set
- Oscillator driver is turned off
- I/O ports maintain the status they had before SLEEP was executed (driving high, low, or high-impedance).

For lowest current consumption in this mode, all I/O pins should be either at VDD, or VSS, with no external circuitry drawing current from the I/O pin and the comparators and CVREF should be disabled. I/O pins that are high-impedance inputs should be pulled high or low externally to avoid switching currents caused by floating inputs. The TOCKI input should also be at VDD or VSS for lowest current consumption. The contribution from on-chip pull-ups on PORTA should be considered.

The MCLR pin must be at a logic high level (VIHMC).

Note:	It should be noted that a Reset generated
	by a WDT time-out does not drive MCLR
	pin low.

9.7.1 WAKE-UP FROM SLEEP

The device can wake-up from Sleep through one of the following events:

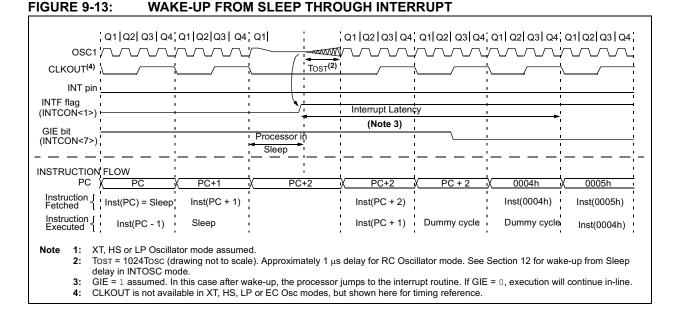
- 1. External Reset input on MCLR pin
- 2. Watchdog Timer Wake-up (if WDT was enabled)
- 3. Interrupt from RA2/INT pin, PORTA change, or a peripheral interrupt.

The first event will cause a device Reset. The two latter events are considered a continuation of program execution. The \overline{TO} and \overline{PD} bits in the STATUS register can be used to determine the cause of device Reset. The \overline{PD} bit, which is set on power-up, is cleared when Sleep is invoked. \overline{TO} bit is cleared if WDT Wake-up occurred.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction after the SLEEP instruction of the instruction of the instruction following SLEEP is not desirable, the user should have an NOP after the SLEEP instruction.

Note:	If the global interrupts are disabled (GIE is
	cleared), but any interrupt source has both
	its interrupt enable bit and the correspond-
	ing interrupt flag bits set, the device will
	immediately wake-up from Sleep. The
	SLEEP instruction is completely executed.

The WDT is cleared when the device wakes up from Sleep, regardless of the source of wake-up.



9.8 Code Protection

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out for verification purposes.

Note: The entire data EEPROM and Flash program memory will be erased when the code protection is turned off. The INTOSC calibration data is also erased. See PIC16F630/676 Programming Specification for more information.

9.9 ID Locations

Four memory locations (2000h-2003h) are designated as ID locations where the user can store checksum or other code identification numbers. These locations are not accessible during normal execution but are readable and writable during Program/Verify. Only the Least Significant 7 bits of the ID locations are used.

9.10 In-Circuit Serial Programming

The PIC16F630/676 microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data, and three other lines for:

- power
- ground
- programming voltage

This allows customers to manufacture boards with unprogrammed devices and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

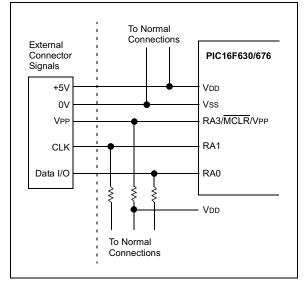
The device is placed into a Program/Verify mode by holding the RA0 and RA1 pins low, while raising the MCLR (VPP) pin from VIL to VIHH (see Programming Specification). RA0 becomes the programming data and RA1 becomes the programming clock. Both RA0 and RA1 are Schmitt Trigger inputs in this mode.

After Reset, to place the device into Programming/Verify mode, the program counter (PC) is at location 00h. A 6-bit command is then supplied to the device. Depending on the command, 14 bits of program data are then supplied to or from the device, depending on whether the command was a load or a read. For complete details of serial programming, please refer to the PIC16F630/676 Programming Specification.

A typical In-Circuit Serial Programming connection is shown in Figure 9-14.

FIGURE 9-14:

TYPICAL IN-CIRCUIT SERIAL PROGRAMMING CONNECTION



9.11 In-Circuit Debugger

Since in-circuit debugging requires the loss of clock, data and MCLR pins, MPLAB[®] ICD 2 development with an 14-pin device is not practical. A special 20-pin PIC16F676-ICD device is used with MPLAB ICD 2 to provide separate clock, data and MCLR pins and frees all normally available pins to the user.

This special ICD device is mounted on the top of the header and its signals are routed to the MPLAB ICD 2 connector. On the bottom of the header is an 14-pin socket that plugs into the user's target via the 14-pin stand-off connector.

When the ICD pin on the PIC16F676-ICD device is held low, the In-Circuit Debugger functionality is enabled. This function allows simple debugging functions when used with MPLAB ICD 2. When the microcontroller has this feature enabled, some of the resources are not available for general use. Table 9-10 shows which features are consumed by the background debugger:

TABLE 9-10: DEBUGGER RESOURCES

I/O pins	ICDCLK, ICDDATA
Stack	1 level
Program Memory	Address 0h must be NOP 300h-3FEh

For more information, see 14-Pin MPLAB ICD 2 Header Information Sheet (DS51292) available on Microchip's web site (www.microchip.com).

NOTES:

10.0 INSTRUCTION SET SUMMARY

The PIC16F630/676 instruction set is highly orthogonal and is comprised of three basic categories:

- Byte-oriented operations
- Bit-oriented operations
- Literal and control operations

Each PIC16 instruction is a 14-bit word divided into an **opcode**, which specifies the instruction type, and one or more **operands**, which further specify the operation of the instruction. The formats for each of the categories is presented in Figure 10-1, while the various opcode fields are summarized in Table 10-1.

Table 10-2 lists the instructions recognized by the MPASMTM assembler. A complete description of each instruction is also available in the PIC[®] Mid-Range Reference Manual (DS33023).

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator specifies which file register is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is zero, the result is placed in the W register. If 'd' is one, the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator, which selects the bit affected by the operation, while 'f' represents the address of the file in which the bit is located.

For **literal and control** operations, **'k**' represents an 8-bit or 11-bit constant, or literal value

One instruction cycle consists of four oscillator periods; for an oscillator frequency of 4 MHz, this gives a normal instruction execution time of 1 μ s. All instructions are executed within a single instruction cycle, unless a conditional test is true, or the program counter is changed as a result of an instruction. When this occurs, the execution takes two instruction cycles, with the second cycle executed as a NOP.

Note:	To maintain upward compatibility with
	future products, do not use the OPTION
	and TRIS instructions.

All instruction examples use the format '0xhh' to represent a hexadecimal number, where 'h' signifies a hexadecimal digit.

10.1 READ-MODIFY-WRITE OPERATIONS

Any instruction that specifies a file register as part of the instruction performs a Read-Modify-Write (R-M-W) operation. The register is read, the data is modified, and the result is stored according to either the instruction, or the destination designator 'd'. A read operation is performed on a register even if the instruction writes to that register. For example, a CLRF PORTA instruction will read PORTA, clear all the data bits, then write the result back to PORTA. This example would have the unintended result of clearing the condition that set the RAIF flag.

TABLE 10-1: OPCODE FIELD DESCRIPTIONS

Field	Description
f	Register file address (0x00 to 0x7F)
W	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
x	Don't care location (= 0 or 1). The assembler will generate code with x = 0. It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select; $d = 0$: store result in W, d = 1: store result in file register f. Default is $d = 1$.
PC	Program Counter
то	Time-out bit
PD	Power-down bit

FIGURE 10-1: GENERAL FORMAT FOR INSTRUCTIONS

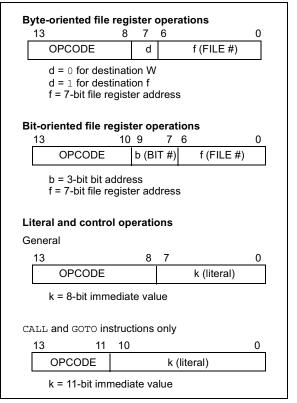


TABLE 10-2: PIC16F630/676 INSTRUCTION SET

Mnemonic, Operands		Description	Description Cycles 14-Bit Opcode		•	Status	N		
		Description	Cycles	MSb			LSb	Affected	Notes
BYTE-ORIENTED FILE REGISTER OPERATIONS									
ADDWF	f, d	Add W and f	1	00	0111	dfff	ffff	C,DC,Z	1,2
ANDWF	f, d	AND W with f	1	00	0101	dfff	ffff	Z	1,2
CLRF	f	Clear f	1	00	0001	lfff	ffff	Z	2
CLRW	-	Clear W	1	00	0001	0xxx	XXXX	Z	
COMF	f, d	Complement f	1	00	1001	dfff	ffff	Z	1,2
DECF	f, d	Decrement f	1	00	0011	dfff	ffff	Z	1,2
DECFSZ	f, d	Decrement f, Skip if 0	1(2)	00	1011	dfff	ffff		1,2,3
INCF	f, d	Increment f	1	00	1010	dfff	ffff	Z	1,2
INCFSZ	f, d	Increment f, Skip if 0	1(2)	00	1111	dfff	ffff		1,2,3
IORWF	f, d	Inclusive OR W with f	1	00	0100	dfff	ffff	Z	1,2
MOVF	f, d	Move f	1	00	1000	dfff	ffff	Z	1,2
MOVWF	f	Move W to f	1	00	0000	lfff	ffff		
NOP	-	No Operation	1	00	0000	0xx0	0000		
RLF	f, d	Rotate Left f through Carry	1	00	1101	dfff	ffff	С	1,2
RRF	f, d	Rotate Right f through Carry	1	00	1100	dfff	ffff	С	1,2
SUBWF	f, d	Subtract W from f	1	00	0010	dfff	ffff	C,DC,Z	1,2
SWAPF	f, d	Swap nibbles in f	1	00	1110	dfff	ffff		1,2
XORWF	f, d	Exclusive OR W with f	1	00	0110	dfff	ffff	Z	1,2
		BIT-ORIENTED FILE		RATIO	١S				
BCF	f, b	Bit Clear f	1	01	00bb	bfff	ffff		1,2
BSF	f, b	Bit Set f	1	01	01bb	bfff	ffff		1,2
BTFSC	f, b	Bit Test f, Skip if Clear	1 (2)	01	10bb	bfff	ffff		3
BTFSS	f, b	Bit Test f, Skip if Set	1 (2)	01	11bb	bfff	ffff		3
		LITERAL AND CO	NTROL OPERAT	IONS					
ADDLW	k	Add literal and W	1	11	111x	kkkk	kkkk	C,DC,Z	
ANDLW	k	AND literal with W	1	11	1001	kkkk	kkkk	Z	
CALL	k	Call subroutine	2	10	0 k k k	kkkk	kkkk		
CLRWDT	-	Clear Watchdog Timer	1	00	0000	0110	0100	TO,PD	
GOTO	k	Go to address	2	10	1kkk	kkkk	kkkk		
IORLW	k	Inclusive OR literal with W	1	11	1000	kkkk	kkkk	Z	
MOVLW	k	Move literal to W	1	11	00xx	kkkk	kkkk		
RETFIE	-	Return from interrupt	2	00	0000	0000	1001		
	k	Return with literal in W	2	11	01xx	kkkk	kkkk		
RETLW	-	Return from Subroutine	2	00	0000	0000	1000		
RETLW RETURN	-					0110	0011		
	-	Go into Standby mode	1	00	0000	0110	0011	TO,PD	
RETURN		Go into Standby mode Subtract W from literal	1	00 11	0000 110x	kkkk		C,DC,Z	

Note 1: When an I/O register is modified as a function of itself (e.g., MOVF PORTA, 1), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

2: If this instruction is executed on the TMR0 register (and, where applicable, d = 1), the prescaler will be cleared if assigned to the Timer0 module.

3: If Program Counter (PC) is modified, or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

Note: Additional information on the mid-range instruction set is available in the PIC[®] Mid-Range MCU Family Reference Manual (DS33023).

f,b

10.2 Instruction Descriptions

ADDLW	Add Literal and W
Syntax:	[<i>label</i>] ADDLW k
Operands:	$0 \le k \le 255$
Operation:	$(W) + k \to (W)$
Status Affected:	C, DC, Z
Description:	The contents of the W register are added to the eight-bit literal 'k and the result is placed in the W register.

	BSF	Bit Set f
is placed in the W	·	-
of the W register ne eight-bit literal 'k'	Status Affected: Description:	None Bit 'b' in register 'f' is cleared.
)	Operation:	$0 \rightarrow (f \le b >)$

BCF

Syntax:

Operands:

ADDWF	Add W and f
Syntax:	[<i>label</i>] ADDWF f,d
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$
Operation:	(W) + (f) \rightarrow (destination)
Status Affected:	C, DC, Z
Description:	Add the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

BSF	Bit Set f
Syntax:	[<i>label</i>] BSF f,b
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ 0 \leq b \leq 7 \end{array}$
Operation:	$1 \rightarrow (f \le b >)$
Status Affected:	None
Description:	Bit 'b' in register 'f' is set.

Bit Clear f

[*label*] BCF

 $0 \leq f \leq 127$

 $0 \le b \le 7$

ANDLW	AND Literal with W
Syntax:	[<i>label</i>] ANDLW k
Operands:	$0 \leq k \leq 255$
Operation:	(W) .AND. (k) \rightarrow (W)
Status Affected:	Z
Description:	The contents of W register are AND'ed with the eight-bit literal 'k'. The result is placed in the W register.

BTFSS	Bit Test f, Skip if Set
Syntax:	[<i>label</i>] BTFSS f,b
Operands:	$0 \le f \le 127$ $0 \le b < 7$
Operation:	skip if (f) = 1
Status Affected:	None
Description:	If bit 'b' in register 'f' is '0', the next instruction is executed. If bit 'b' is '1', then the next instruc- tion is discarded and a NOP is executed instead, making this a 2-cycle instruction.

ANDWF	AND W with f
Syntax:	[<i>label</i>] ANDWF f,d
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$
Operation:	(W) .AND. (f) \rightarrow (destination)
Status Affected:	Z
Description:	AND the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

BTFSC	Bit Test, Skip if Clear
Syntax:	[/abe/] BTFSC f,b
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ 0 \leq b \leq 7 \end{array}$
Operation:	skip if (f) = 0
Status Affected:	None
Description:	If bit 'b' in register 'f' is '1', the next instruction is executed. If bit 'b', in register 'f', is '0', the next instruction is discarded, and a NOP is executed instead, making this a 2-cycle instruction.

CALL	Call Subroutine
Syntax:	[<i>label</i>] CALL k
Operands:	$0 \leq k \leq 2047$
Operation:	(PC)+ 1 \rightarrow TOS, k \rightarrow PC<10:0>, (PCLATH<4:3>) \rightarrow PC<12:11>
Status Affected:	None
Description:	Call Subroutine. First, return address (PC + 1) is pushed onto the stack. The eleven-bit immedi- ate address is loaded into PC bits <10:0>. The upper bits of the PC are loaded from PCLATH. CALL is a two-cycle instruction.

CLRWDT	Clear Watchdog Timer
Syntax:	[label] CLRWDT
Operands:	None
Operation:	$00h \rightarrow WDT$ $0 \rightarrow WDT \text{ prescaler,}$ $1 \rightarrow TO$ $1 \rightarrow PD$
Status Affected:	TO, PD
Description:	CLRWDT instruction resets the Watchdog Timer. It also resets the prescaler of the WDT. Status bits TO and PD are set.

CLRF	Clear f
Syntax:	[<i>label</i>] CLRF f
Operands:	$0 \leq f \leq 127$
Operation:	$\begin{array}{l} 00h \rightarrow (f) \\ 1 \rightarrow Z \end{array}$
Status Affected:	Z
Description:	The contents of register 'f' are cleared and the Z bit is set.

COMF	Complement f
Syntax:	[<i>label</i>] COMF f,d
Operands:	$\begin{array}{l} 0\leq f\leq 127\\ d\in [0,1] \end{array}$
Operation:	$(\overline{f}) \rightarrow (destination)$
Status Affected:	Z
Description:	The contents of register 'f' are complemented. If 'd' is 0, the result is stored in W. If 'd' is 1, the result is stored back in register 'f'.

CLRW	Clear W
Syntax:	[label] CLRW
Operands:	None
Operation:	$\begin{array}{l} 00h \rightarrow (W) \\ 1 \rightarrow Z \end{array}$
Status Affected:	Z
Description:	W register is cleared. Zero bit (Z) is set.

DECF	Decrement f
Syntax:	[/abe/] DECF f,d
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$
Operation:	(f) - 1 \rightarrow (destination)
Status Affected:	Z
Description:	Decrement register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

DECFSZ	Decrement f, Skip if 0	
Syntax:	[label] DECFSZ f,d	
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$	
Operation:	(f) - 1 \rightarrow (destination); skip if result = 0	
Status Affected:	None	
Description:	The contents of register 'f' are decremented. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'. If the result is 1, the next instruction is executed. If the result is 0, then a NOP is executed instead, making it a 2-cycle instruction.	

INCFSZ	Increment f, Skip if 0		
Syntax:	[label] INCFSZ f,d		
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$		
Operation:	(f) + 1 \rightarrow (destination), skip if result = 0		
Status Affected:	None		
Description:	The contents of register 'f' are incremented. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'. If the result is 1, the next instruc- tion is executed. If the result is 0, a NOP is executed instead, making		

GOTO	Unconditional Branch
Syntax:	[<i>label</i>] GOTO k
Operands:	$0 \leq k \leq 2047$
Operation:	$k \rightarrow PC<10:0>$ PCLATH<4:3> \rightarrow PC<12:11>
Status Affected:	None
Description:	GOTO is an unconditional branch. The eleven-bit immediate value is loaded into PC bits <10:0>. The upper bits of PC are loaded from PCLATH<4:3>. GOTO is a two- cycle instruction.

IORLW	Inclusive OR Literal with W
Syntax:	[<i>label</i>] IORLW k
Operands:	$0 \leq k \leq 255$
Operation:	(W) .OR. $k \rightarrow$ (W)
Status Affected:	Z
Description:	The contents of the W register are OR'ed with the eight-bit literal 'k'. The result is placed in the W register.

INCF	Increment f	IORWF	Inclusive OR W with f
Syntax:	[<i>label</i>] INCF f,d	Syntax:	[<i>label</i>] IORWF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$	Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$
Operation:	(f) + 1 \rightarrow (destination)	Operation:	(W) .OR. (f) \rightarrow (destination)
Status Affected:	Z	Status Affected:	Z
Description:	The contents of register 'f' are incremented. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.	Description:	Inclusive OR the W register with register 'f'. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.

MOVF	Move f
Syntax:	[<i>label</i>] MOVF f,d
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$
Operation:	(f) \rightarrow (destination)
Status Affected:	Z
Description:	The contents of register f are moved to a destination dependant upon the status of d. If $d = 0$, destination is W register. If $d = 1$, the destination is file register f itself. d = 1 is useful to test a file register, since status flag Z is affected.

NOP	No Operation
Syntax:	[label] NOP
Operands:	None
Operation:	No operation
Status Affected:	None
Description:	No operation.

MOVLW	Move Literal to W
Syntax:	[<i>label</i>] MOVLW k
Operands:	$0 \leq k \leq 255$
Operation:	$k \rightarrow (W)$
Status Affected:	None
Description:	The eight-bit literal 'k' is loaded into W register. The don't cares will assemble as 0's.

RETFIE	Return from Interrupt
Syntax:	[label] RETFIE
Operands:	None
Operation:	$TOS \rightarrow PC$, 1 $\rightarrow GIE$
Status Affected:	None

MOVWF	Move W to f
Syntax:	[<i>label</i>] MOVWF f
Operands:	$0 \leq f \leq 127$
Operation:	$(W) \to (f)$
Status Affected:	None
Description:	Move data from W register to register 'f'.

RETLW	Return with Literal in W
Syntax:	[<i>label</i>] RETLW k
Operands:	$0 \leq k \leq 255$
Operation:	$k \rightarrow (W);$ TOS \rightarrow PC
Status Affected:	None
Description:	The W register is loaded with the eight-bit literal 'k'. The program counter is loaded from the top of the stack (the return address). This is a two-cycle instruction.

RLF	Rotate Left f through Carry
Syntax:	[<i>label</i>] RLF f,d
Operands:	$\begin{array}{l} 0\leq f\leq 127\\ d\in [0,1] \end{array}$
Operation:	See description below
Status Affected:	С
Description:	The contents of register 'f' are rotated one bit to the left through the Carry Flag. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is stored back in register 'f'.

SLEEP

Syntax:	[label] SLEEP
Operands:	None
Operation:	$\begin{array}{l} 00h \rightarrow WDT, \\ 0 \rightarrow WDT \text{ prescaler}, \\ 1 \rightarrow \overline{TO}, \\ 0 \rightarrow \overline{PD} \end{array}$
Status Affected:	TO, PD
Description:	The power-down Status bit, \overline{PD} is cleared. Time-out Status bit, \overline{TO} is set. Watchdog Timer and its prescaler are cleared. The processor is put into Sleep mode with the oscillator stopped.

RETURN	Return from Subroutine
Syntax:	[label] RETURN
Operands:	None
Operation:	$TOS \rightarrow PC$
Status Affected:	None
Description:	Return from subroutine. The stack is POPed and the top of the stack (TOS) is loaded into the program counter. This is a two-cycle instruction.

RRF	Rotate Right f through Carry
Syntax:	[<i>label</i>] RRF f,d
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$
Operation:	See description below
Status Affected:	С
Description:	The contents of register 'f' are rotated one bit to the right through the Carry Flag. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.

SUBLW	Subtract W from Literal
Syntax:	[<i>label</i>] SUBLW k
Operands:	$0 \leq k \leq 255$
Operation:	$k - (W) \to (W)$
Status Affected:	C, DC, Z
Description:	The W register is subtracted (2's complement method) from the eight-bit literal 'k'. The result is placed in the W register.

SUBWF	Subtract W from f
Syntax:	[<i>label</i>] SUBWF f,d
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$
Operation:	(f) - (W) \rightarrow (destination)
Status Affected:	C, DC, Z
Description:	Subtract (2's complement method) W register from register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

SWAPF	Swap Nibbles in f
Syntax:	[<i>label</i>] SWAPF f,d
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$
Operation:	$(f<3:0>) \rightarrow (destination<7:4>), (f<7:4>) \rightarrow (destination<3:0>)$
Status Affected:	None
Description:	The upper and lower nibbles of register 'f' are exchanged. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed in register 'f'.

XORWF	Exclusive OR W with f
Syntax:	[<i>label</i>] XORWF f,d
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$
Operation:	(W) .XOR. (f) \rightarrow (destination)
Status Affected:	Z
Description:	Exclusive OR the contents of the W register with register 'f'. If 'd' is 0, the result is stored in the W register. If 'd' is 1, the result is stored back in register 'f'.

XORLW	Exclusive OR Literal with W							
Syntax:	[<i>label</i>] XORLW k							
Operands:	$0 \leq k \leq 255$							
Operation:	(W) .XOR. $k \rightarrow (W)$							
Status Affected:	Z							
Description:	The contents of the W register are XOR'ed with the eight-bit literal 'k'. The result is placed in the W register.							

11.0 DEVELOPMENT SUPPORT

The PIC[®] microcontrollers and dsPIC[®] digital signal controllers are supported with a full range of software and hardware development tools:

- Integrated Development Environment
- MPLAB[®] IDE Software
- Compilers/Assemblers/Linkers
 - MPLAB C Compiler for Various Device Families
 - HI-TECH C for Various Device Families
 - MPASM[™] Assembler
 - MPLINK[™] Object Linker/ MPLIB[™] Object Librarian
 - MPLAB Assembler/Linker/Librarian for Various Device Families
- Simulators
 - MPLAB SIM Software Simulator
- Emulators
 - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers
 - MPLAB ICD 3
 - PICkit™ 3 Debug Express
- Device Programmers
 - PICkit[™] 2 Programmer
 - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits, and Starter Kits

11.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8/16/32-bit microcontroller market. The MPLAB IDE is a Windows[®] operating system-based application that contains:

- A single graphical interface to all debugging tools
 - Simulator
 - Programmer (sold separately)
 - In-Circuit Emulator (sold separately)
 - In-Circuit Debugger (sold separately)
- · A full-featured editor with color-coded context
- A multiple project manager
- Customizable data windows with direct edit of contents
- · High-level source code debugging
- · Mouse over variable inspection
- Drag and drop variables from source to watch windows
- · Extensive on-line help
- Integration of select third party tools, such as IAR C Compilers

The MPLAB IDE allows you to:

- Edit your source files (either C or assembly)
- One-touch compile or assemble, and download to emulator and simulator tools (automatically updates all project information)
- · Debug using:
 - Source files (C or assembly)
 - Mixed C and assembly
 - Machine code

MPLAB IDE supports multiple debugging tools in a single development paradigm, from the cost-effective simulators, through low-cost in-circuit debuggers, to full-featured emulators. This eliminates the learning curve when upgrading to tools with increased flexibility and power.

11.2 MPLAB C Compilers for Various Device Families

The MPLAB C Compiler code development systems are complete ANSI C compilers for Microchip's PIC18, PIC24 and PIC32 families of microcontrollers and the dsPIC30 and dsPIC33 families of digital signal controllers. These compilers provide powerful integration capabilities, superior code optimization and ease of use.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

11.3 HI-TECH C for Various Device Families

The HI-TECH C Compiler code development systems are complete ANSI C compilers for Microchip's PIC family of microcontrollers and the dsPIC family of digital signal controllers. These compilers provide powerful integration capabilities, omniscient code generation and ease of use.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

The compilers include a macro assembler, linker, preprocessor, and one-step driver, and can run on multiple platforms.

11.4 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel[®] standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code and COFF files for debugging.

The MPASM Assembler features include:

- · Integration into MPLAB IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multi-purpose source files
- Directives that allow complete control over the assembly process

11.5 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler and the MPLAB C18 C Compiler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

11.6 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC devices. MPLAB C Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- · Support for the entire device instruction set
- · Support for fixed-point and floating-point data
- Command line interface
- · Rich directive set
- Flexible macro language
- · MPLAB IDE compatibility

11.7 MPLAB SIM Software Simulator

The MPLAB SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC[®] DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB SIM Software Simulator fully supports symbolic debugging using the MPLAB C Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

11.8 MPLAB REAL ICE In-Circuit Emulator System

MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs PIC[®] Flash MCUs and dsPIC[®] Flash DSCs with the easy-to-use, powerful graphical user interface of the MPLAB Integrated Development Environment (IDE), included with each kit.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with incircuit debugger systems (RJ11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB IDE. In upcoming releases of MPLAB IDE, new devices will be supported, and new features will be added. MPLAB REAL ICE offers significant advantages over competitive emulators including low-cost, full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, a ruggedized probe interface and long (up to three meters) interconnection cables.

11.9 MPLAB ICD 3 In-Circuit Debugger System

MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost effective high-speed hardware debugger/programmer for Microchip Flash Digital Signal Controller (DSC) and microcontroller (MCU) devices. It debugs and programs PIC[®] Flash microcontrollers and dsPIC[®] DSCs with the powerful, yet easyto-use graphical user interface of MPLAB Integrated Development Environment (IDE).

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

11.10 PICkit 3 In-Circuit Debugger/ Programmer and PICkit 3 Debug Express

The MPLAB PICkit 3 allows debugging and programming of PIC[®] and dsPIC[®] Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB Integrated Development Environment (IDE). The MPLAB PICkit 3 is connected to the design engineer's PC using a full speed USB interface and can be connected to the target via an Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the reset line to implement in-circuit debugging and In-Circuit Serial Programming[™].

The PICkit 3 Debug Express include the PICkit 3, demo board and microcontroller, hookup cables and CDROM with user's guide, lessons, tutorial, compiler and MPLAB IDE software.

11.11 PICkit 2 Development Programmer/Debugger and PICkit 2 Debug Express

The PICkit[™] 2 Development Programmer/Debugger is a low-cost development tool with an easy to use interface for programming and debugging Microchip's Flash families of microcontrollers. The full featured Windows® programming interface supports baseline (PIC10F, PIC12F5xx, PIC16F5xx), midrange (PIC12F6xx, PIC16F), PIC18F, PIC24, dsPIC30, dsPIC33, and PIC32 families of 8-bit, 16-bit, and 32-bit microcontrollers, and many Microchip Serial EEPROM products. With Microchip's powerful MPLAB Integrated Development Environment (IDE) the PICkit[™] 2 enables in-circuit debugging on most PIC[®] microcontrollers. In-Circuit-Debugging runs, halts and single steps the program while the PIC microcontroller is embedded in the application. When halted at a breakpoint, the file registers can be examined and modified.

The PICkit 2 Debug Express include the PICkit 2, demo board and microcontroller, hookup cables and CDROM with user's guide, lessons, tutorial, compiler and MPLAB IDE software.

11.12 MPLAB PM3 Device Programmer

The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at VDDMIN and VDDMAX for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages and a modular, detachable socket assembly to support various package types. The ICSP™ cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PIC devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices and incorporates an MMC card for file storage and data applications.

11.13 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM[™] and dsPICDEM[™] demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ[®] security ICs, CAN, IrDA[®], PowerSmart battery management, SEEVAL[®] evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

12.0 ELECTRICAL SPECIFICATIONS

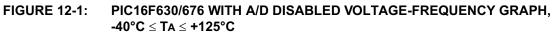
Absolute Maximum Ratings†

40 to +125°C
65°C to +150°C
0.3 to +6.5V
0.3 to +13.5V
0.3V to (VDD + 0.3V)
800 mW
300 mA
250 mA
± 20 mA
± 20 mA
25 mA
25 mA
200 mA
200 mA

Note 1: Power dissipation is calculated as follows: PDIS = VDD x {IDD - \sum IOH} + \sum {(VDD-VOH) x IOH} + \sum (VOI x IOL).

† NOTICE: Stresses above those listed under 'Absolute Maximum Ratings' may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Note: Voltage spikes below Vss at the \overline{MCLR} pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100 Ω should be used when applying a "low" level to the \overline{MCLR} pin, rather than pulling this pin directly to Vss.



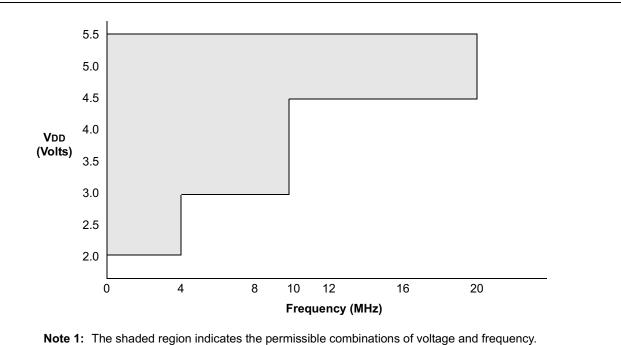


FIGURE 12-2: PIC16F676 WITH A/D ENABLED VOLTAGE-FREQUENCY GRAPH, $\textbf{-40^{\circ}C} \leq \textbf{TA} \leq \textbf{+125^{\circ}C}$

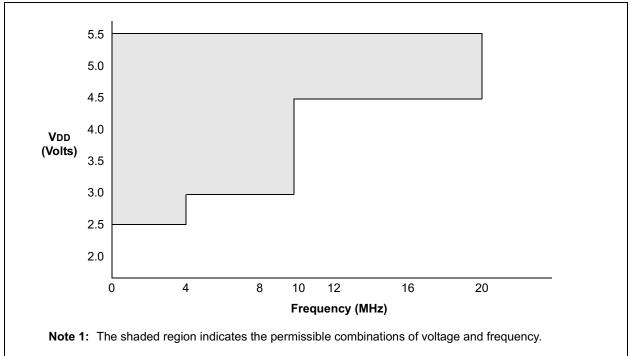
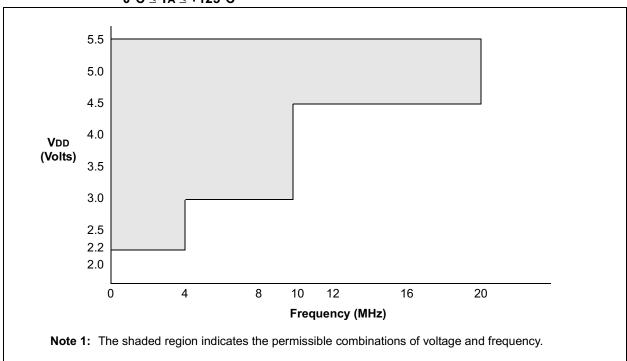


FIGURE 12-3: PIC16F676 WITH A/D ENABLED VOLTAGE-FREQUENCY GRAPH, 0°C \leq Ta \leq +125°C



12.1 DC Characteristics: PIC16F630/676-I (Industrial), PIC16F630/676-E (Extended)

DC CHARACTERISTICS				$\begin{array}{l} \mbox{Standard Operating Conditions (unless otherwise stated)} \\ \mbox{Operating temperature} & -40^{\circ}C \leq Ta \leq +85^{\circ}C \mbox{ for industrial} \\ & -40^{\circ}C \leq Ta \leq +125^{\circ}C \mbox{ for extended} \end{array}$							
Param No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions				
D001 D001A D001B D001C D001D D002	Vdd	Supply Voltage	2.0 2.2 2.5 3.0 4.5 1.5*		5.5 5.5 5.5 5.5 5.5 5.5	V V V V V	Fosc < = 4 MHz: PIC16F630/676 with A/D off PIC16F676 with A/D on, 0°C to +125°C PIC16F676 with A/D on, -40°C to +125°C 4 MHz < Fosc < = 10 MHz				
D002	VDR	Voltage ⁽¹⁾	1.5		_	v	Device in Sleep mode				
D003	VPOR	VDD Start Voltage to ensure internal Power-on Reset signal	—	Vss		V	See section on Power-on Reset for details				
D004	Svdd	VDD Rise Rate to ensure internal Power-on Reset signal	0.05*			V/ms	See section on Power-on Reset for details				
D005	VBOD		_	2.1	_	V					

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

			ard Ope ting tem	-		•	ess otherwise stated) +85°C for industrial
Param	Device Characteristics	Min	Тур†	Max	Units		Conditions
No.			.,,,,,	max	• · · · · ·	VDD	Note
D010	Supply Current (IDD)	-	9	16	μA	2.0	Fosc = 32 kHz
		—	18	28	μA	3.0	LP Oscillator Mode
		_	35	54	μA	5.0	
D011		_	110	150	μA	2.0	Fosc = 1 MHz
		_	190	280	μA	3.0	XT Oscillator Mode
		—	330	450	μA	5.0	
D012		—	220	280	μA	2.0	Fosc = 4 MHz
		_	370	650	μA	3.0	XT Oscillator Mode
		_	0.6	1.4	mA	5.0	
D013		—	70	110	μA	2.0	Fosc = 1 MHz
			140	250	μA	3.0	EC Oscillator Mode
		_	260	390	μA	5.0	
D014			180	250	μA	2.0	Fosc = 4 MHz
			320	470	μA	3.0	EC Oscillator Mode
		_	580	850	μA	5.0	
D015			340	450	μA	2.0	Fosc = 4 MHz
			500	780	μA	3.0	INTOSC Mode
			0.8	1.1	mA	5.0	
D016			180	250	μA	2.0	Fosc = 4 MHz
			320	450	μA	3.0	EXTRC Mode
			580	800	μA	5.0	
D017			2.1	2.95	mA	4.5	Fosc = 20 MHz
		_	2.4	3.0	mA	5.0	HS Oscillator Mode

12.2 DC Characteristics: PIC16F630/676-I (Industrial)

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The test conditions for all IDD measurements in Active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD; MCLR = VDD; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

		Standard Operating Conditions (unless otherwise stated)Operating temperature $-40^{\circ}C \le TA \le +85^{\circ}C$ for industrial									
Param	Device Characteristics	Min	Truck	Max	11		Conditions				
No.	Device Characteristics	Min	Тур†	Max	Units	VDD	Note				
D020	Power-down Base Current		0.99	700	nA	2.0	WDT, BOD, Comparators, VREF,				
	(IPD)		1.2	770	nA	3.0	and T1OSC disabled				
		_	2.9	995	nA	5.0					
D021		-	0.3	1.5	μA	2.0	WDT Current ⁽¹⁾				
			1.8	3.5	μA	3.0					
			8.4	17	μA	5.0					
D022			58	70	μA	3.0	BOD Current ⁽¹⁾				
			109	130	μA	5.0					
D023			3.3	6.5	μA	2.0	Comparator Current ⁽¹⁾				
		—	6.1	8.5	μA	3.0					
		—	11.5	16	μA	5.0					
D024			58	70	μA	2.0	CVREF Current ⁽¹⁾				
			85	100	μA	3.0					
			138	160	μA	5.0					
D025		_	4.0	6.5	μA	2.0	T1 Osc Current ⁽¹⁾				
			4.6	7.0	μA	3.0					
		—	6.0	10.5	μA	5.0					
D026		_	1.2	755	nA	3.0	A/D Current ⁽¹⁾				
			0.0022	1.0	μA	5.0					

12.3 DC Characteristics: PIC16F630/676-I (Industrial)

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The peripheral current is the sum of the base IDD or IPD and the additional current consumed when this peripheral is enabled. The peripheral ∆ current can be determined by subtracting the base IDD or IPD current from this limit. Max values should be used when calculating total current consumption.

2: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD.

			ard Ope ting tem	-		•	ss otherwise stated) +125°C for extended
Param	Device Characteristics	Min	Tunt	Мах	Units		Conditions
No.	Device Characteristics	Min	Тур†	wax	Units	VDD	Note
D010E	Supply Current (IDD)	-	9	16	μA	2.0	Fosc = 32 kHz
		—	18	28	μA	3.0	LP Oscillator Mode
		—	35	54	μA	5.0	
D011E		-	110	150	μA	2.0	Fosc = 1 MHz
		—	190	280	μA	3.0	XT Oscillator Mode
		—	330	450	μA	5.0	
D012E		-	220	280	μA	2.0	Fosc = 4 MHz
		—	370	650	μA	3.0	XT Oscillator Mode
		_	0.6	1.4	mA	5.0	
D013E		-	70	110	μA	2.0	Fosc = 1 MHz
		—	140	250	μA	3.0	EC Oscillator Mode
		—	260	390	μA	5.0	
D014E		—	180	250	μA	2.0	Fosc = 4 MHz
		—	320	470	μA	3.0	EC Oscillator Mode
		—	580	850	μA	5.0	
D015E		—	340	450	μA	2.0	Fosc = 4 MHz
		—	500	780	μA	3.0	INTOSC Mode
		—	0.8	1.1	mA	5.0	
D016E			180	250	μA	2.0	Fosc = 4 MHz
			320	450	μA	3.0	EXTRC Mode
		_	580	800	μA	5.0	
D017E			2.1	2.95	mA	4.5	Fosc = 20 MHz
			2.4	3.0	mA	5.0	HS Oscillator Mode

12.4 DC Characteristics: PIC16F630/676-E (Extended)

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The test conditions for all IDD measurements in Active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD; MCLR = VDD; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

12.5 DC Characteristics: PIC16F630/676-E (Extended)

			ard Opera ting tempe				otherwise stated) 125°C for extended
Param	Device Characteristics	Min	Typ†	Max	Units		Conditions
No.	Device Gridiacteristics	WIIII	турт	IVIAX	Units	VDD	Note
D020E	Power-down Base Current	_	0.00099	3.5	μΑ	2.0	WDT, BOD, Comparators, VREF,
	(IPD)	_	0.0012	4.0	μA	3.0	and T1OSC disabled
		—	0.0029	8.0	μA	5.0	
D021E		—	0.3	6.0	μA	2.0	WDT Current ⁽¹⁾
		—	1.8	9.0	μA	3.0	
		—	8.4	20	μA	5.0	
D022E		—	58	70	μA	3.0	BOD Current ⁽¹⁾
		_	109	130	μA	5.0	
D023E		_	3.3	10	μA	2.0	Comparator Current ⁽¹⁾
		—	6.1	13	μA	3.0	
		—	11.5	24	μA	5.0	
D024E		—	58	70	μA	2.0	CVREF Current ⁽¹⁾
		—	85	100	μA	3.0	
		_	138	165	μA	5.0	
D025E			4.0	10	μA	2.0	T1 Osc Current ⁽¹⁾
		_	4.6	12	μA	3.0	
		_	6.0	20	μΑ	5.0	
D026E			0.0012	6.0	μA	3.0	A/D Current ⁽¹⁾
		_	0.0022	8.5	μA	5.0	

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The peripheral current is the sum of the base IDD or IPD and the additional current consumed when this peripheral is enabled. The peripheral ∆ current can be determined by subtracting the base IDD or IPD current from this limit. Max values should be used when calculating total current consumption.

2: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD.

12.6 DC Characteristics: PIC16F630/676-I (Industrial), PIC16F630/676-E (Extended)

DC CH	ARACT	ERISTICS			-40°C ≤ 1	ГА ≤ +8	s otherwise stated) 5°C for industrial 25°C for extended	
Param No.	Sym	Characteristic	Min	Тур†	Мах	Units	Conditions	
		Input Low Voltage						
	VIL	I/O ports						
D030		with TTL buffer	Vss	—	0.8	V	$4.5V \leq V\text{DD} \leq 5.5V$	
D030A			Vss	—	0.15 Vdd	V	Otherwise	
D031		with Schmitt Trigger buffer	Vss		0.2 Vdd	V	Entire range	
D032		MCLR, OSC1 (RC mode)	Vss		0.2 Vdd	V		
D033		OSC1 (XT and LP modes)	Vss	—	0.3	V	(Note 1)	
D033A		OSC1 (HS mode)	Vss	—	0.3 Vdd	V	(Note 1)	
		Input High Voltage						
	Vін	I/O ports		—				
D040		with TTL buffer	2.0	_	Vdd	V	$4.5V \le VDD \le 5.5V$	
D040A			(0.25 VDD+0.8)	—	Vdd	V	otherwise	
D041		with Schmitt Trigger buffer	0.8 Vdd	—	Vdd		entire range	
D042		MCLR	0.8 Vdd	—	Vdd	V		
D043		OSC1 (XT and LP modes)	1.6	—	Vdd	V	(Note 1)	
D043A		OSC1 (HS mode)	0.7 Vdd	—	Vdd	V	(Note 1)	
D043B		OSC1 (RC mode)	0.9 Vdd	—	Vdd	V		
D070	Ipur	PORTA Weak Pull-up Current	50*	250	400*	μA	VDD = 5.0V, VPIN = VSS	
		Input Leakage Current ⁽³⁾						
D060	lı∟	I/O ports	—	± 0.1	± 1	μA	$Vss \le VPIN \le VDD,$ Pin at high-impedance	
D060A		Analog inputs	—	± 0.1	± 1	μA	$Vss \le VPIN \le VDD$	
D060B		VREF	—	± 0.1	± 1	μA	$VSS \leq VPIN \leq VDD$	
D061		MCLR ⁽²⁾	_	± 0.1	± 5	μA	$Vss \leq VPIN \leq VDD$	
D063		OSC1	_	± 0.1	± 5	μA	Vss \leq VPIN \leq VDD, XT, HS and LP osc configuration	
		Output Low Voltage						
D080	Vol	I/O ports	—	—	0.6	V	IOL = 8.5 mA, VDD = 4.5V (Ind.	
D083		OSC2/CLKOUT (RC mode)	_	—	0.6	V	IOL = 1.6 mA, VDD = 4.5V (Ind. IOL = 1.2 mA, VDD = 4.5V (Ext.	
		Output High Voltage						
D090	Vон	I/O ports	Vdd - 0.7	—	_	V	ІОН = -3.0 mA, VDD = 4.5V (Ind.)	
D092		OSC2/CLKOUT (RC mode)	Vdd - 0.7	—	_	V	ІОН = -1.3 mA, VDD = 4.5V (Ind.) ІОН = -1.0 mA, VDD = 4.5V (Ext.)	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended to use an external clock in RC mode.

2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

DC Characteristics: PIC16F630/676-I (Industrial), PIC16F630/676-E (Extended) 12.7 (Cont.)

DC CHAR	ACTERI	STICS	$\begin{array}{l} \mbox{Standard Operating Conditions (unless otherwise stated)} \\ \mbox{Operating temperature} & -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for industrial} \\ & -40^{\circ}C \leq TA \leq +125^{\circ}C \mbox{ for extended} \end{array}$							
Param No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions			
		Capacitive Loading Specs on Output Pins								
D100	Cosc2	OSC2 pin	_	—	15*	pF	In XT, HS and LP modes when external clock is used to drive OSC1			
D101	Сю	All I/O pins	_	_	50*	pF				
		Data EEPROM Memory								
D120	ED	Byte Endurance	100K	1M	—	E/W	$-40^{\circ}C \le TA \le +85^{\circ}C$			
D120A	ED	Byte Endurance	10K	100K	—	E/W	$+85^{\circ}C \leq TA \leq +125^{\circ}C$			
D121	Vdrw	VDD for Read/Write	Vmin	_	5.5	V	Using EECON to read/write VMIN = Minimum operating voltage			
D122	TDEW	Erase/Write cycle time	_	5	6	ms				
D123	Tretd	Characteristic Retention	40	—	_	Year	Provided no other specifications are violated			
D124	TREF	Number of Total Erase/Write Cycles before Refresh ⁽¹⁾	1M	10M	_	E/W	$-40^{\circ}C \leq TA \leq +85^{\circ}C$			
		Program Flash Memory								
D130	Eр	Cell Endurance	10K	100K	—	E/W	$-40^{\circ}C \leq TA \leq +85^{\circ}C$			
D130A	ED	Cell Endurance	1K	10K	—	E/W	$+85^{\circ}C \leq TA \leq +125^{\circ}C$			
D131	Vpr	VDD for Read	VMIN	—	5.5	V	VMIN = Minimum operating voltage			
D132	VPEW	VDD for Erase/Write	4.5	_	5.5	V				
D133	TPEW	Erase/Write cycle time	_	2	2.5	ms				
D134	Tretd	Characteristic Retention	40	—	_	Year	Provided no other specifications are violated			

t Data in 'Typ' column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: See Section 8.5.1 for additional information.

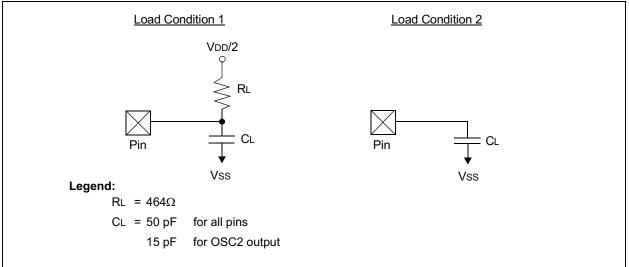
12.8 TIMING PARAMETER SYMBOLOGY

The timing parameter symbols have been created with one of the following formats:

- 1. TppS2ppS
- 2. TppS

2. Tpp3			
т			
F	Frequency	Т	Time
Lowerc	ase letters (pp) and their meanings:		
рр			
сс	CCP1	osc	OSC1
ck	CLKOUT	rd	RD
CS	CS	rw	RD or WR
di	SDI	sc	SCK
do	SDO	SS	SS
dt	Data in	tO	ТОСКІ
io	I/O port	t1	T1CKI
mc	MCLR	wr	WR
Upperc	ase letters and their meanings:		
S			
F	Fall	Р	Period
н	High	R	Rise
I	Invalid (High-impedance)	V	Valid
L	Low	Z	High-impedance

FIGURE 12-4: LOAD CONDITIONS



12.9 AC CHARACTERISTICS: PIC16F630/676 (INDUSTRIAL, EXTENDED)

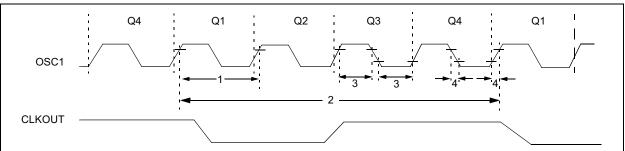


FIGURE 12-5: EXTERNAL CLOCK TIMING

TABLE 12-1: EXTERNAL CLOCK TIMING REQUIREMENTS

Param No.	Sym	Characteristic	Min	Тур†	Мах	Units	Conditions
	Fosc	External CLKIN Frequency ⁽¹⁾	DC	_	37	kHz	LP Osc mode
			DC	—	4	MHz	XT mode
			DC	—	20	MHz	HS mode
			DC	—	20	MHz	EC mode
		Oscillator Frequency ⁽¹⁾	5	—	37	kHz	LP Osc mode
			—	4	—	MHz	INTOSC mode
			DC	—	4	MHz	RC Osc mode
			0.1	—	4	MHz	XT Osc mode
			1	—	20	MHz	HS Osc mode
1	Tosc	External CLKIN Period ⁽¹⁾	27	—	∞	μs	LP Osc mode
			50	—	∞	ns	HS Osc mode
			50	—	x	ns	EC Osc mode
			250	—	x	ns	XT Osc mode
		Oscillator Period ⁽¹⁾	27		200	μs	LP Osc mode
			—	250	—	ns	INTOSC mode
			250	—	—	ns	RC Osc mode
			250	—	10,000	ns	XT Osc mode
			50	—	1,000	ns	HS Osc mode
2	Тсү	Instruction Cycle Time ⁽¹⁾	200	TCY	DC	ns	Tcy = 4/Fosc
3	TosL,	External CLKIN (OSC1) High	2*	_	_	μS	LP oscillator, Tosc L/H duty cycle
	TosH	External CLKIN Low	20*	—	—	ns	HS oscillator, Tosc L/H duty cycle
			100 *		—	ns	XT oscillator, Tosc L/H duty cycle
4	TosR,	External CLKIN Rise	—	_	50*	ns	LP oscillator
	TosF	External CLKIN Fall	—	—	25*	ns	XT oscillator
			—	—	15*	ns	HS oscillator

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min" values with an external clock applied to OSC1 pin. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

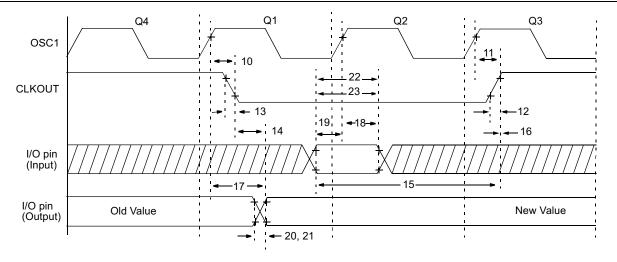
Param No.	Sym	Characteristic	Freq Tolerance	Min	Тур†	Max	Units	Conditions
F10	Fosc	Internal Calibrated	±1	3.96	4.00	4.04	MHz	Vdd = 3.5V, 25°C
		INTOSC Frequency	±2	3.92	4.00	4.08	MHz	$2.5V \leq V\text{DD} \leq 5.5V$
								$0^{\circ}C \le TA \le +85^{\circ}C$
			±5	3.80	4.00	4.20	MHz	$2.0V \leq V\text{DD} \leq 5.5V$
								$-40^{\circ}C \le TA \le +85^{\circ}C$ (IND)
								$-40^{\circ}C \le TA \le +125^{\circ}C$ (EXT)
F14	Tiosc	Oscillator Wake-up from	—		6	8	μs	VDD = 2.0V, -40°C to +85°C
	ST	Sleep start-up time*	—	_	4	6	μs	VDD = 3.0V, -40°C to +85°C
			—	—	3	5	μS	VDD = 5.0V, -40°C to +85°C
* -	These p	parameters are characteriz	zed but not t	ested.				

TABLE 12-2: PRECISION INTERNAL OSCILLATOR PARAMETERS

These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.





Param No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
10	TosH2ckL	OSC1↑ to CLOUT↓	—	75	200	ns	(Note 1)
11	TosH2ckH	OSC1↑ to CLOUT↑	—	75	200	ns	(Note 1)
12	TckR	CLKOUT rise time	—	35	100	ns	(Note 1)
13	TckF	CLKOUT fall time	—	35	100	ns	(Note 1)
14	TckL2ioV	CLKOUT↓ to Port out valid	—	_	20	ns	(Note 1)
15	TioV2ckH	Port in valid before CLKOUT↑	Tosc + 200 ns	_	_	ns	(Note 1)
16	TckH2iol	Port in hold after CLKOUT↑	0	_	_	ns	(Note 1)
17	TosH2ioV	OSC1 [↑] (Q1 cycle) to Port out valid	—	50	150 *	ns	
				_	300	ns	
18	TosH2iol	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	100	—	—	ns	
19	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	0	—	—	ns	
20	TioR	Port output rise time	—	10	40	ns	
21	TioF	Port output fall time	—	10	40	ns	
22	Tinp	INT pin high or low time	25	—	_	ns	
23	Trbp	PORTA change INT high or low time	Тсү	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated.

Note 1: Measurements are taken in RC mode where CLKOUT output is 4xTosc.



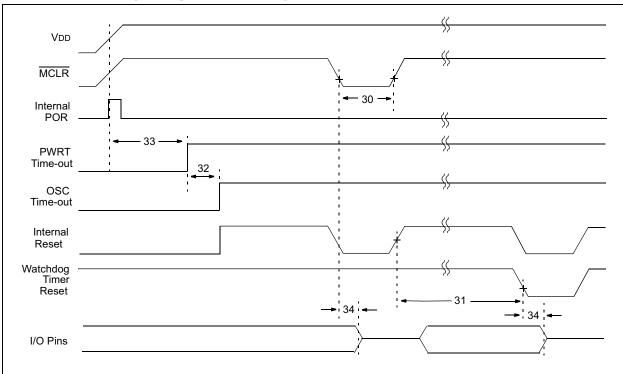


FIGURE 12-8: BROWN-OUT DETECT TIMING AND CHARACTERISTICS

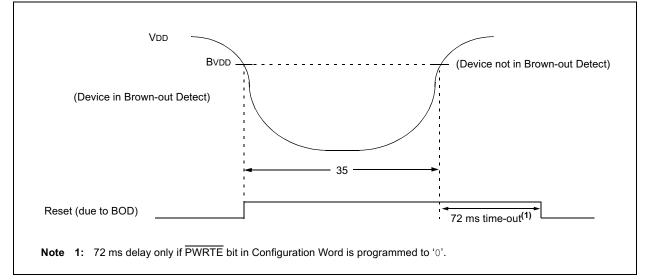


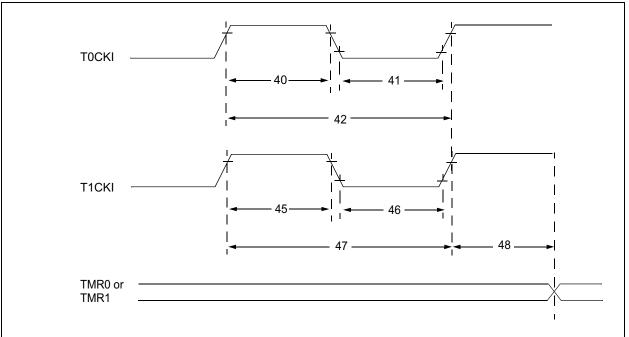
TABLE 12-4:RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER,
AND BROWN-OUT DETECT REQUIREMENTS

Param No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
30	TMCL	MCLR Pulse Width (low)	2 11	 18	 24	μs ms	VDD = 5V, -40°C to +85°C Extended temperature
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	10 10	17 17	25 30	ms ms	V _{DD} = 5V, -40°C to +85°C Extended temperature
32	Тоѕт	Oscillation Start-up Timer Period	_	1024Tosc	_		Tosc = OSC1 period
33*	TPWRT	Power-up Timer Period	28* TBD	72 TBD	132* TBD	ms ms	VDD = 5V, -40°C to +85°C Extended Temperature
34	Tioz	I/O High-impedance from MCLR Low or Watchdog Timer Reset	_	_	2.0	μS	
	BVDD	Brown-out Detect Voltage	2.025		2.175	V	
		Brown-out Hysteresis	TBD	—		—	
35	Твор	Brown-out Detect Pulse Width	100*		—	μs	$VDD \le BVDD (D005)$

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.





Param No.	Sym		Characteristic		Min	Тур†	Max	Units	Conditions
40*	Tt0H	T0CKI High Pulse	Width No Prescaler		0.5 Tcy + 20	-		ns	
				With Prescaler	10	—		ns	
41*	Tt0L	T0CKI Low Pulse	Width	No Prescaler	0.5 Tcy + 20	—	_	ns	
				With Prescaler	10	—	_	ns	
42*	TtOP	T0CKI Period		Greater of: 20 or <u>Tcy + 40</u> N	_		ns	N = prescale value (2, 4,, 256)	
45*	Tt1H	T1CKI High Time	Synchronous, No	Synchronous, No Prescaler		—	_	ns	
			Synchronous, with Prescaler		15	-		ns	
			Asynchronous		30	—	_	ns	
46*	Tt1L	T1CKI Low Time	Synchronous, No	Synchronous, No Prescaler		—	_	ns	
			Synchronous, with Prescaler		15	-		ns	
			Asynchronous		30	—	_	ns	
47*	Tt1P	T1CKI Input Period	Synchronous		Greater of: 30 or <u>Tcy + 40</u> N	_	_	ns	N = prescale value (1, 2, 4, 8)
			Asynchronous		60	—		ns	
	Ft1	Timer1 oscillator ir (oscillator enabled		0	DC	_	200*	kHz	
48	TCKEZtmr1	Delay from externa	al clock edge to tir	ner increment	2 Tosc*	—	7 Tosc*	—	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

TABLE 12-6: COMPARATOR SPECIFICATIONS

Comparate	or Specifications	Standard Operating Conditions -40°C to +125°C (unless otherwise stated)						
Sym	Characteristics	Min	Тур	Max	Units	Comments		
Vos	Input Offset Voltage		± 5.0	± 10	mV			
Vсм	Input Common Mode Voltage	0		Vdd - 1.5	V			
CMRR	Common Mode Rejection Ratio	+55*	_	—	db			
Trt	Response Time ⁽¹⁾	—	150	400*	ns			
TMC2COV	Comparator Mode Change to Output Valid	_	—	10*	μS			

* These parameters are characterized but not tested.

Note 1: Response time measured with one comparator input at (VDD - 1.5)/2 while the other input transitions from Vss to VDD - 1.5V.

TABLE 12-7: COMPARATOR VOLTAGE REFERENCE SPECIFICATIONS

Voltage I	Reference Specifications	Standard Operating Conditions -40°C to +125°C (unless otherwise stated)					
Sym	Characteristics	Min	Тур	Max	Units	Comments	
	Resolution		Vdd/24* Vdd/32	_	LSb LSb	Low Range (VRR = 1) High Range (VRR = 0)	
	Absolute Accuracy		—	± 1/2* ± 1/2*	LSb LSb	Low Range (VRR = 1) High Range (VRR = 0)	
	Unit Resistor Value (R)	—	2k*	_	Ω		
	Settling Time ⁽¹⁾	—	—	10*	μS		

* These parameters are characterized but not tested.

Note 1: Settling time measured while VRR = 1 and VR<3:0> transitions from 0000 to 1111.

Param No.	Sym	Characteristic	Min	Тур†	Мах	Units	Conditions
A01	NR	Resolution	_	_	10 bits	bit	
A02	Eabs	Total Absolute Error*		_	±1	LSb	VREF = 5.0V
A03	EIL	Integral Error	_	—	±1	LSb	VREF = 5.0V
A04	Edl	Differential Error	—	_	±1	LSb	No missing codes to 10 bits VREF = 5.0V
A05	Efs	Full Scale Range	2.2*	—	5.5*	V	
A06	EOFF	Offset Error	_	—	±1	LSb	VREF = 5.0V
A07	Egn	Gain Error	_	—	±1	LSb	VREF = 5.0V
A10	—	Monotonicity	_	guaranteed ⁽³⁾		—	$VSS \leq VAIN \leq VREF+$
A20 A20A	VREF	Reference Voltage	2.0 2.5	—	 Vdd + 0.3	V	Absolute minimum to ensure 10-bit accuracy
A21	Vref	Reference V High (VDD or VREF)	Vss	—	Vdd	V	
A25	Vain	Analog Input Voltage	Vss	_	VREF	V	
A30	ZAIN	Recommended Impedance of Analog Voltage Source	_	_	10	kΩ	
A50	IREF	VREF Input Current ⁽²⁾	10	—	1000	μΑ	During VAIN acquisition. Based on differential of VHOLD to VAIN.
			—	—	10	μA	During A/D conversion cycle.

TABLE 12-8:	PIC16F676 A/D CONVERTER CHARACTERISTICS:

These parameters are characterized but not tested.

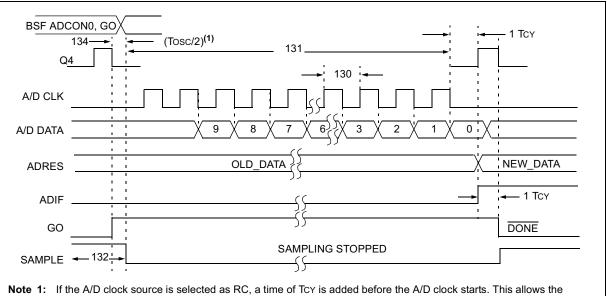
† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: When A/D is off, it will not consume any current other than leakage current. The power-down current spec includes any such leakage from the A/D module.

2: VREF current is from External VREF or VDD pin, whichever is selected as reference input.

3: The A/D conversion result never decreases with an increase in the input voltage and has no missing codes.





SLEEP instruction to be executed.

TABLE 12-9 :	PIC16F676 A/D CONVERSION REQUIREMENTS

Param No.	Sym	Characteristic	Min	Тур†	Мах	Units	Conditions
130	Tad	A/D Clock Period	1.6			μS	Tosc based, VREF \geq 3.0V
			3.0*	—	—	μs	Tosc based, VREF full range
130	Tad	A/D Internal RC Oscillator Period	3.0*	6.0	9.0*	μs	ADCS<1:0> = 11 (RC mode) At VDD = 2.5V
			2.0*	4.0	6.0*	μs	At VDD = 5.0V
131	TCNV	Conversion Time (not including Acquisition Time) ⁽¹⁾	_	11	_	TAD	Set GO bit to new data in A/D result register
132	TACQ	Acquisition Time	(Note 2)	11.5		μs	
			5*	_	_	μs	The minimum time is the amplifier settling time. This may be used if the "new" input voltage has not changed by more than 1 LSb (i.e., 4.1 mV @ 4.096V) from the last sampled volt- age (as stored on CHOLD).
134	TGO	Q4 to A/D Clock Start		Tosc/2	_	_	If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: ADRES register may be read on the following TCY cycle.

2: See Table 7-1 for minimum conditions.

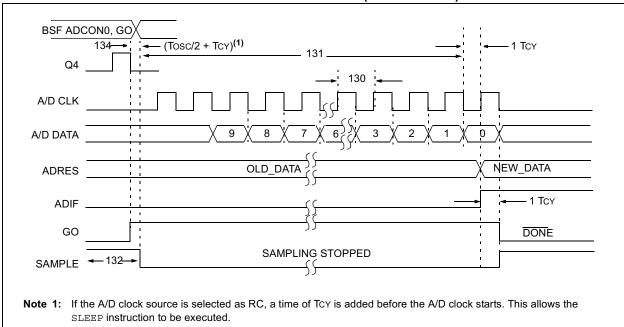


FIGURE 12-11:	PIC16F676 A/D CONVERSION TIMING (SLEEP MODE)

Param No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
130	TAD	A/D Clock Period	1.6	—	_	μs	$VREF \ge 3.0V$
			3.0*	—	—	μS	VREF full range
130	TAD	A/D Internal RC Oscillator Period	3.0*	6.0	9.0*	μS	ADCS<1:0> = 11 (RC mode) At VDD = 2.5V
			2.0*	4.0	6.0*	μs	At VDD = 5.0V
131	TCNV	Conversion Time (not including Acquisition Time) ⁽¹⁾	_	11	_	TAD	
132	TACQ	Acquisition Time	(Note 2)	11.5		μs	
			5*		_	μs	The minimum time is the amplifier settling time. This may be used if the "new" input voltage has not changed by more than 1 LSb (i.e., 4.1 mV @ 4.096V) from the last sampled voltage (as stored on CHOLD).
134	TGO	Q4 to A/D Clock Start		Tosc/2 + Tcy		—	If the A/D clock source is selected as RC, a time of TcY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: ADRES register may be read on the following TCY cycle.

2: See Table 7-1 for minimum conditions.

NOTES:

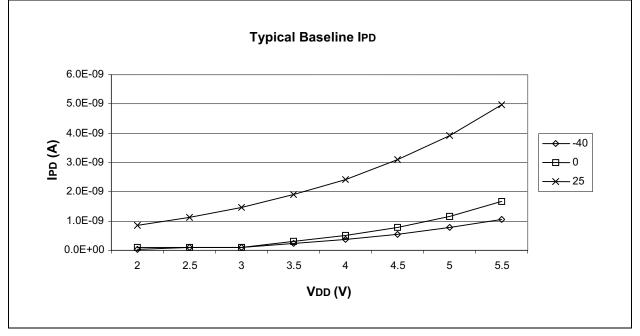
13.0 DC AND AC CHARACTERISTICS GRAPHS AND TABLES

The graphs and tables provided in this section are for design guidance and are not tested.

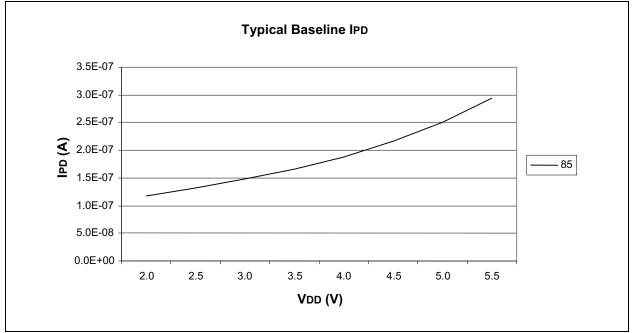
In some graphs or tables, the data presented are **outside specified operating range** (i.e., outside specified VDD range). This is for **information only** and devices are ensured to operate properly only within the specified range.

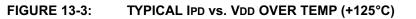
The data presented in this section is a **statistical summary** of data collected on units from different lots over a period of time and matrix samples. "Typical" represents the mean of the distribution at 25°C. "Max" or "min" represents (mean + 3σ) or (mean - 3σ) respectively, where σ is standard deviation, over the whole temperature range.

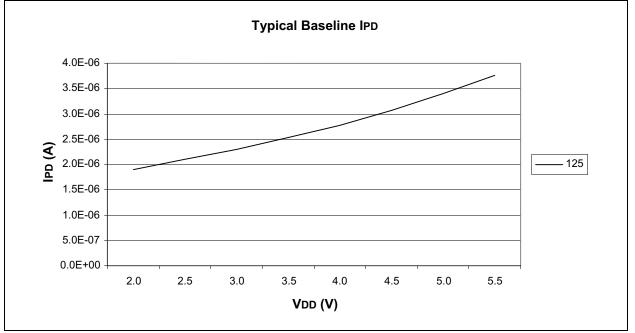


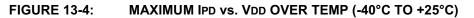


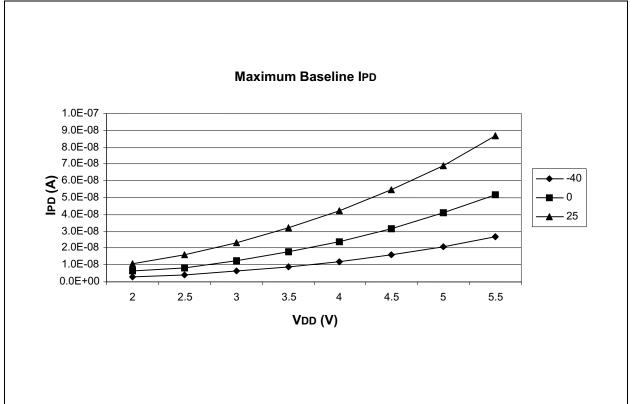












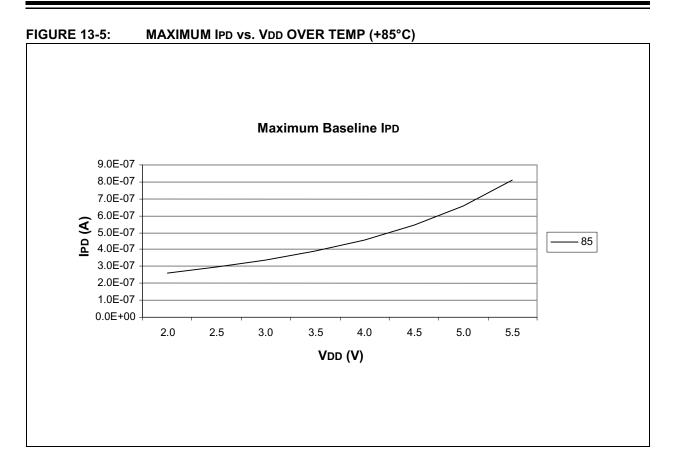
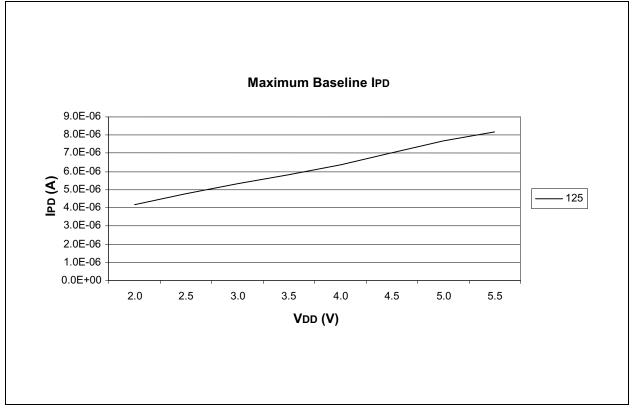
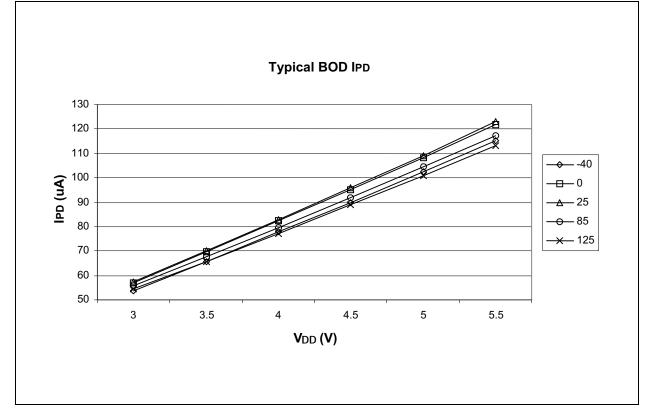


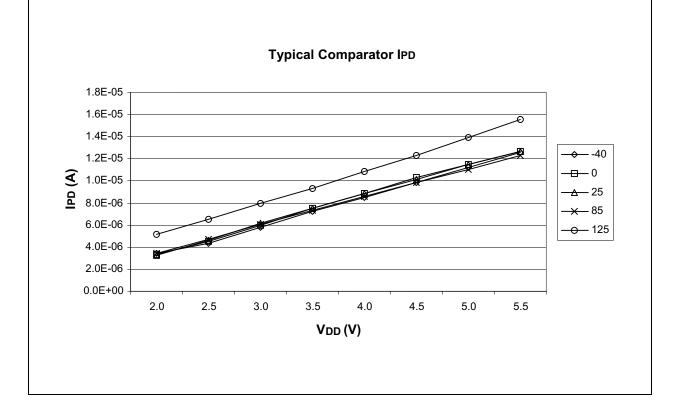
FIGURE 13-6: MAXIMUM IPD vs. VDD OVER TEMP (+125°C)











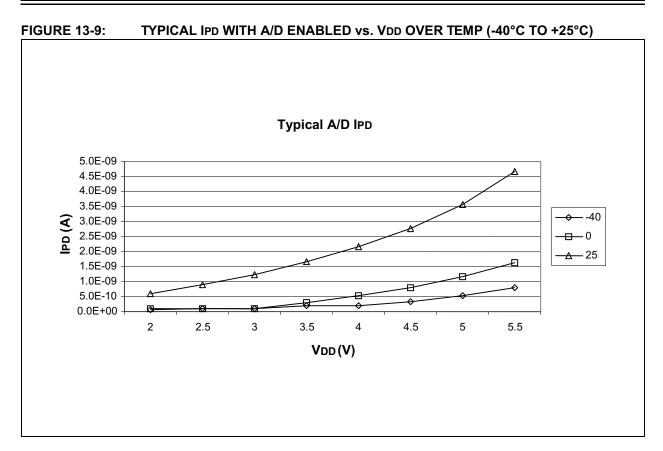
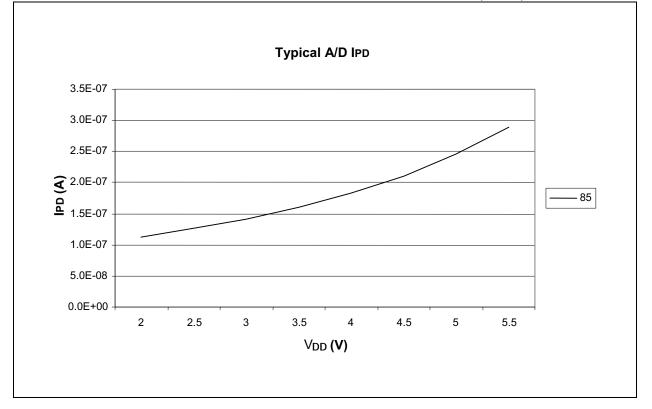
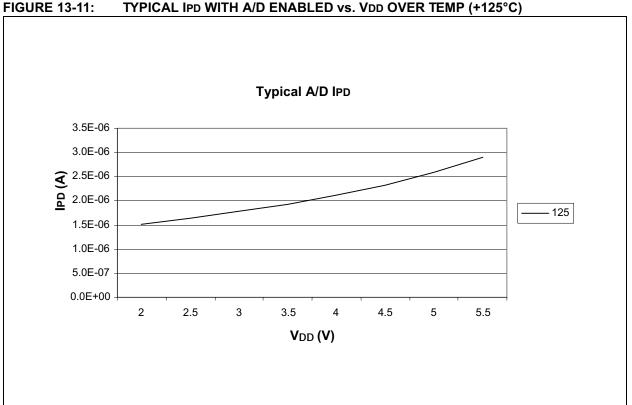
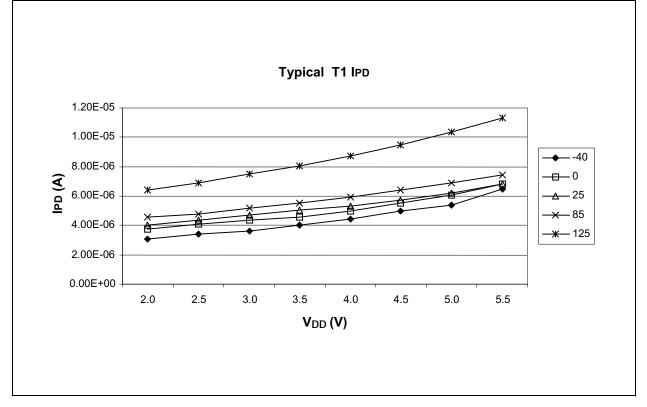


FIGURE 13-10: TYPICAL IPD WITH A/D ENABLED vs. VDD OVER TEMP (+85°C)









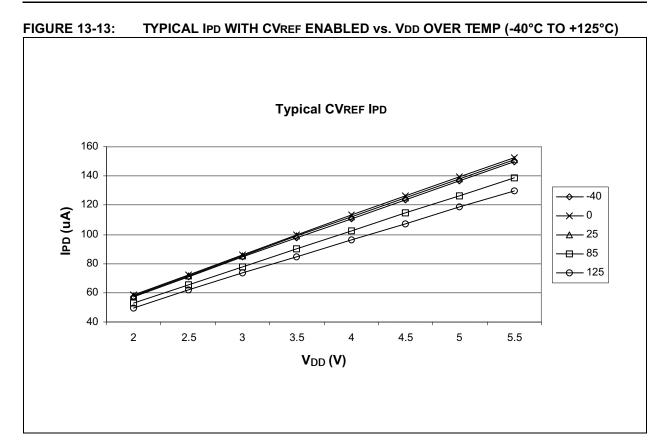


FIGURE 13-14: TYPICAL IPD WITH WDT ENABLED vs. VDD OVER TEMP (-40°C TO +125°C)

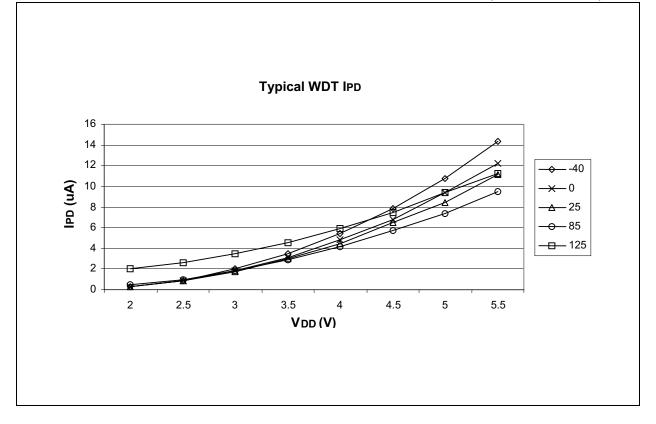


FIGURE 13-15: MAXIMUM AND MINIMUM INTOSC FREQ vs. TEMPERATURE WITH 0.1μ F AND 0.01μ F DECOUPLING (VDD = 3.5V)

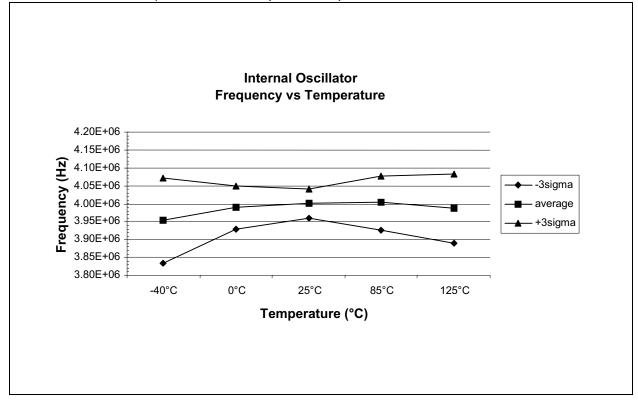
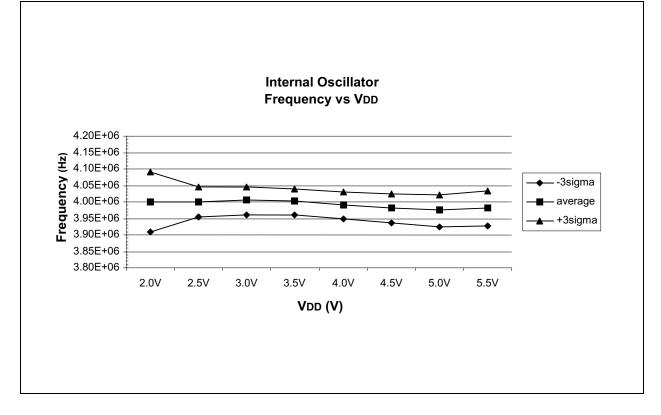
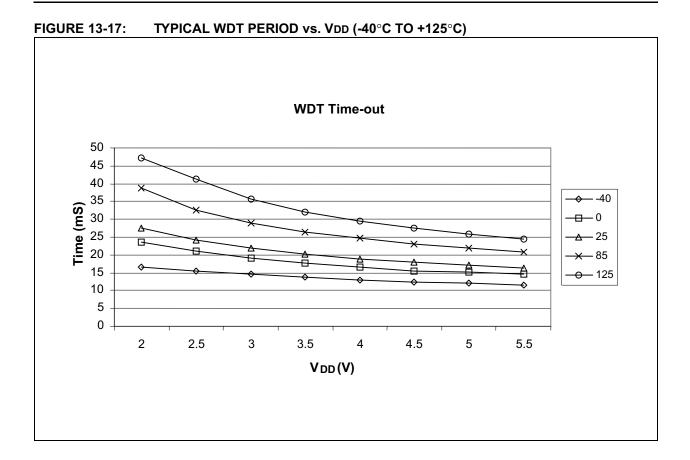


FIGURE 13-16: MAXIMUM AND MINIMUM INTOSC FREQ vs. VDD WITH 0.1μ F AND 0.01μ F DECOUPLING (+25°C)



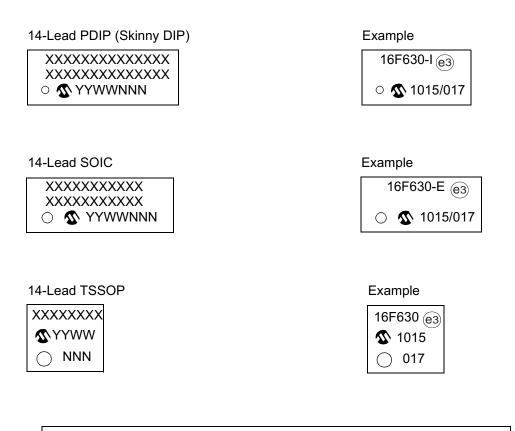


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NOTES:

14.0 PACKAGING INFORMATION

14.1 Package Marking Information



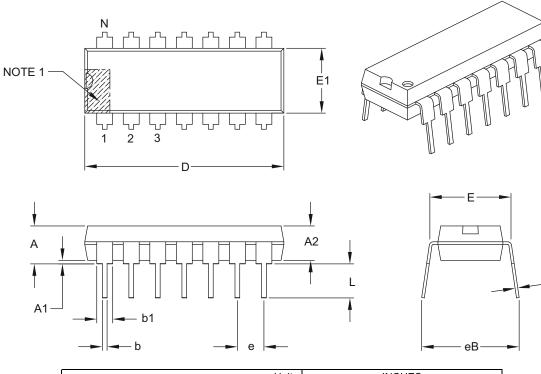
Leg	end:	XXX Y YY WW NNN @3 *	Customer-specific information Year code (last digit of calendar year) Year code (last 2 digits of calendar year) Week code (week of January 1 is week '01') Alphanumeric traceability code Pb-free JEDEC designator for Matte Tin (Sn) This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.
Not	b	e carried	nt the full Microchip part number cannot be marked on one line, it will d over to the next line, thus limiting the number of available for customer-specific information.

14.2 Package Details

The following sections give the technical details of the packages.

14-Lead Plastic Dual In-Line (P) – 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units		INCHES	
Dimensio	on Limits	MIN	NOM	MAX
Number of Pins	Ν		14	
Pitch	е		.100 BSC	
Top to Seating Plane	Α	-	-	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	-	-
Shoulder to Shoulder Width	Е	.290	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.735	.750	.775
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	С	.008	.010	.015
Upper Lead Width	b1	.045	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	_	_	.430

Notes:

- 1. Pin 1 visual index feature may vary, but must be located with the hatched area.
- 2. § Significant Characteristic.
- 3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
- 4. Dimensioning and tolerancing per ASME Y14.5M.

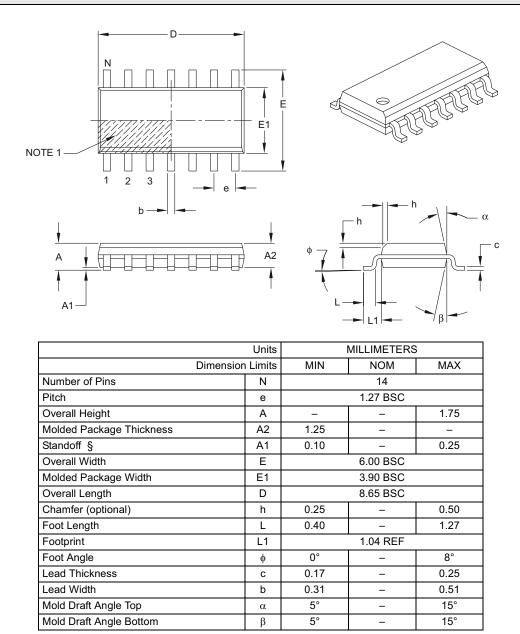
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-005B

C

14-Lead Plastic Small Outline (SL) – Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

2. § Significant Characteristic.

3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.

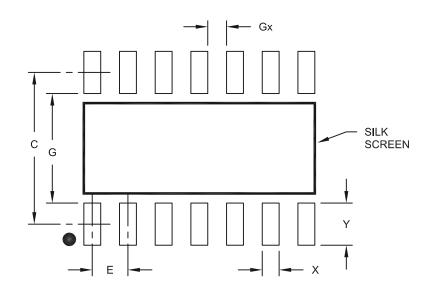
- 4. Dimensioning and tolerancing per ASME Y14.5M.
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-065B

14-Lead Plastic Small Outline (SL) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	Units	N	ILLIMETER:	S
Dimension	Limits	MIN	NOM	MAX
Contact Pitch	E		1.27 BSC	
Contact Pad Spacing	С		5.40	
Contact Pad Width	Х			0.60
Contact Pad Length	Y			1.50
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	3.90		

Notes:

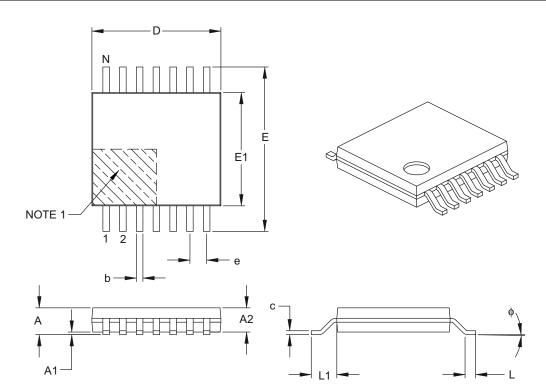
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2065A

14-Lead Plastic Thin Shrink Small Outline (ST) – 4.4 mm Body [TSSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units		MILLIMETERS	6
Dimensio	n Limits	MIN	NOM	MAX
Number of Pins	Ν		14	
Pitch	е		0.65 BSC	
Overall Height	Α	—	-	1.20
Molded Package Thickness	A2	0.80	1.00	1.05
Standoff	A1	0.05	_	0.15
Overall Width	Е		6.40 BSC	
Molded Package Width	E1	4.30	4.40	4.50
Molded Package Length	D	4.90	5.00	5.10
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	¢	0°	-	8°
Lead Thickness	с	0.09	-	0.20
Lead Width	b	0.19	-	0.30

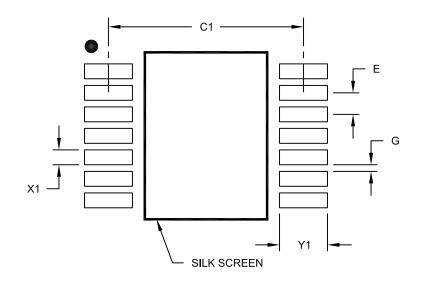
Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.
- 3. Dimensioning and tolerancing per ASME Y14.5M.
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-087B

14-Lead Plastic Thin Shrink Small Outline (ST) - 4.4 mm Body [TSSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimensior	n Limits	MIN	NOM	MAX
Contact Pitch	Е		0.65 BSC	
Contact Pad Spacing	C1		5.90	
Contact Pad Width (X14)	X1			0.45
Contact Pad Length (X14)	Y1			1.45
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2087A

APPENDIX A: DATA SHEET REVISION HISTORY

Revision A

This is a new data sheet.

Revision B

Added characterization graphs.

Updated specifications.

Added notes to indicate Microchip programmers maintain all calibration bits to factory settings and the PIC16F676 ANSEL register must be initialized to configure pins as digital I/O.

Revision C

Revision D

Updated Package Drawings; Replaced PICmicro with PIC.

Revision E (03/2007)

Replaced Package Drawings (Rev. AM); Replaced Development Support Section.

Revision F (05/2010)

Replaced Package Drawings (Rev. BD); Replaced Development Support Section.

APPENDIX B: DEVICE DIFFERENCES

The differences between the PIC16F630/676 devices listed in this data sheet are shown in Table B-1.

TABLE B-1: DEVICE DIFFERENCES

Feature	PIC16F630	PIC16F676
A/D	No	Yes

APPENDIX C: DEVICE MIGRATIONS

This section is intended to describe the functional and electrical specification differences when migrating between functionally similar devices (such as from a PIC16C74A to a PIC16C74B).

Not Applicable

APPENDIX D: MIGRATING FROM OTHER PIC[®] DEVICES

This discusses some of the issues in migrating from other PIC devices to the PIC16F6XX family of devices.

D.1 PIC12C67X to PIC12F6XX

Feature	PIC12C67X	PIC16F6XX
Max Operating Speed	10 MHz	20 MHz
Max Program Memory	2048 bytes	1024 bytes
A/D Resolution	8-bit	10-bit
Data EEPROM	16 bytes	64 bytes
Oscillator Modes	5	8
Brown-out Detect	N	Y
Internal Pull-ups	RA0/1/3	RA0/1/2/4/5
Interrupt-on-change	RA0/1/3	RA0/1/2/3/4/5
Comparator	Ν	Y

TABLE 1: FEATURE COMPARISON

Note:	This device has been designed to perform to the parameters of its data sheet. It has been tested to an electrical specification designed to determine its conformance with these parameters. Due to process differences in the manufacture of this device, this device may have different performance characteristics than its earlier version. These differences may cause this device to perform differently in your application than the earlier version of this
	device.

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Device:	Range : Standard VDD range T: (Tape and Reel)	package, 20 MHz, QTP pattern #301 b) PIC16F676 – I/SL = Industrial Temp., SOIC package, 20 MHz
Temperature Range:	$I = -40^{\circ}C \text{ to } +85^{\circ}C$ E = -40^{\circ}C \text{ to } +125^{\circ}C	
Package:	P = PDIP SL = SOIC (Gull wing, 3.90 mm body) ST = TSSOP(4.4 mm)	
Pattern: 3-Digit Pattern Code for QTP (blank otherwise)		

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